Fourth Quarter FY 2021
Quarterly Update

Infineon Technologies AG
Investor Relations

Infineon at a glance

Addressing long-term high-growth trends

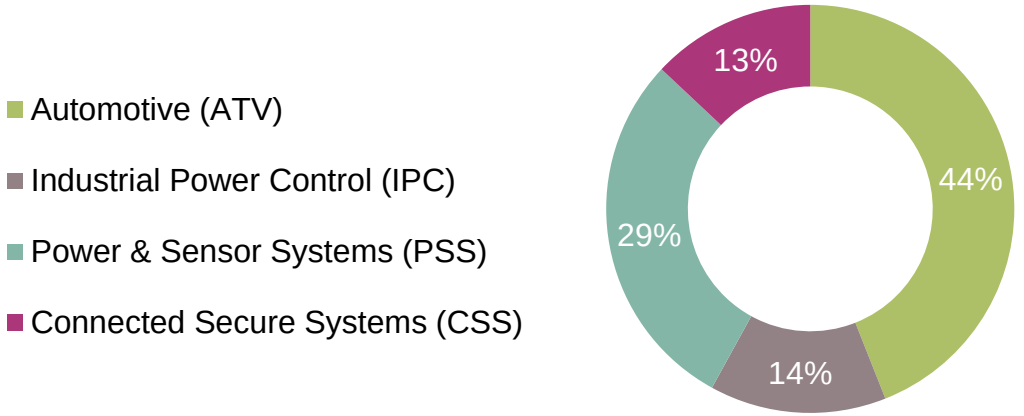
Electrification

- CO_2 saving
- Energy efficiency
- Cost saving

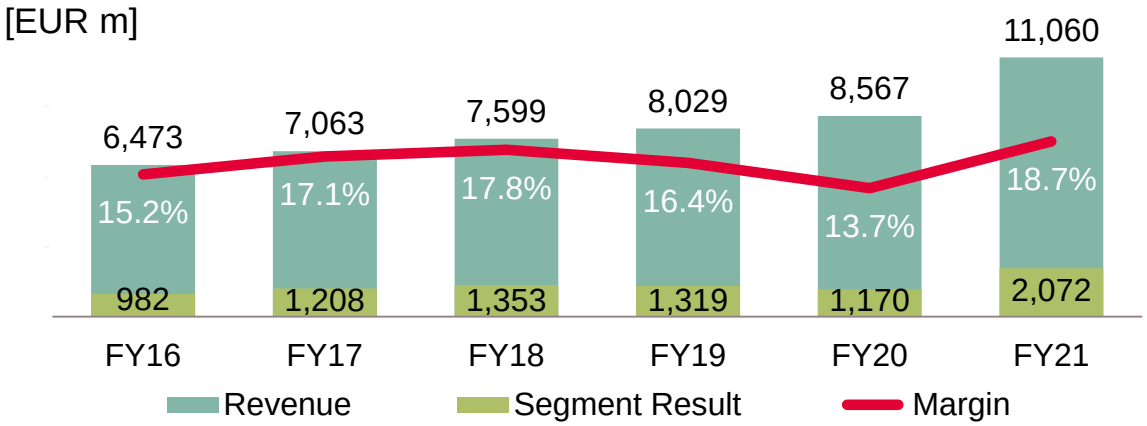
Digitalization

- Productivity
- Comfort
- New use cases

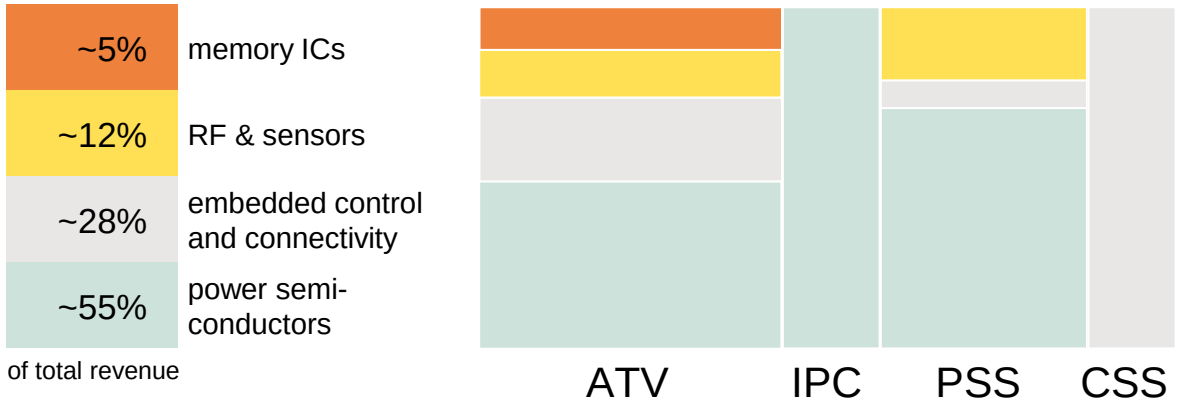
FY21 revenue by segment



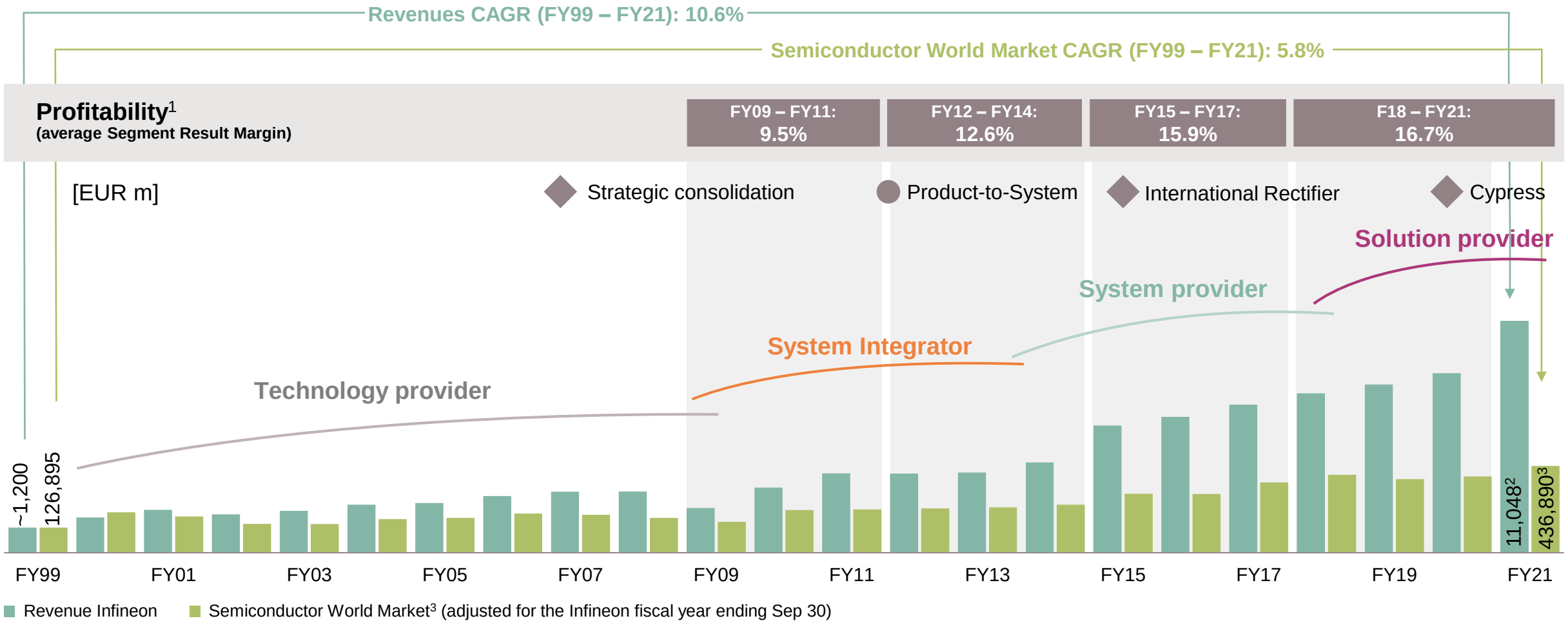
Financials



FY21 revenue by product category



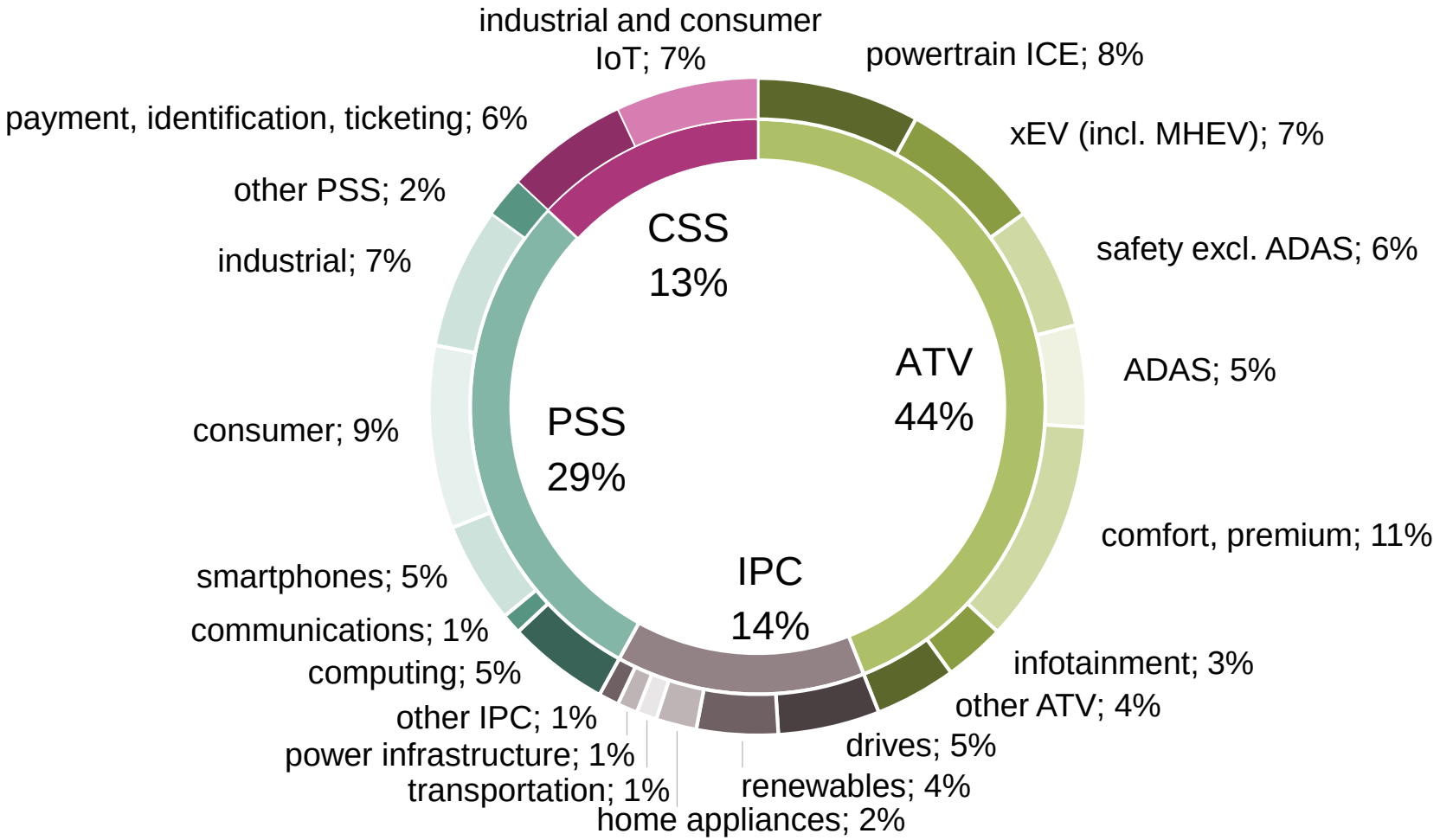
Since 1999, Infineon has grown by more than 10% p.a., thereby consistently outperforming the semiconductor market



1 In FY09 Infineon's management changed the measure it uses to assess the operating performance of its operating segments to "Segment Result"
2 Based on Infineon's portfolio (excl. Other Operating Segments and Corporate & Eliminations) per end of FY21 | **3** Source: WSTS (World Semiconductor Trade Statistics) in EUR adjusted for fiscal year, September 2021

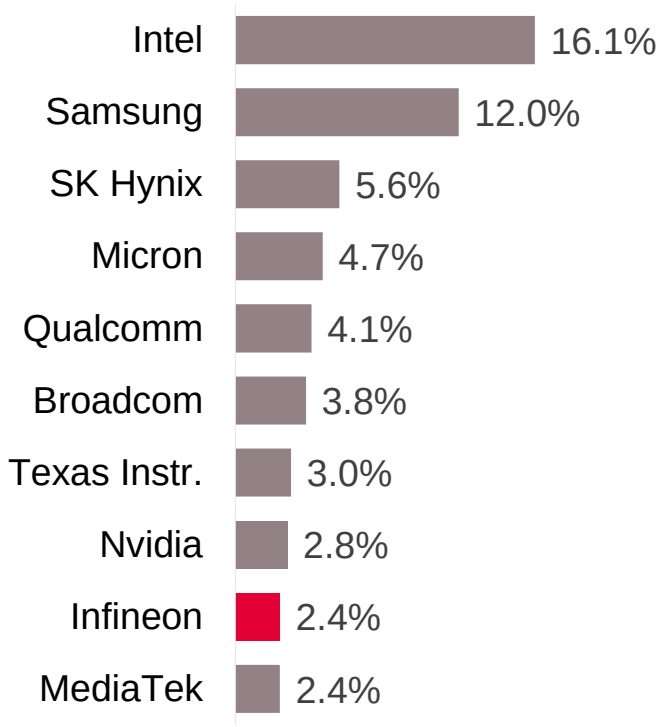
Well-balanced portfolio among key trends Electrification and Digitalization

FY21 revenue of €11,060m by target application

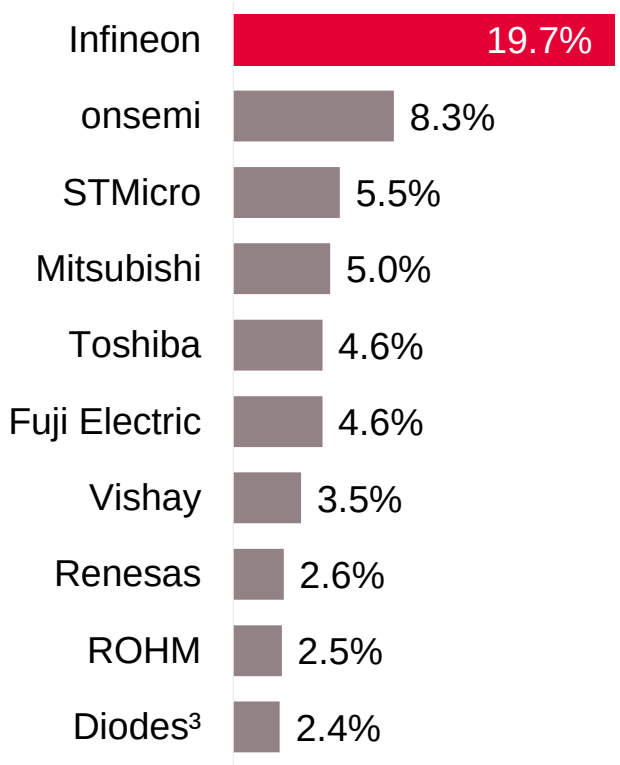


Infineon is a global top-10 player, #1 in power semiconductors, and ranked #3 in the overall microcontroller market

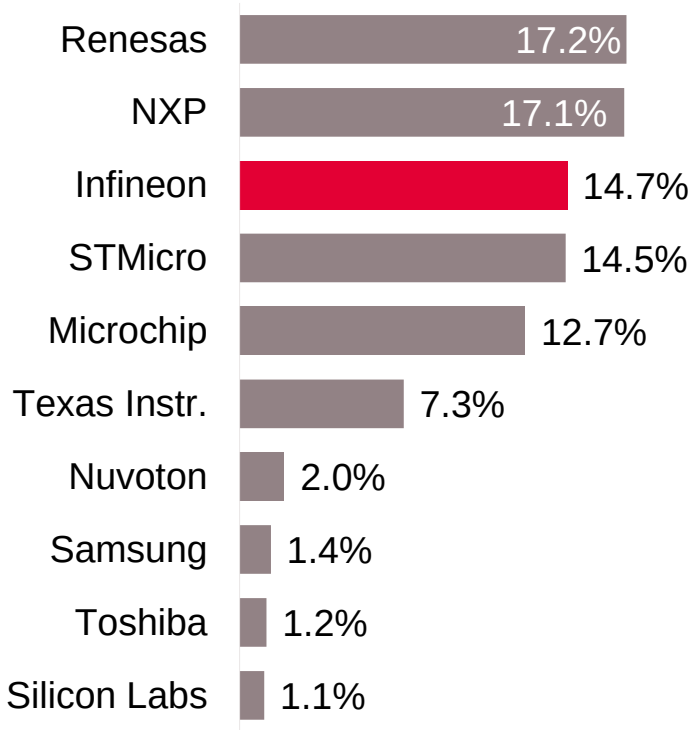
Semiconductor suppliers
2020 total market: $473bn[1]



Power discretes and modules
2020 total market: $20.9bn[2]



MCU suppliers
2020 total market: $17.3bn[1]



1 Based on or includes research from Omdia: *Annual 2001-2020 Semiconductor Market Share Competitive Landscaping Tool – Q2 2021.* August 2021. | **2** Based on or includes research from Omdia: *Power Semiconductor Market Share Database – 2020.* September 2021. | **3** Diodes acquired Lite-On Semiconductor in November 2020. Both companies are reported combined as Diodes.
Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk.

Outlook for Q1 FY22 and FY22

	Outlook Q1 FY22[1]	Outlook FY22[1]
Revenue	**~ €3.0bn**	**€12.7bn +/- €500m**
Segment Result Margin	**~ 21%**	At the mid-point of the revenue guidance: **~ 21%**
Investments in FY22		**~ €2.4bn**
D&A in FY22		**€1.6bn - €1.7bn[2]**
Free cash flow in FY22		**~ €1.0bn**

1 Based on an assumed average exchange rate of $1.20 for €1.00
2 Including the effects of the purchase price allocation for Cypress and, to a lesser extent, International Rectifier

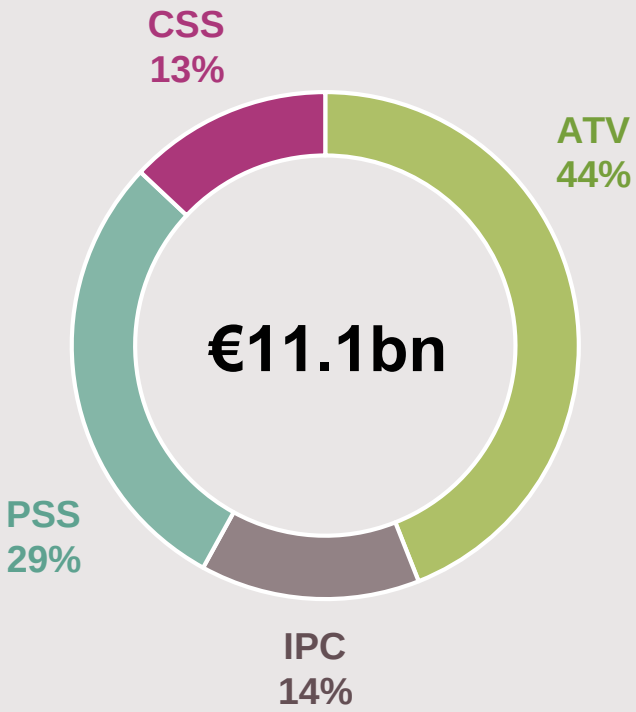
Infineon’s value creation is crystallized in a resilient through-cycle Target Operating Model

	Target Operating Model[1]
Revenue growth	9%+
Segment Result Margin	19%
Investment-to-sales	13%

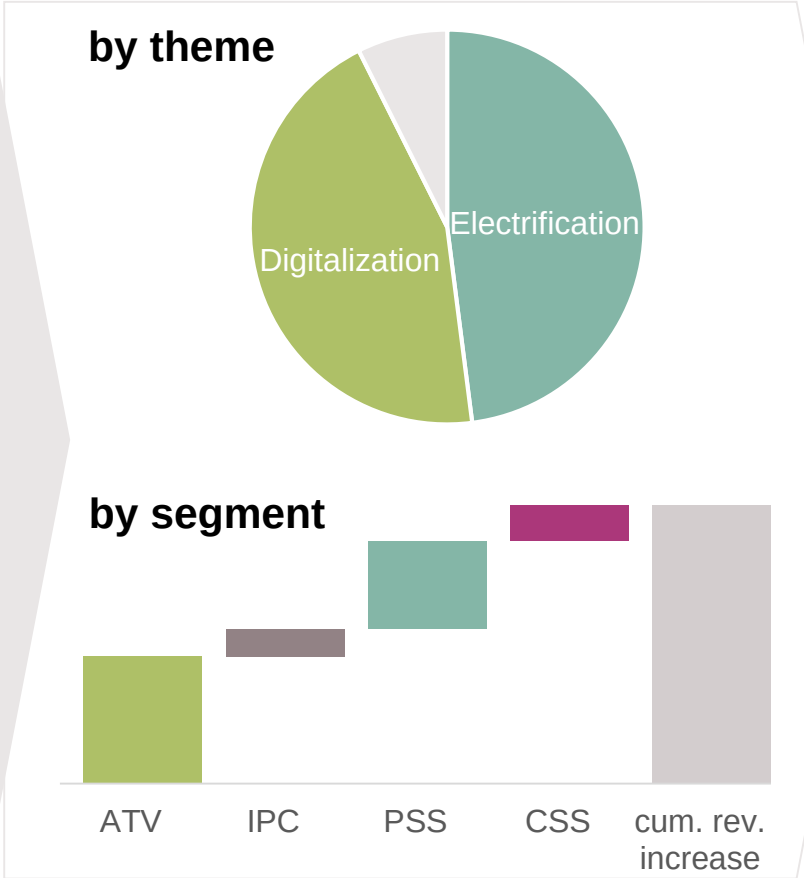
1 Infineon financial performance to approach targets as Cypress integration progresses

Growing annual revenues by €5bn+ in FY25 – multitude of growth drivers across markets/applications; well-diversified divisional split

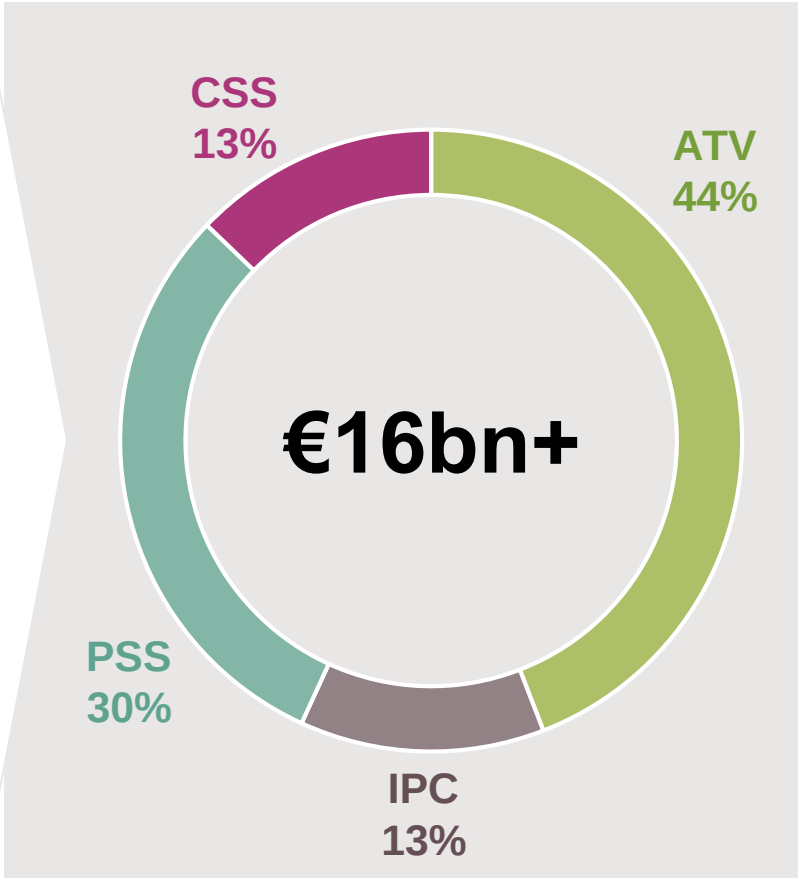
FY21 by division



Cum. rev. growth FY21 to FY25e



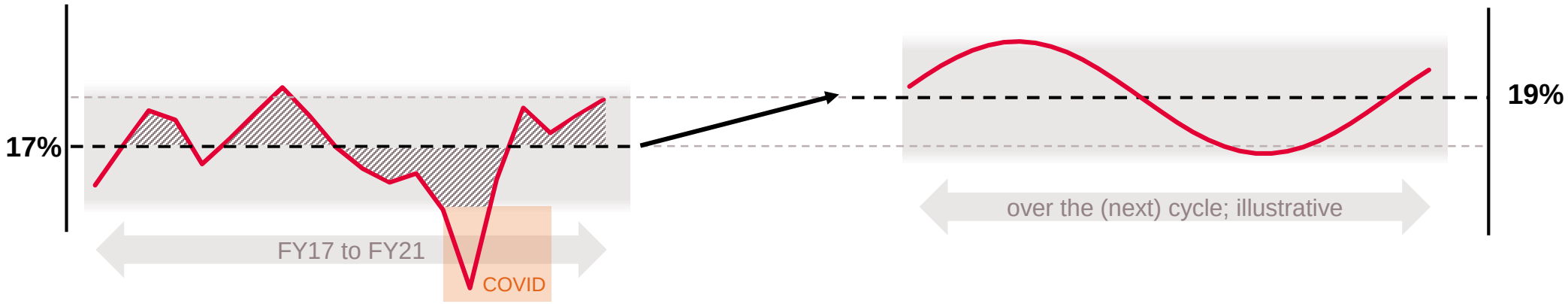
FY25e by division (indicative)



Key levers identified to get to the target profitability flight level – 19% Segment Result Margin over the (next) cycle

Looking back: former TOM achieved

Looking ahead: all set up to reach current TOM



Assuming no pandemic, 17% Segment Result Margin target would have been achieved over the cycle

Levers for margin expansion

- Higher value system solutions:
  - P2S and Cypress revenue synergies
  - Additional customer value creation
  - Business mix
- Manufacturing productivity and cost control:
  - 300 mm productivity
  - Cypress cost synergies, SG&A scaling
- Cypress accretion for entire period

Inhibitors to margin expansion

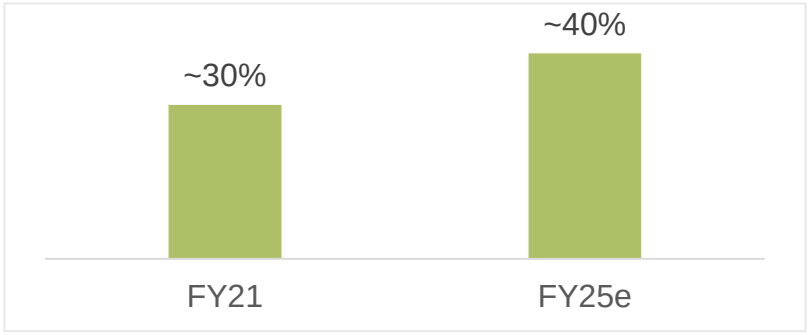
- Increased supplier (foundry) and materials costs
- Pre-funding P2S synergies
- Pre-funding SiC/GaN roadmap

Strategic differentiation through in-house manufacturing

In-house manufacturing

- We manufacture power and sensor technologies in-house where we can gain a strategic advantage from our leading-edge manufacturing technologies and our outstanding process expertise
- This results in a differentiation potential in terms of cost and/or performance
- **The current chip shortage highlights the strategic value of in-house manufacturing**

Infineon's outsourcing share

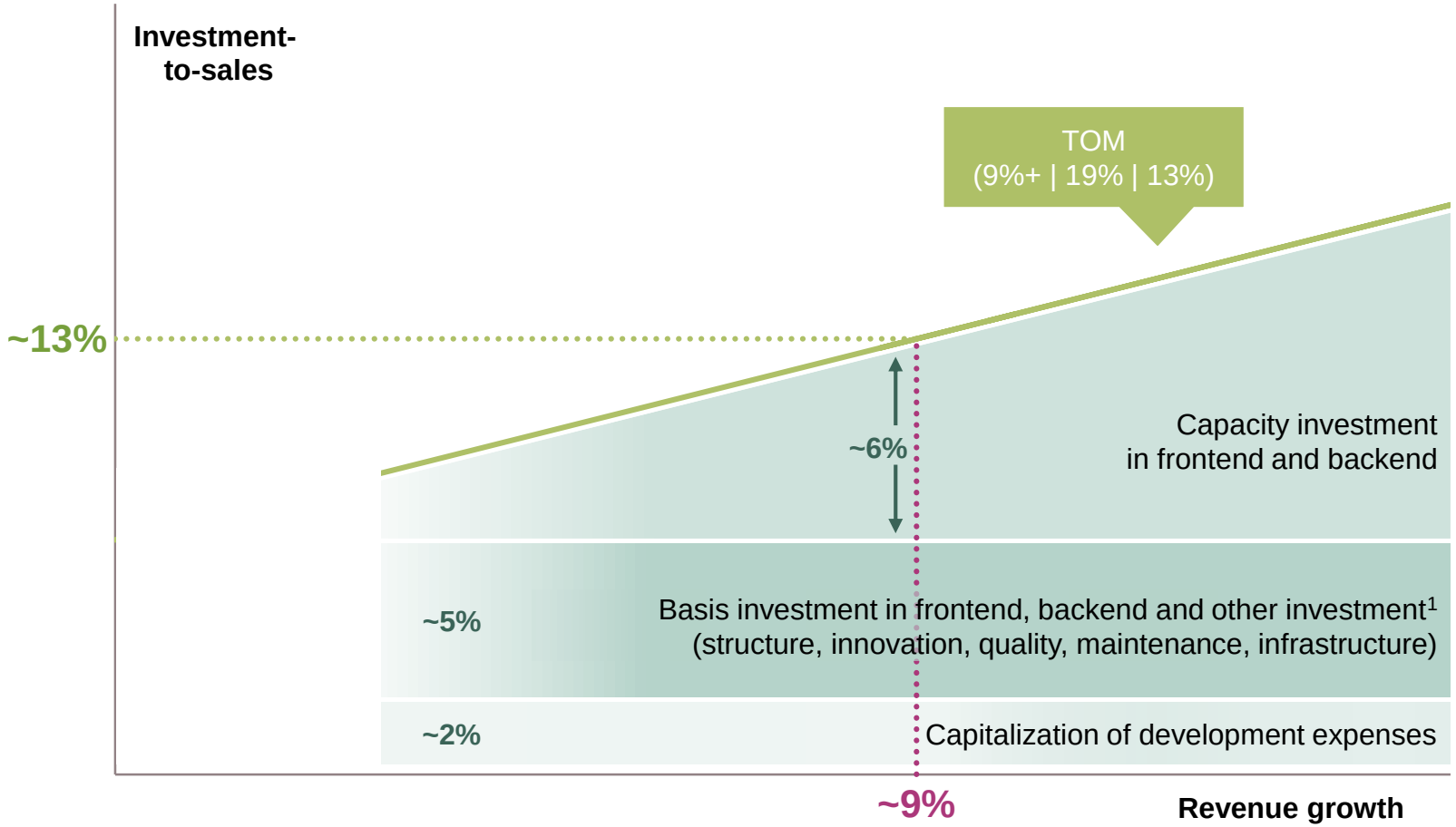


Outsourcing

- We work with outsourcing partners where we see no or only little differentiation to optimize our capital efficiency (CMOS and derivate technologies and standard packages)
- We cooperate with subcontractors and foundries in order to ensure adequate capacity growth and flexibility
- Infineon's outsourcing share is expected to increase from ~30% in FY21 to ~40% in FY25

We focus our investments to those areas with highest differentiation

Split of investment-to-sales by category



Major focus topics

- Capacity expansion for **SiC and GaN**
- Further capacity expansion for **300 mm** in **Villach and Dresden**
- Further capacity expansion for **200 mm** in **Kulim**
- **Focused insourcing** from silicon foundries
- **Clean room** for WBG / 300 mm and major office buildings (slightly above €1bn over five years)
- **~€2.4bn** investments planned in FY22

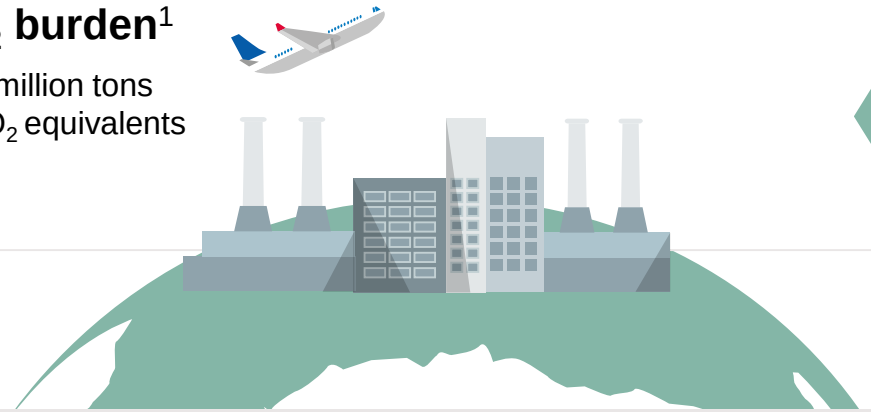
1 Frontend clean rooms and major office buildings are not included

ESG: targets and achievements

We contribute a net CO_2 reduction of more than 70 million tons

CO_2 burden[1]

2.18 million tons of CO_2 equivalents



Ratio ~1:33

CO_2 savings[2]

72.45 million tons of CO_2 equivalents

Net ecological benefit: **CO_2 emissions reduction of more than 70 million tons**

Infineon is excellent in resource efficiency

We are committed to CO_2 neutrality by 2030

Our CO_2-saving applications are high-growth, we are part of the solution!

The ~1:33 ratio is expected to further improve in the coming years

1 | **2** For explanatory notes see “ESG footnotes” in the appendix.

Note: Compared to the last fiscal year, the increase in CO_2 burden can be mainly explained by the inclusion of the data from Cypress

Infineon is excellent in resource efficiency and committed to CO_2 neutrality – sustainability is in our DNA

Infineon ranks among the 10 percent[1] most sustainable companies in the world

In CY19, we used resources in our manufacturing processes much more efficiently than the global average of the semiconductor industry[1]:

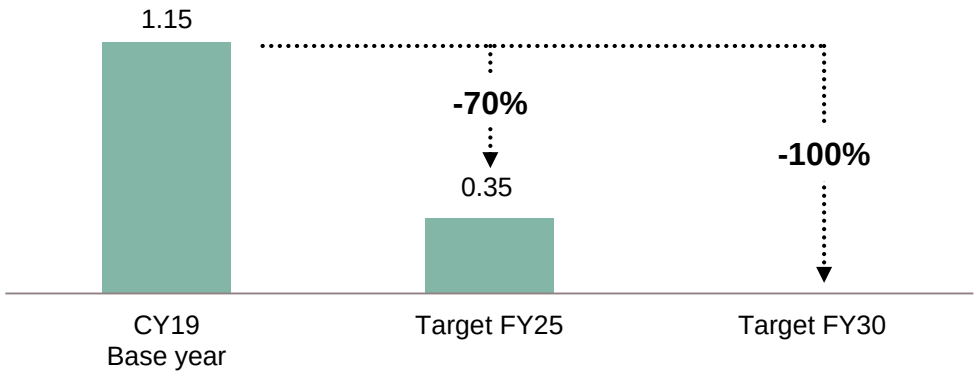
53%
less electricity consumed
per cm² manufactured wafer

31%
less water consumed
per cm² manufactured wafer

66%
less waste generated
per cm² manufactured wafer

Infineon's CO_2 target[2] by 2025 and 2030

Net CO_2 emissions in million tons of CO_2 equivalents[2]



1. Avoiding direct emissions and further reducing energy consumption
2. Purchasing green electricity with guarantees of origin
3. Compensate the smallest part by certificates that combine development support and CO_2 abatement

1 Based on the results of *The Sustainability Yearbook 2020* by S&P Global in cooperation with RobecoSam | **2** Related to Scope 1 and 2 emissions

High-growth applications offer further additional CO_2 savings potential

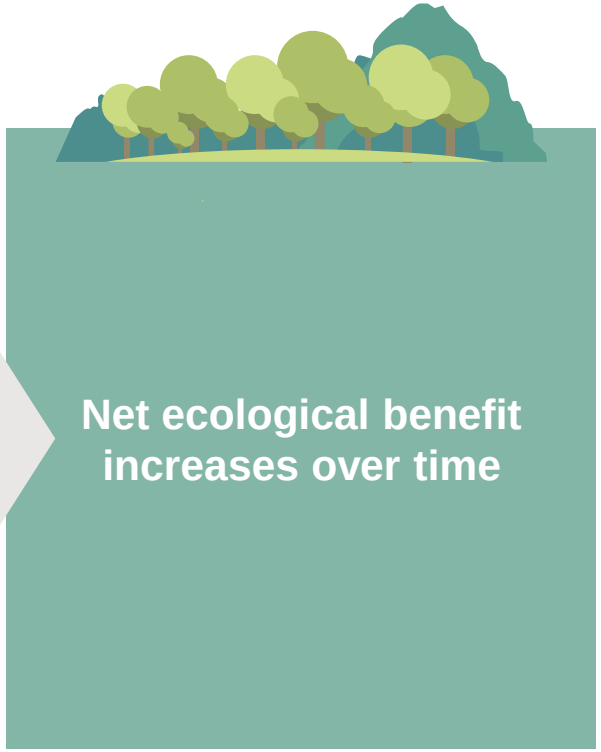
In CY20:

Wind energy: Annual installation capacity increased over 80%[1]

PV energy: Annual installation capacity increase of ~15%[2]

Drives: Increasing penetration of more efficient drives[3]

EVs: Increased sales contributed to an average fleet emission reduction of 14 g/km in Europe[4]



1 Wood Mackenzie: *Global Wind Power Market Outlook, Q2 2021*. June 2021 | **2** Based on or includes content supplied by IHS Markit Climate and Sustainability Group: *PV Installations Tracker, Q2 2021*. June 2021
3 Based on or includes research from Omdia*: Industrial Motor Control Sourcebook 2020.* December 2020 | **4** CO_2 emissions from new passenger cars in Europe: Car manufacturers' performance in 2020 - 08/2021

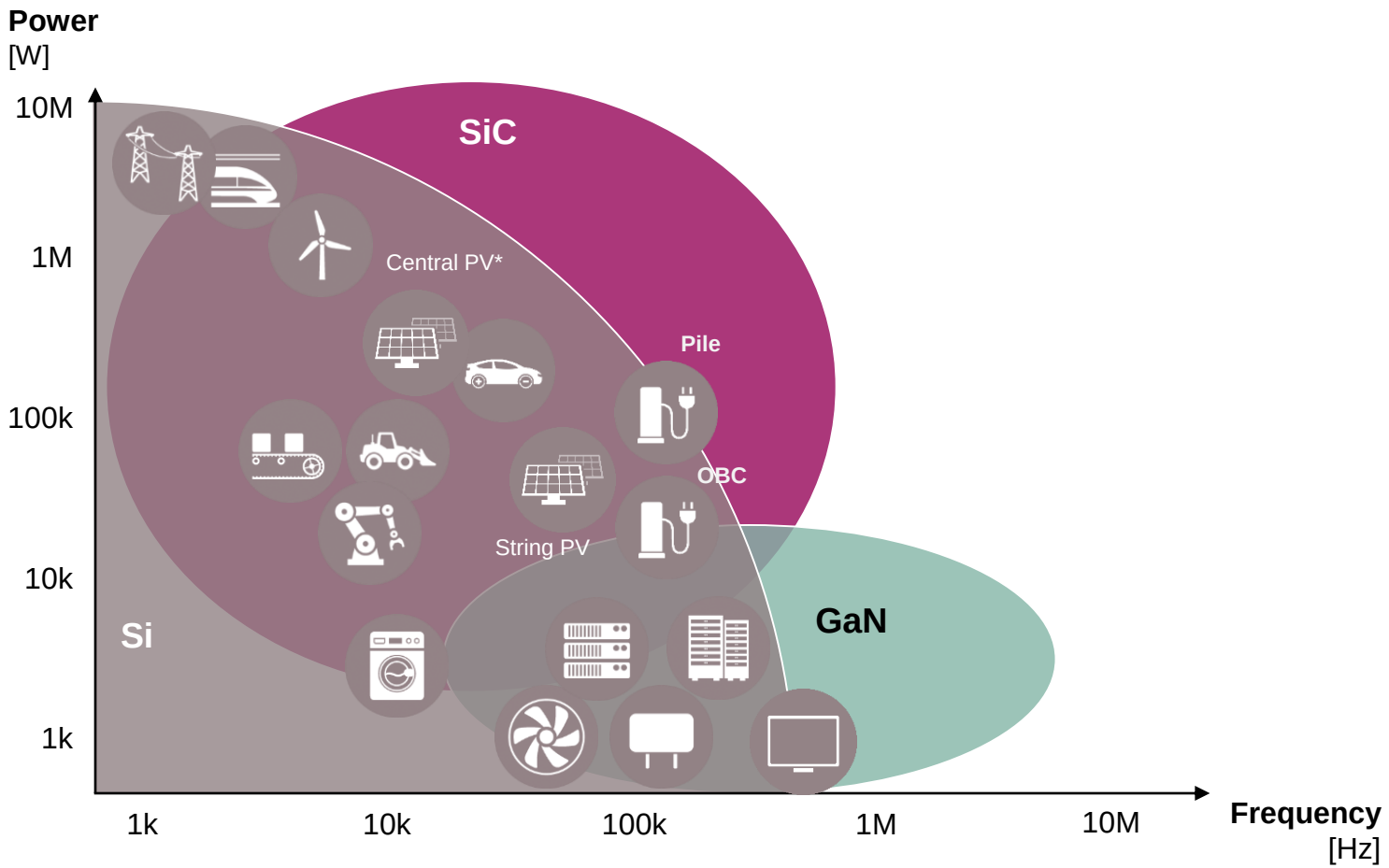
External recognitions confirm our engagement in contributing to a sustainable society

	Rating/Score	Scale	Date
MSCI ESG	AA	CCC to AAA	02/2021
CDP	B climate scoring B water scoring	F to A	12/2020
Ecovadis	98th percentile “Gold” award	0 to 100	11/2020
Dow Jones Sustainability Index	81 Dow Jones Sustain-ability™ World and Europe Index listing	0 to 100	11/2021
Ethibel Sustainability Index Excelence Europe”	Index member	-	05/2020
ISS ESG Corporate Rating	B- Prime Status	D- to A+	01/2021
FTSE4Good Index	Index member	-	06/2021
Euronext Vigeo Eurozone 120 Index Euronext Vigeo Europe 120 Index	Indices member	-	06/2020
Sustainalytics	77 “Outperformer” level	0 to 100	06/2020

Infineon's Wide Band Gap Strategy

Leveraging full potential based on the power ratings and switching frequency required by the application

Comparison of technologies



Si

- Si is the mainstream technology
- Targeting 25 V – 6.5 kV
- Suitable from low to high power

SiC

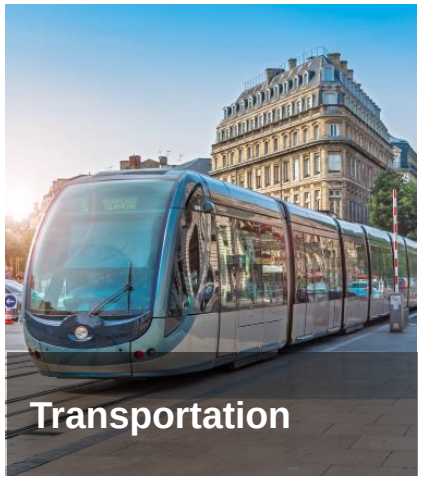
- SiC complements Si in many applications and enables new solutions
- Targeting 650 V – 3.3 kV
- High power – high switching frequency

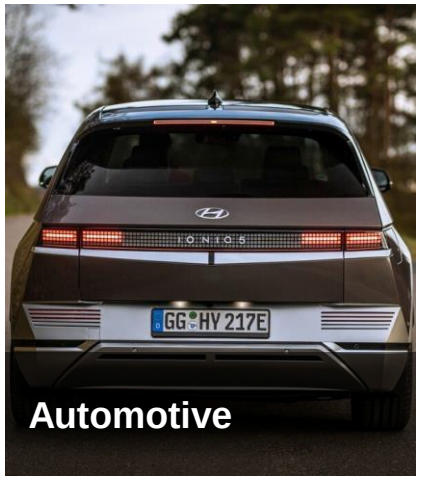
GaN

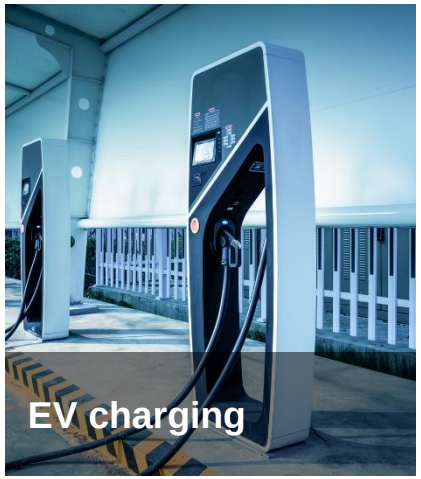
- GaN enables new horizons in power supply applications and audio fidelity
- Targeting 80 V – 600 V
- Medium power – highest switching frequency

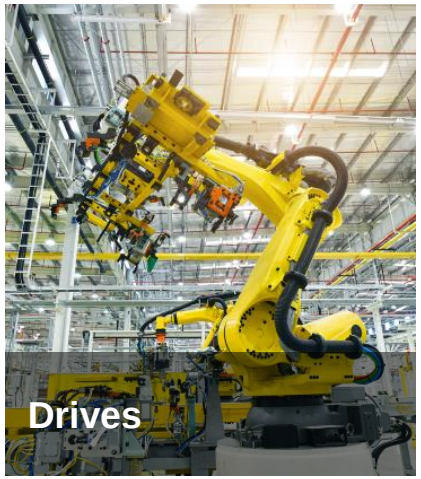
SiC – Infineon is serving all relevant applications

Focus applications









Infineon serves

> 3,000

customers directly or via distribution

Customers

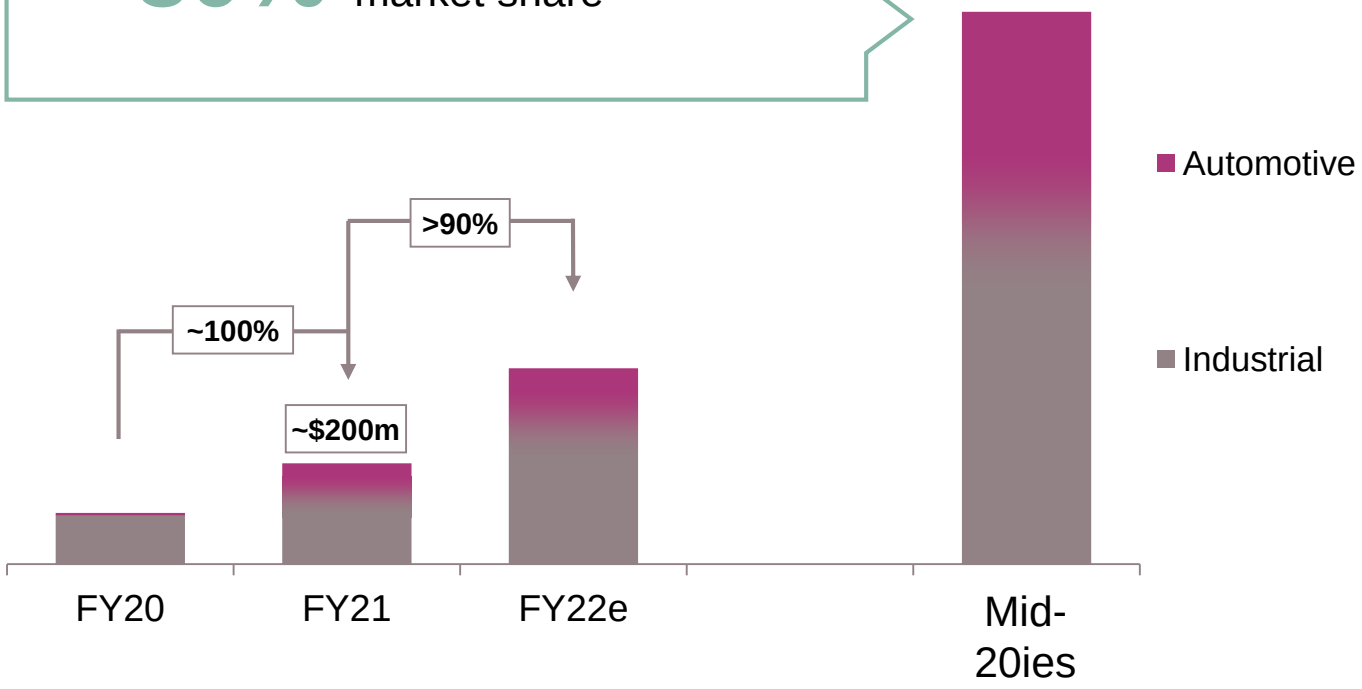
ABB, alpitronic, 中国中车 CRRC, DELTA, HYUNDAI, LG, LITEON, Schneider Electric, SIEMENS, SMA, solaredge, 阳光电源 SUNGROW, TRITIUM, XPENG

SiC – US$ 1 billion revenue in sight

SiC revenue development

~$1bn revenue

~30% market share

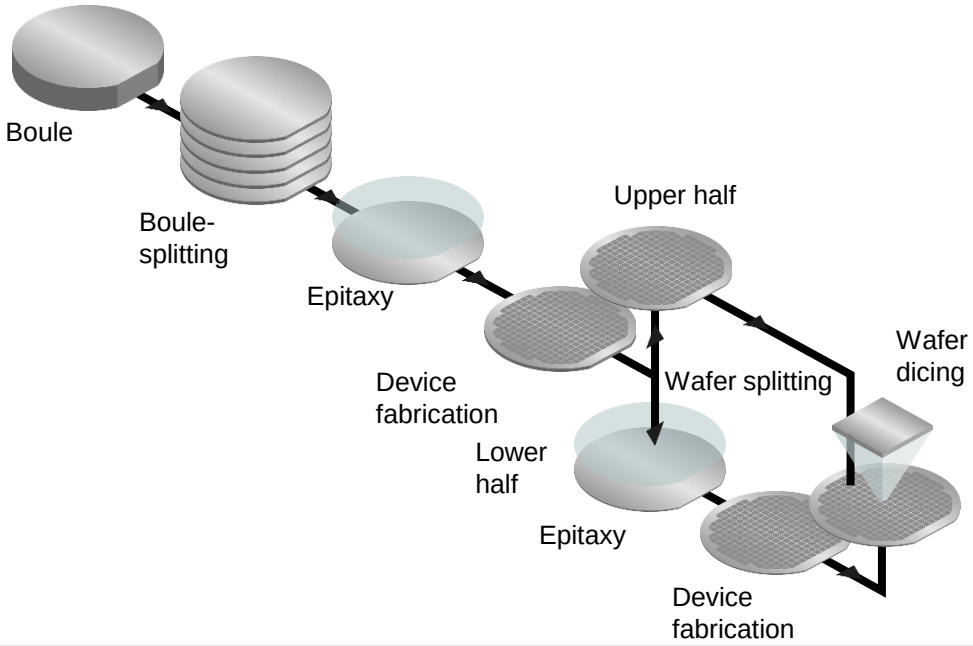


Infineon's success factors

- Best in class Trench MOSFET on the market
- 2nd Gen. CoolSiC™ Trench MOSFET will be launched in FY22
- Broadest portfolio fits customers' individual needs
- Scalable portfolio allows for easy and seamless upgrade from IGBT to SiC-based inverters
- Strong module capabilities
- System expertise and customer access

Our Cold Split technology leads to significant reduction of raw material losses during SiC manufacturing

Cold Split technology

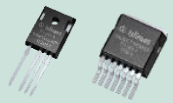
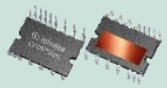
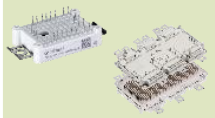


- First product qualified on Cold Split technology
- Ramping pilot line and prepare volume production
- 3 supplier LTAs for boules and wafers in place

	Crystal › Technology	# of wafers (indexed)
Today	SiC boule ····· Sawing Grinding ·····	1x
	Traditional wire sawing wastes ~75% of raw material!	
2021	SiC boule ····· Boule Splitting Grinding ·····	Up to 2x
	Boule splitting reduces raw material losses by 50%!	
Next step	SiC wafer ····· Wafer Splitting ·····	2x
	Wafer splitting results in minimal raw material losses!	

Strong CoolSiC™ portfolio expansion: by packages and by voltages

Broadest and best-in-class SiC portfolio

package options / voltages	Industrial						Automotive grade			
	CoolSiC™ Diode	CoolSiC™ Hybrid		CoolSiC™ MOSFET			CoolSiC™ Diode	CoolSiC™ Hybrid	CoolSiC™ MOSFET	
	Discrete	Discrete	Module	Discrete	IPM	Module	Discrete	Discrete	Discrete	Module
										
600 V										
650 V										
1200 V										
1700 V										

Continuous expansion of portfolio

SiC and GaN capacity expansion to respond to fast growing demand

Villach, Austria

- 150/200 mm Si lines will be converted to SiC and GaN manufacturing while reusing non specific equipment
- → SiC capacity secured in Villach
- → GaN scaling-up to volume manufacturing

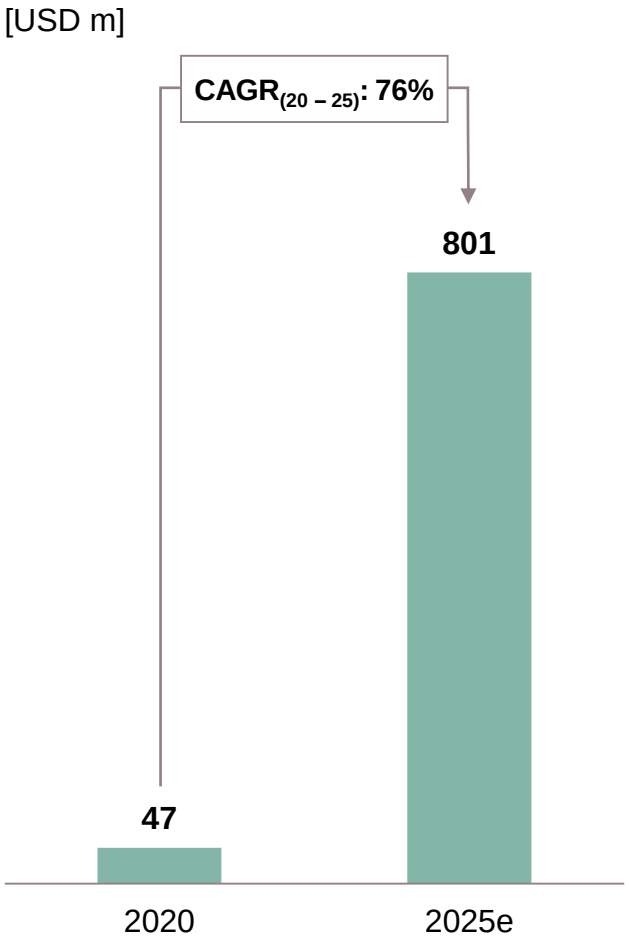
Further expansion in Kulim

Kulim, Malaysia

- Transfers of
  - 200 mm Si
  - WBG epitaxy as first step
- Ground ready for 3rd module

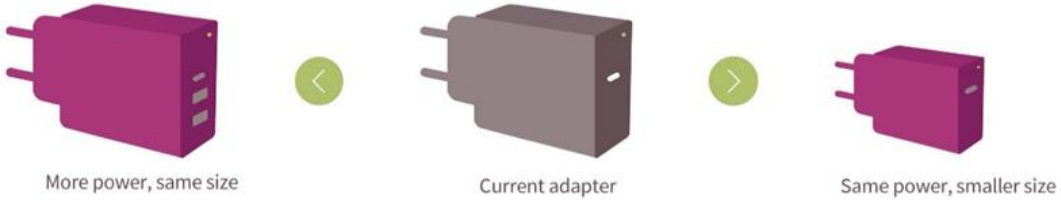
GaN technology – Infineon well positioned to address key markets

GaN market forecast[1]



Key values of GaN vs Si

Higher power density in adapters and chargers



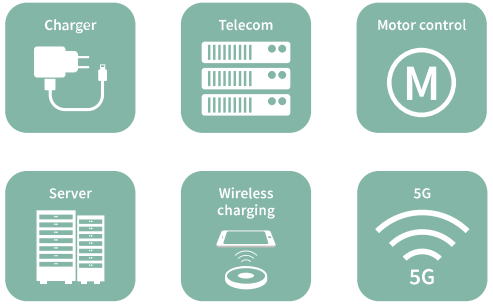
10x switching frequency	**> 2%** more power efficiency	**20%** lower System Cost	**25%** higher power density	**3x** less weight

We combine leading-edge system and application understanding with additional strengths:

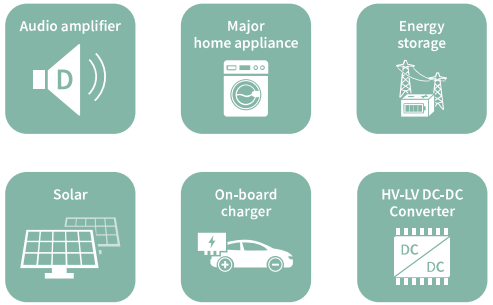
Broad GaN IP portfolio, large R&D force and best-in-class manufacturing landscape

Applications

Focus applications



Emerging applications

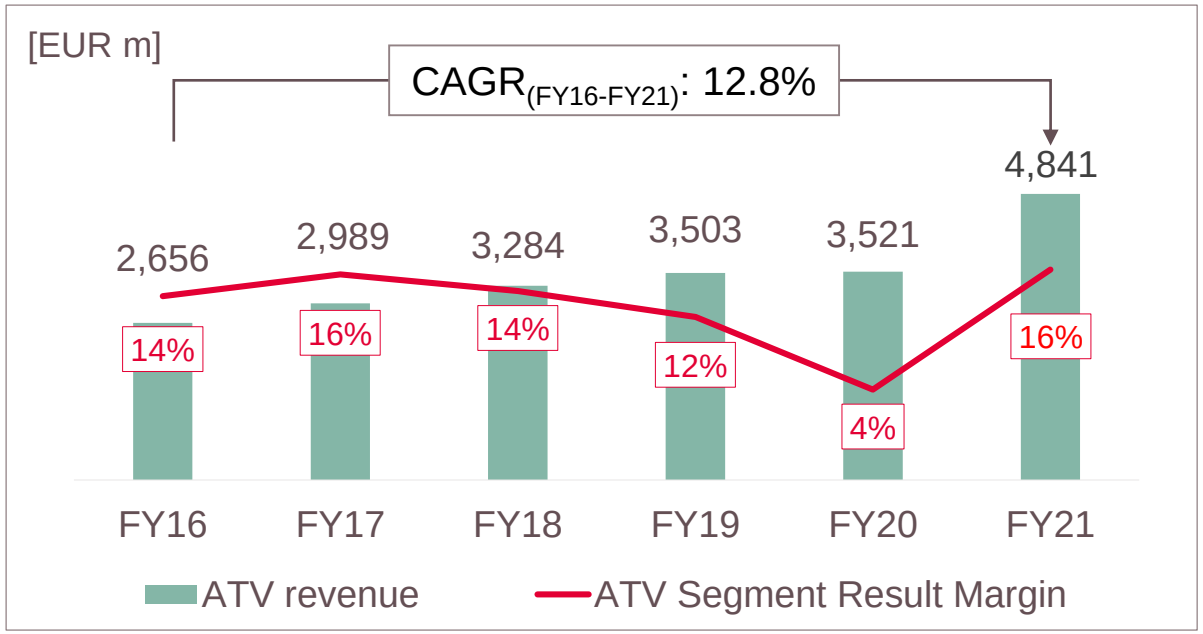


1 GaN power devices market forecast. Yole Développement (Yole): *Compound Semiconductor Quarterly Market Monitor*. Q3 2021

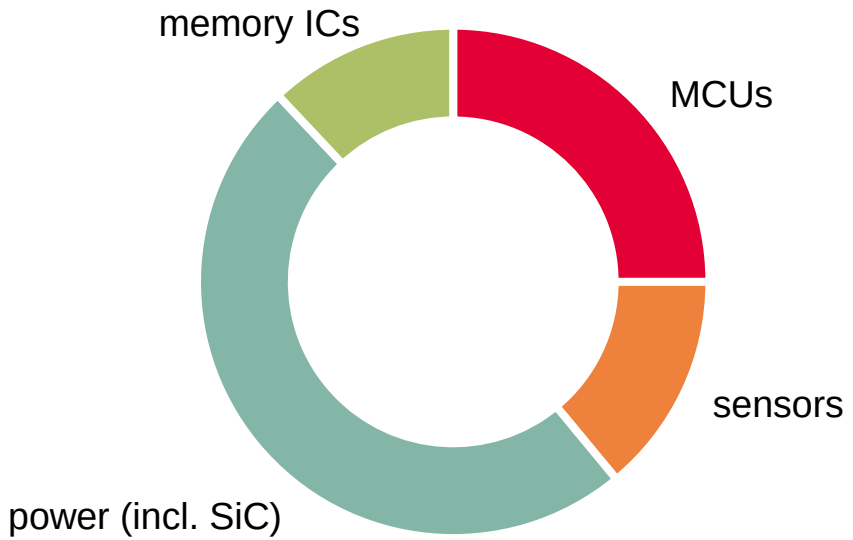
Automotive

ATV at a glance

ATV revenue and Segment Result Margin



FY21 revenue split by product group



Key customers

APTIV · Astemo · BorgWarner · BOSCH · BYD 比亚迪汽车 · Continental · DENSO · HELLA

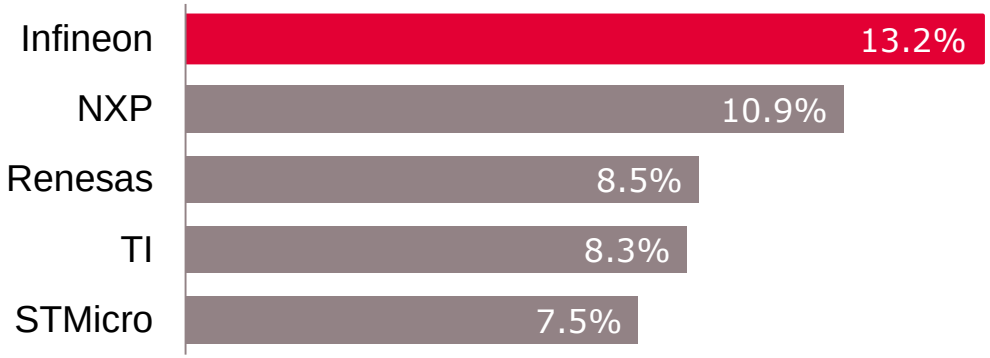
HYUNDAI · LEAR CORPORATION · Mando · MITSUBISHI ELECTRIC · Nidec · Valeo · veoneer · vitesco TECHNOLOGIES · ZF

Market outlook for ATV division's target applications

Applications	Market Outlook for CY22
	› Market demand-supply uncertainties to continue into CY22 due to COVID-19 pandemic and component supply limitations › Gradual easing of semiconductor shortages throughout the year expected; risks of further supply chain disruptions remain › Normalization of extraordinary effects likely, e.g. elevated share of premium cars
	› Electromobility momentum expected to continue › Stricter CO_2 regulations, government incentives as well as consumer demand expected to support the growth momentum › Acceleration of OEMs' xEV roadmaps, build-up of battery capacities are expected to continue into 2022
	› L1 and L2 will see strong growth as L0 share declines › L2+ shipments will grow from a comparatively small base › Robotaxi pilots and small-scale launches continue

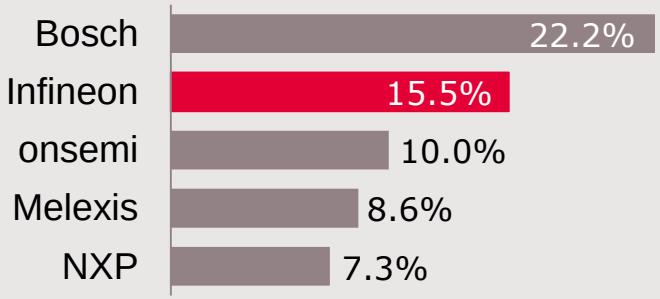
Infineon's top market position is built on system competence based on an industry-leading product portfolio

Automotive semiconductors (2020 total market: $35.0bn)

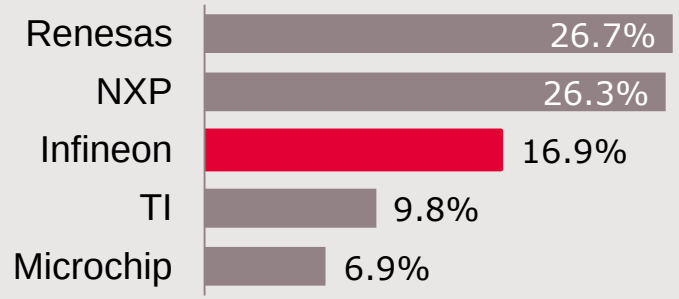


- Strengthened #1 position; increasing distance to #2
- #1 in power semiconductors
- Undisputed #1 in automotive NOR Flash memory ICs
- #2 position in sensors
- Solid #3 position in microcontrollers due to strong demand in AURIX™, TRAVEO™ and PSoC™ families

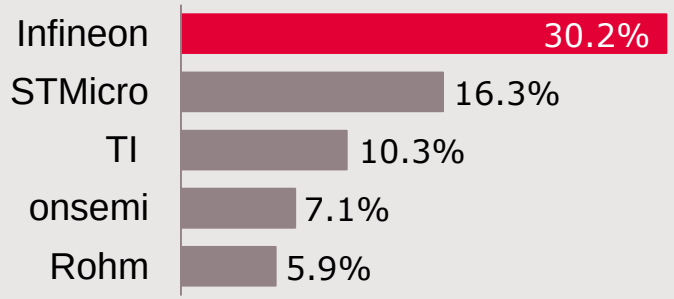
Sensors



Microcontrollers



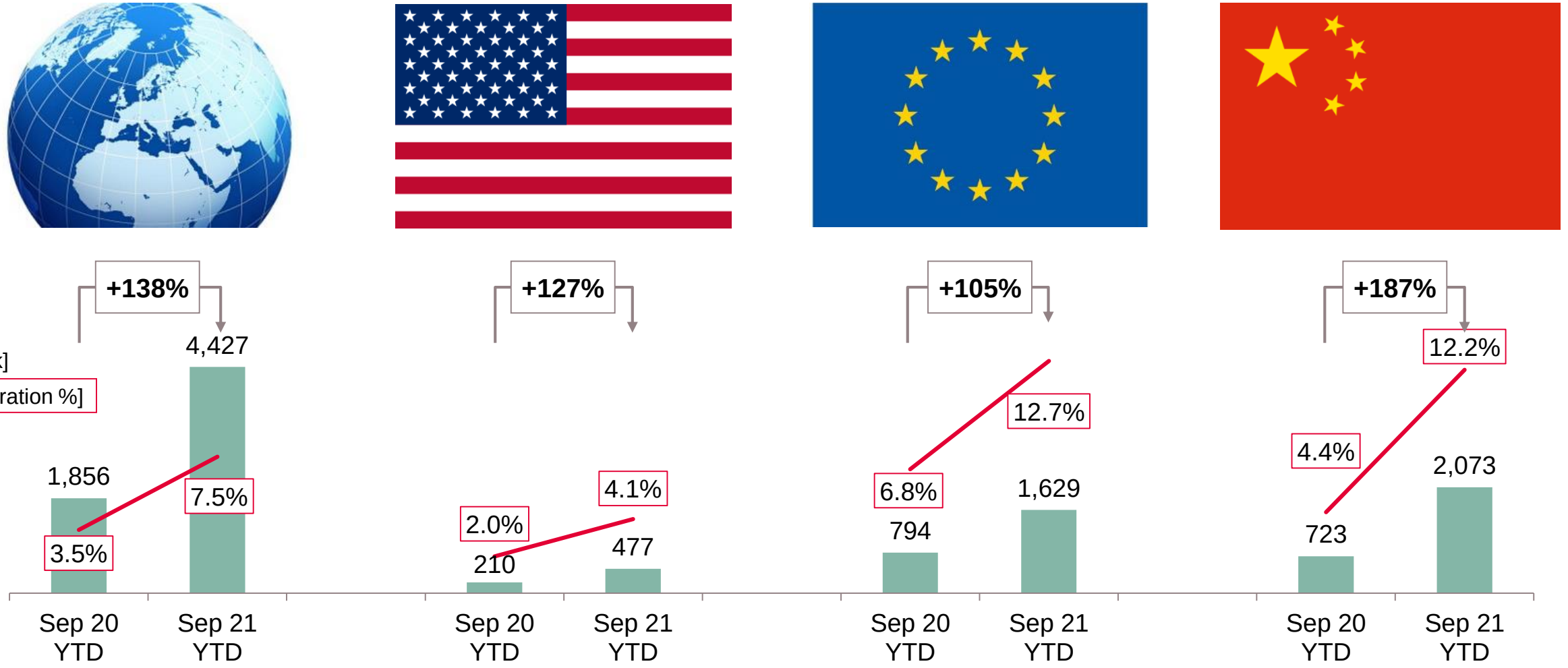
Power semiconductors



Strategy Analytics: *Automotive Semiconductor Vendor Market Shares*. April 2021.

Electromobility

In the first nine month of CY21, xEV (PHEV + BEV) sales more than doubled y-y in all regions reaching ~4.5m units globally



Source: Based on or includes content supplied by IHS Markit Automotive: *PEV Volumes*. November 2021

The road to emission-free cruising: Governments and OEMs indicated when to ban the ICE

/ Government regulations

2035:
- EU: all new cars zero-emission.
- China: public transport vehicles to be fully electrified.
- Canada: no new ICE on sales.
- California, Massachusetts, New Jersey, Thailand: no ICE on the street.

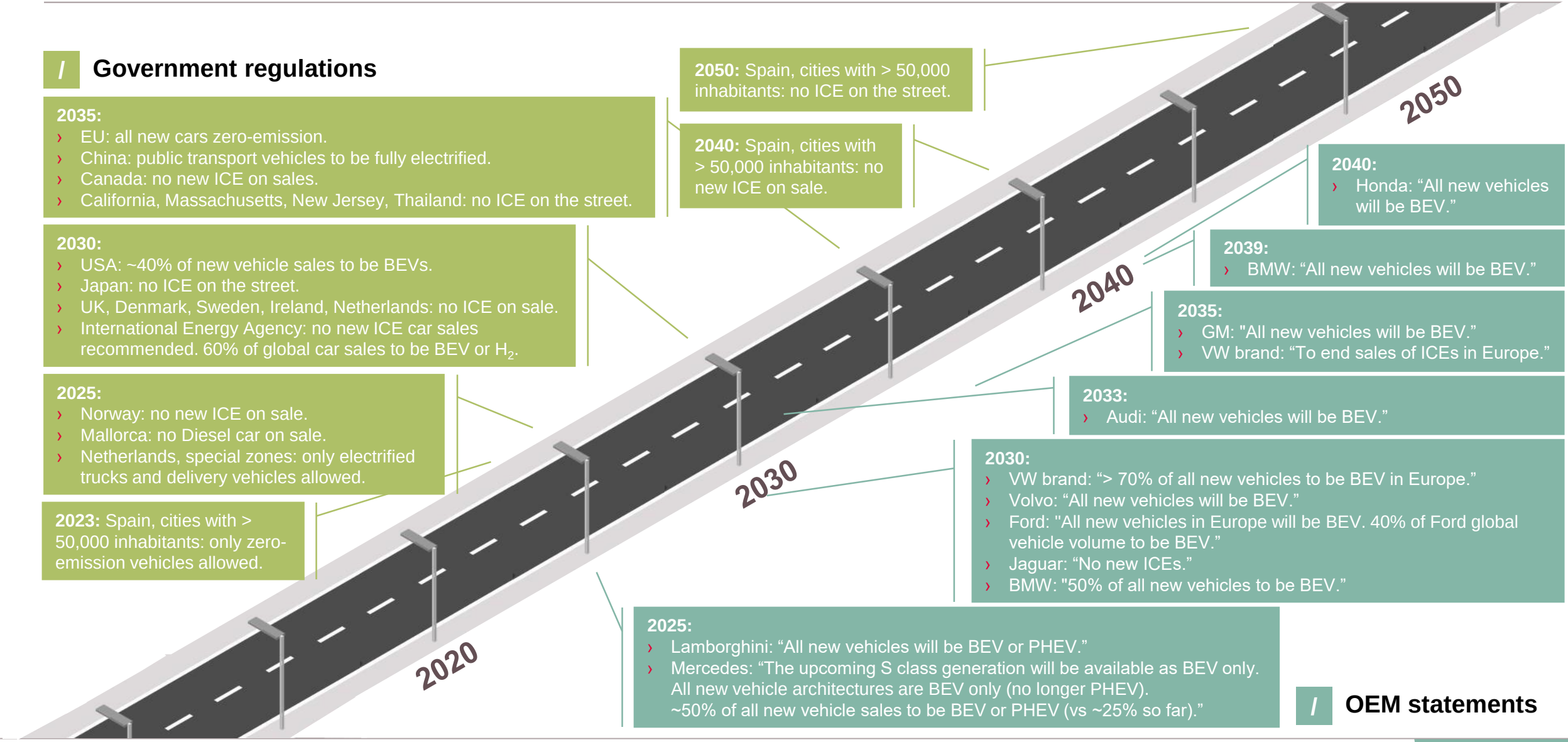
2030:
- USA: ~40% of new vehicle sales to be BEVs.
- Japan: no ICE on the street.
- UK, Denmark, Sweden, Ireland, Netherlands: no ICE on sale.
- International Energy Agency: no new ICE car sales recommended. 60% of global car sales to be BEV or H_2.

2025:
- Norway: no new ICE on sale.
- Mallorca: no Diesel car on sale.
- Netherlands, special zones: only electrified trucks and delivery vehicles allowed.

2023: Spain, cities with > 50,000 inhabitants: only zero-emission vehicles allowed.

2050: Spain, cities with > 50,000 inhabitants: no ICE on the street.

2040: Spain, cities with > 50,000 inhabitants: no new ICE on sale.



2040:
- Honda: “All new vehicles will be BEV.”

2039:
- BMW: “All new vehicles will be BEV.”

2035:
- GM: "All new vehicles will be BEV.”
- VW brand: “To end sales of ICEs in Europe.”

2033:
- Audi: “All new vehicles will be BEV.”

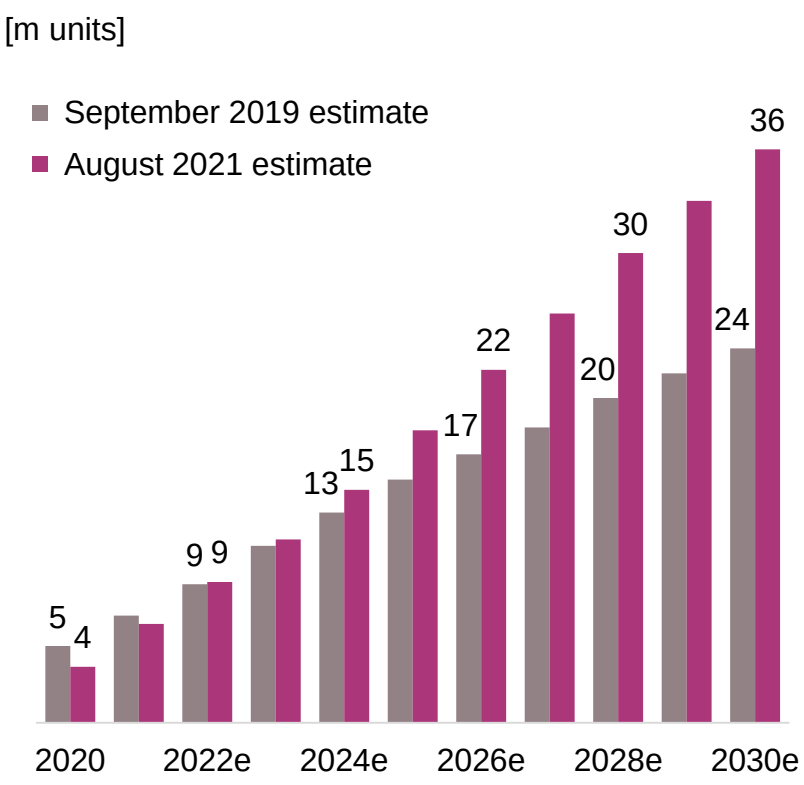
2030:
- VW brand: “> 70% of all new vehicles to be BEV in Europe.”
- Volvo: “All new vehicles will be BEV.”
- Ford: "All new vehicles in Europe will be BEV. 40% of Ford global vehicle volume to be BEV.”
- Jaguar: “No new ICEs.”
- BMW: "50% of all new vehicles to be BEV.”

2025:
- Lamborghini: “All new vehicles will be BEV or PHEV.”
- Mercedes: “The upcoming S class generation will be available as BEV only. All new vehicle architectures are BEV only (no longer PHEV). ~50% of all new vehicle sales to be BEV or PHEV (vs ~25% so far).”

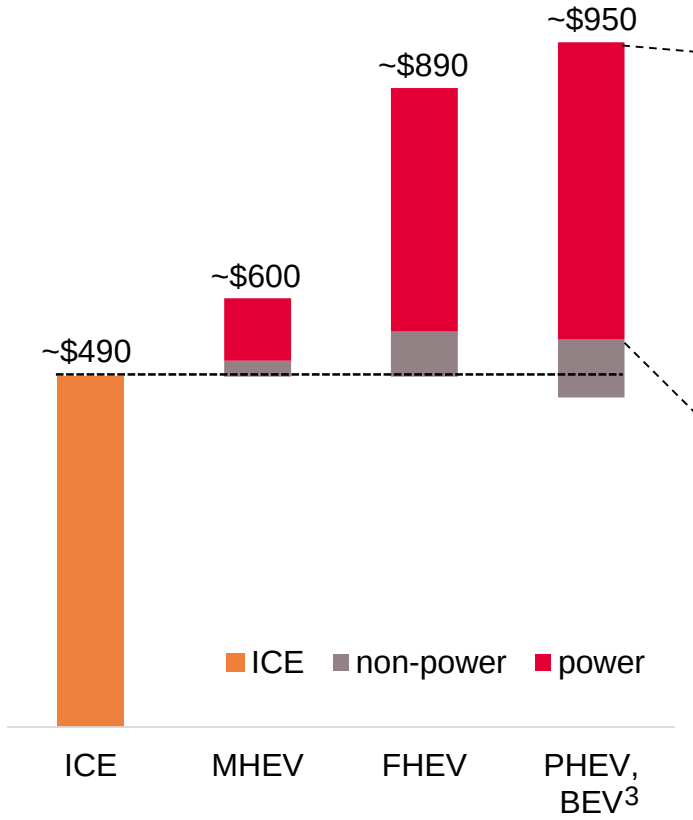
/ OEM statements

The penetration of PHEV + BEV is accelerating; the incremental content of power semis in xEV is a significant opportunity for Infineon

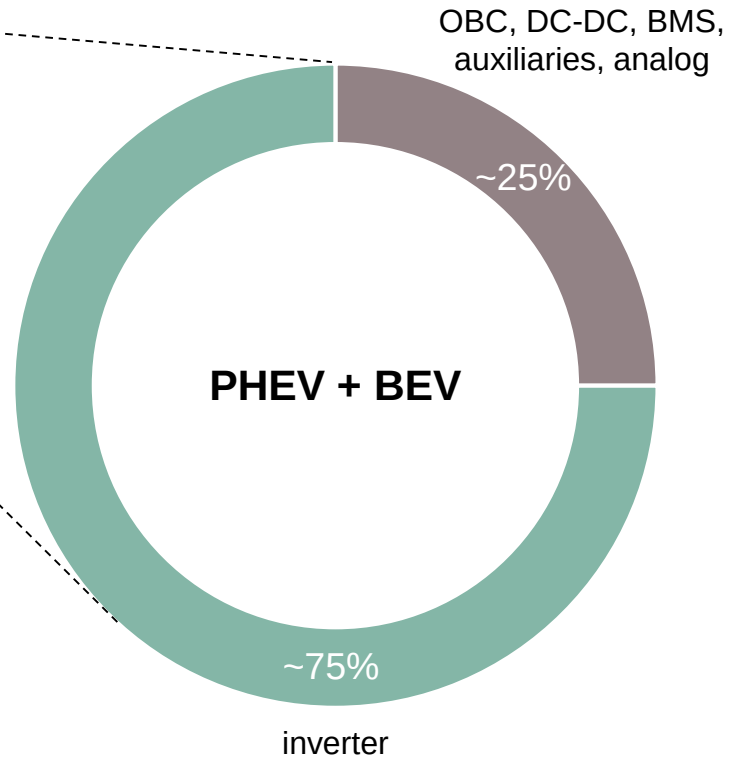
PHEV + BEV annual car production[1]



2021 average xEV semi content[2]



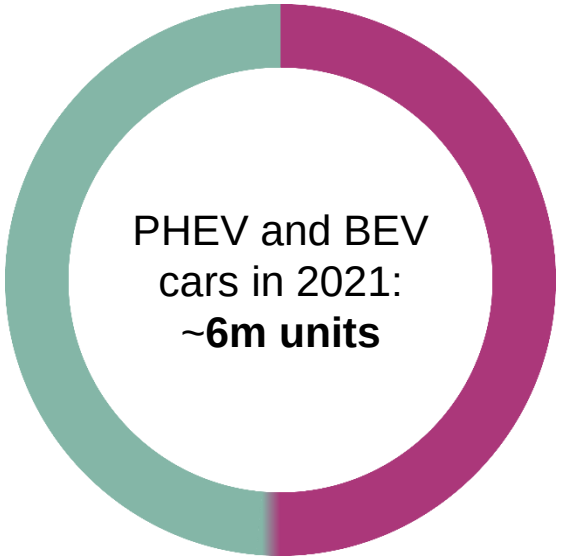
Incremental power semi by application



1 Based on or includes content supplied by IHS Markit Automotive: *Alternative Propulsion Forecast.* September 2019, August 2021.
2 Strategy Analytics: *Automotive Semiconductor Demand Forecast 2019 - 2028*. July 2021; Infineon. "power" includes voltage regulators, ADCs and ASICs.
3 Due to missing ICE engine in BEV the weighted incremental semiconductor content for PHEV and BEV starts below the "~$490" line.

For newly produced cars in CY21, about every second inverter for a PHEV or BEV car is equipped with Infineon power semiconductors

2021e PHEV + BEV inverters[1]



Share of inverters equipped with Infineon chips or modules

Ex. of OEMs powered by Infineon

Examples of SiC design-wins

- Infineon has an excellent position to win upcoming SiC-based xEV platforms:
  - leverage huge IGBT customer base with broadest portfolio and full system solution
  - seamless and cost-effective upgrade path across entire power range

1 Based on or includes content supplied by IHS Markit Automotive: *Alternative Propulsion Forecast.* August 2021; Strategy Analytics: *Automotive Semiconductor Demand Forecast 2019 - 2028*. July 2021; Infineon

Automated Driving

The car of the future is driving digitalization in many aspects and Infineon provides the ingredients

ADAS/AD

- object recognition
- advanced spatial sensing

- MCU (AURIX™, TRAVEO™ 2, PSoC™)
- radar sensor
- NOR flash and RAM memory

software-over-the-air

- remote OS updates
- secure feature upgrades

- NOR flash memory
- security solution

infotainment and HMI

- seamless digital entertainment
- always-on, secure connectivity
- intuitive user interface (UI)

- MCU (AURIX™, TRAVEO™ 2, PSoC™)
- Wi-Fi, Bluetooth, USB Type C
- touch controller with CapSense™

digital instrument cluster

- real-time driver information
- user-specific digital content

- MCU (AURIX™, TRAVEO™ 2, PSoC™)
- NOR flash and RAM memory

Car of the future

comfort / premium

- automatic exterior and interior lighting
- passenger-specific automatic settings

- MCU (AURIX™, TRAVEO™ 2, PSoC™)
- pressure and magnetic sensors
- LED driver ICs

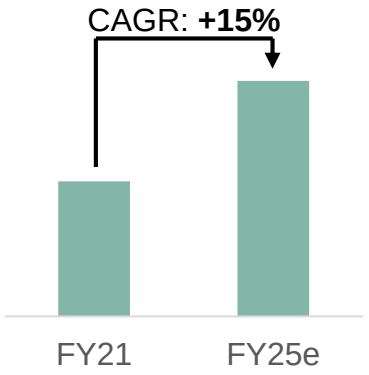
trends | examples of benefitting products

The Infineon AURIX™ MCU family has become the first-choice automotive architecture for high-growth and safety-critical applications

Infineon AURIX™ revenue development over time

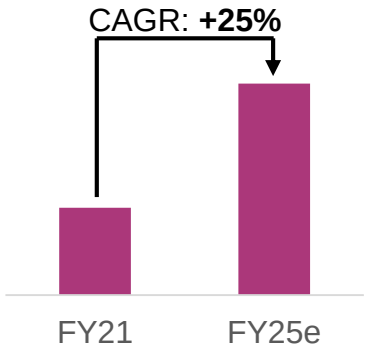
Powertrain

- ICE engine management
- ICE transmission
- xEV motor control



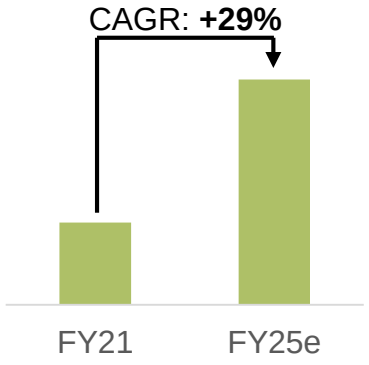
Classical safety

- power steering
- braking
- airbag



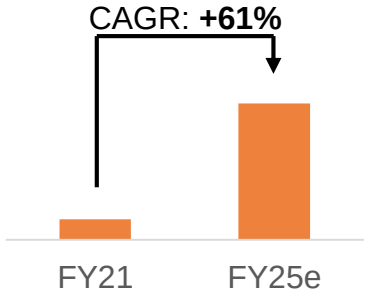
ADAS/AD

- camera host control
- sensor fusion host control
- radar signal pre-processing



Domain and zone control

- drive domain
- body & convenience domain
- zone control



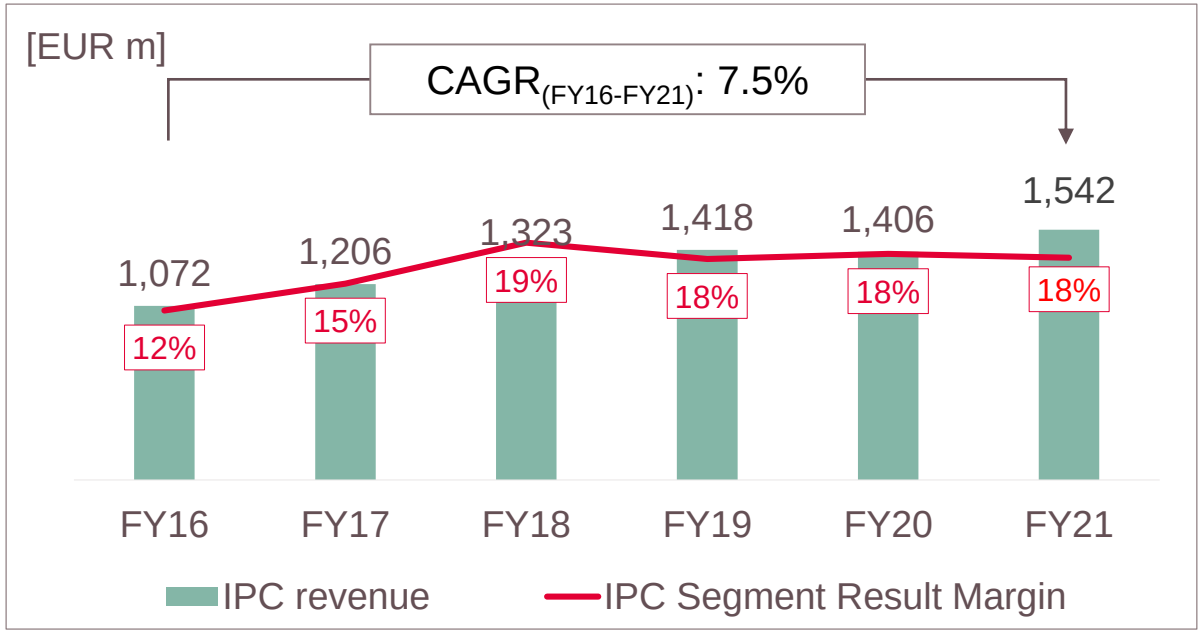
Example of AURIX™ platform design-win

~7x AURIX™ in powertrain **+** **~7x AURIX™** in classical safety **+** **~10x AURIX™** in ADAS/AD **+** **~11x AURIX™** in domain and zone control **=** **~35x AURIX™** in OEM platform

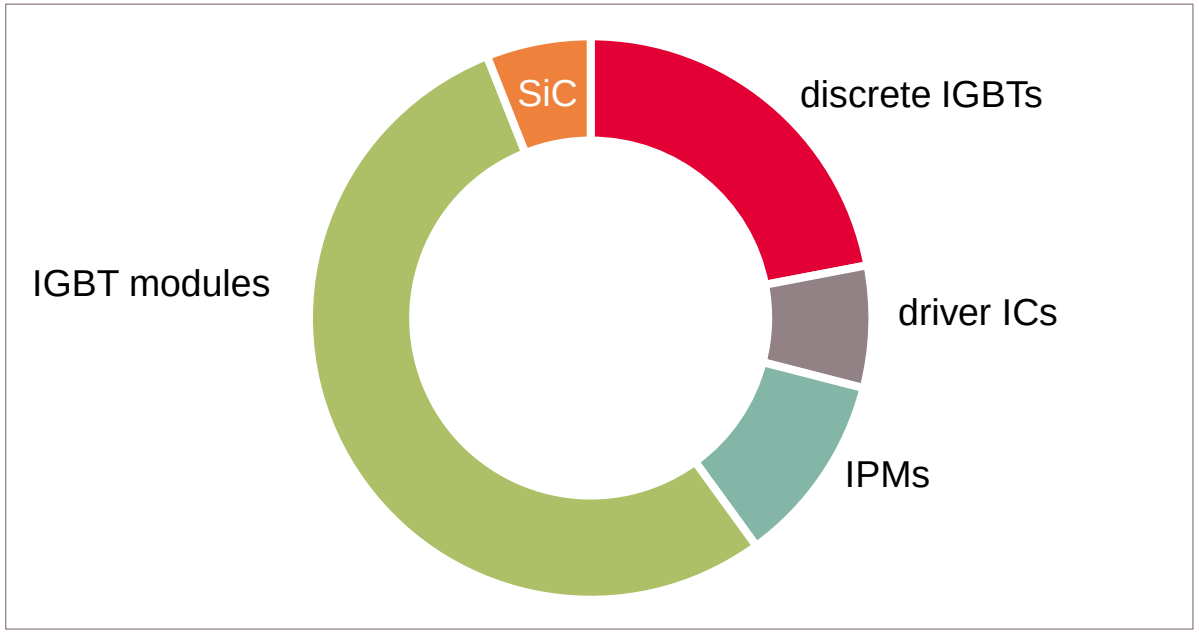
Industrial Power Control

IPC at a glance

IPC revenue and Segment Result Margin



FY21 revenue split by product group (indicative)



Key customers

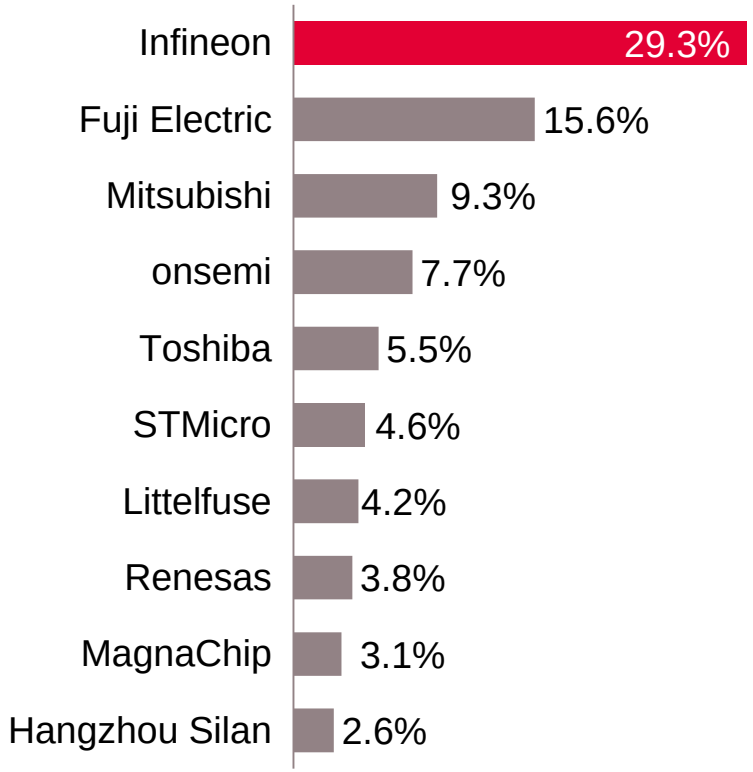
ABB, ALSTOM, 中国中车 CRRC, Danfoss, GOLDWIND, Inovance, LG, Midea, OMRON, Rockwell Automation, Schneider Electric, SEMIKRON innovation + service, SIEMENS, SMA, SUNGROW, Vestas, YASKAWA

Market outlook for IPC division's target applications

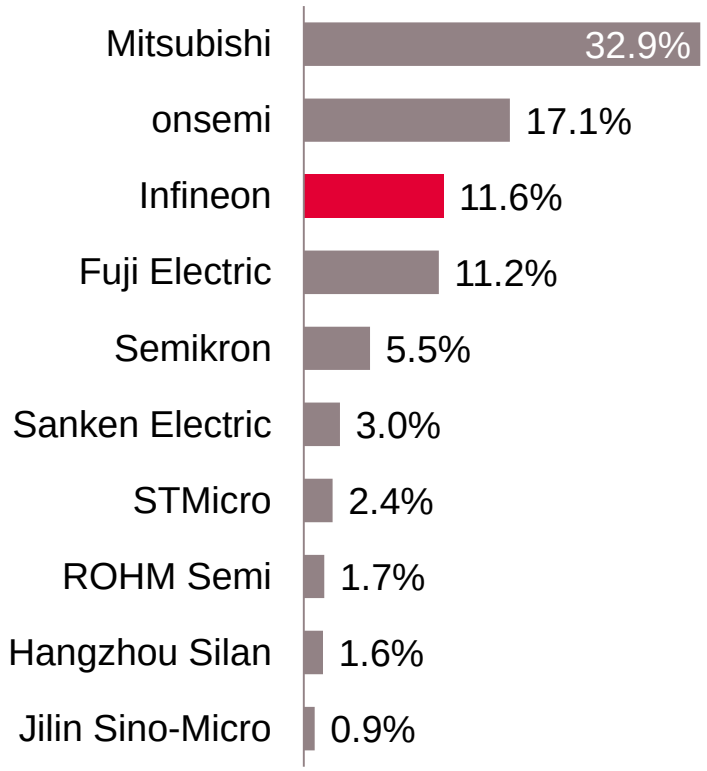
Applications (% of FY21 segment revenue)		Market Outlook for CY22
	~33%	› After strong recovery in CY21, growth rates returning to long-term averages with demand still exceeding supply and long lead times in CY22.
	~28%	› Wind: installations forecasted at similar level as in CY21 › PV with ongoing double-digit growth in installations
	~17%	› Demand still driven by energy efficiency incentives for major appliances; growth after strong surge in CY21 expected to be flattish
	~7%	› Overall expectations dominated and dampened by still delayed recovery for traction in China; growth expected for delivery vehicles and eTrucks, as well as for traction projects in other regions
	~8%	› Strong growth of xEV driving charging infrastructure; continuous installation of renewable energy generation driving energy storage systems
	~7%	› Long-term positive outlook driven by general trend of electrification in emerging applications (e.g. eMarine)

Clear leader in discrete IGBTs and IGBT modules; fostering position in IPMs

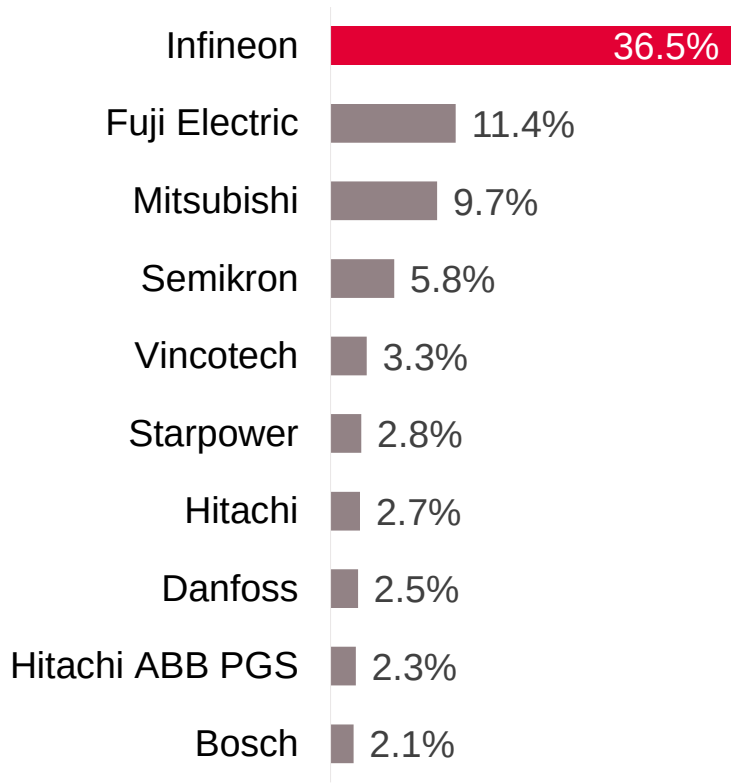
Discrete IGBTs
2020 total market: $1.59bn



IPMs
2020 total market: $1.43bn

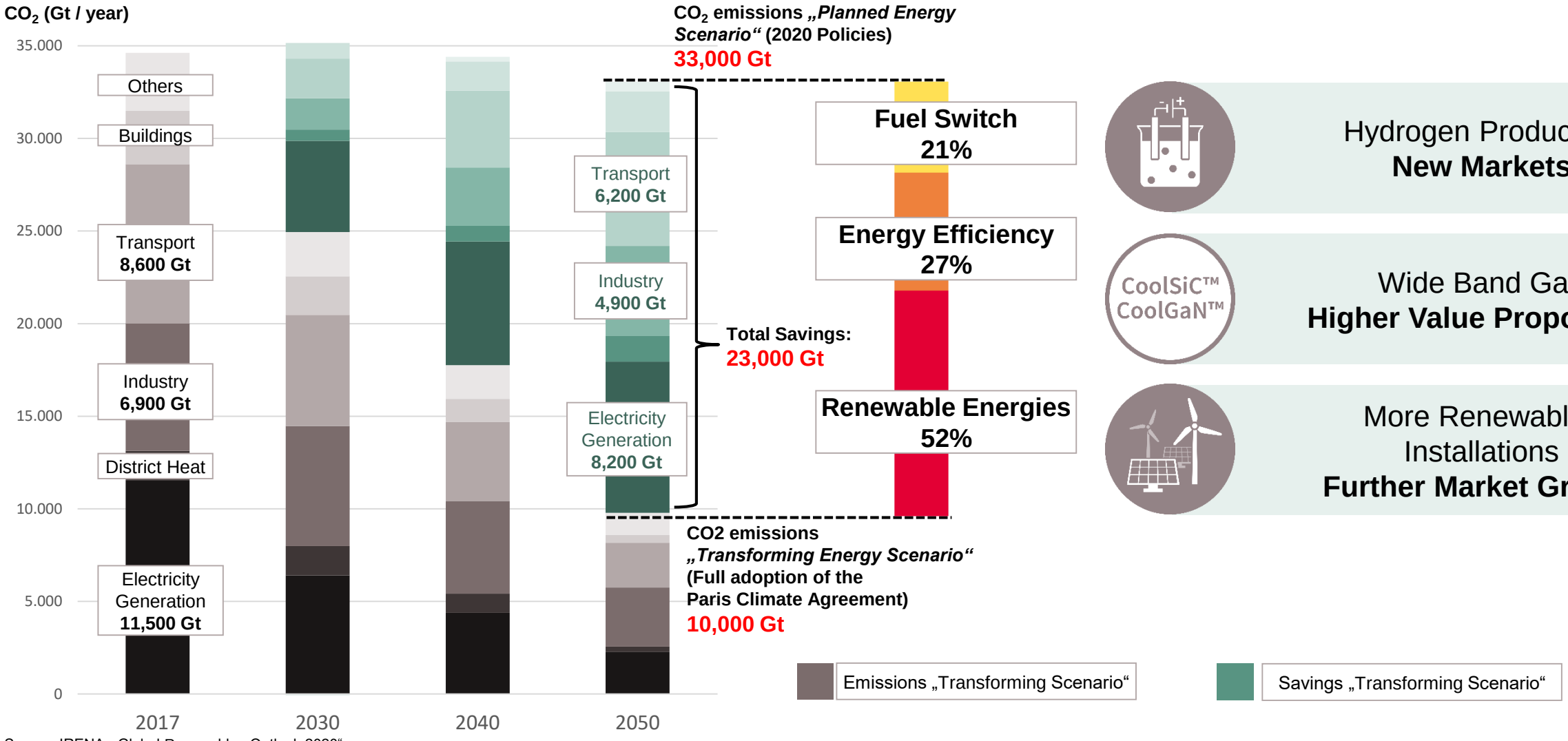


IGBT modules[1]
2020 total market: $3.63bn



1 Including standard (non-integrated) IGBT modules and power integrated modules (PIMs) / converter inverter brake (CIB) modules
Based on or includes research from Omdia: *Power Semiconductor Market Share Database 2020.* September 2021

Infineon will benefit from all CO_2 saving measures



Source: IRENA, „Global Renewables Outlook 2020“

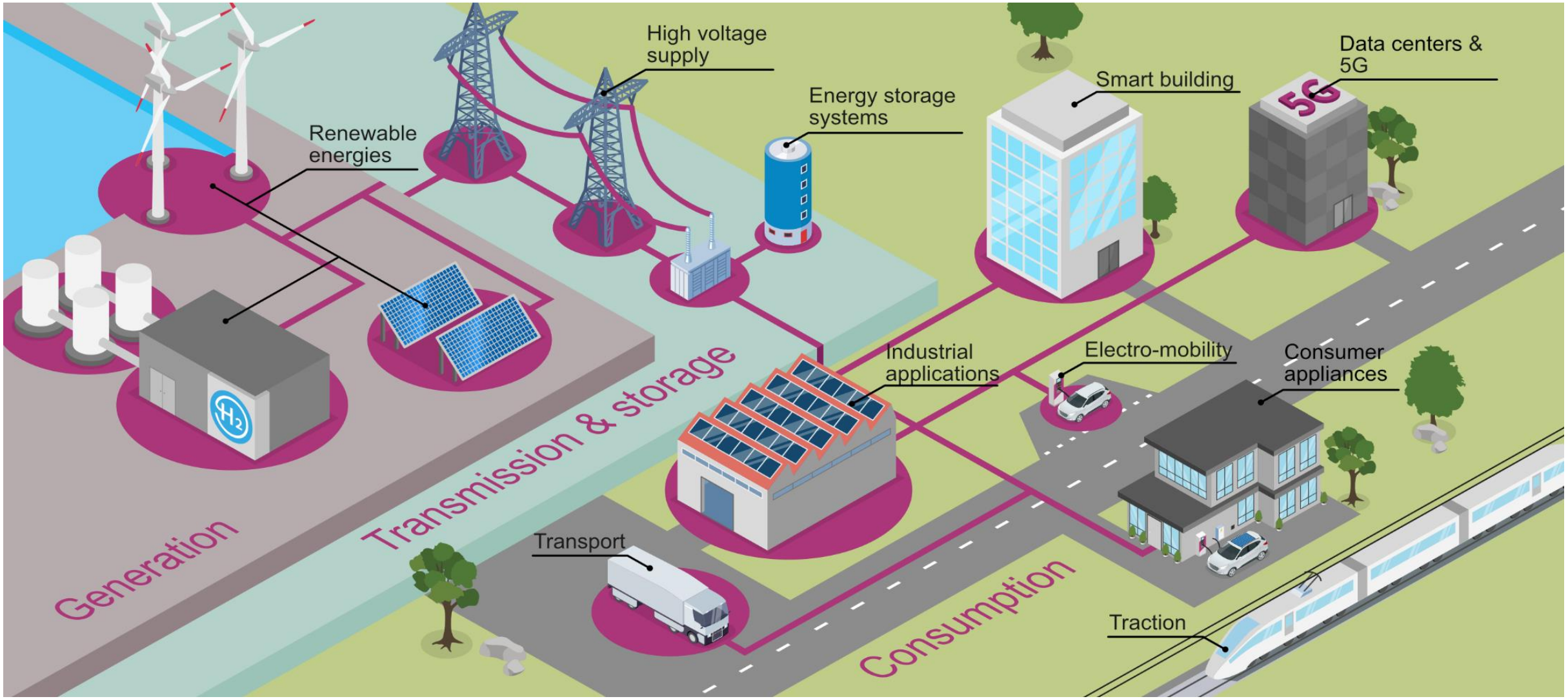
Hydrogen Production
New Markets

CoolSiC™
CoolGaN™

Wide Band Gap
Higher Value Proposition

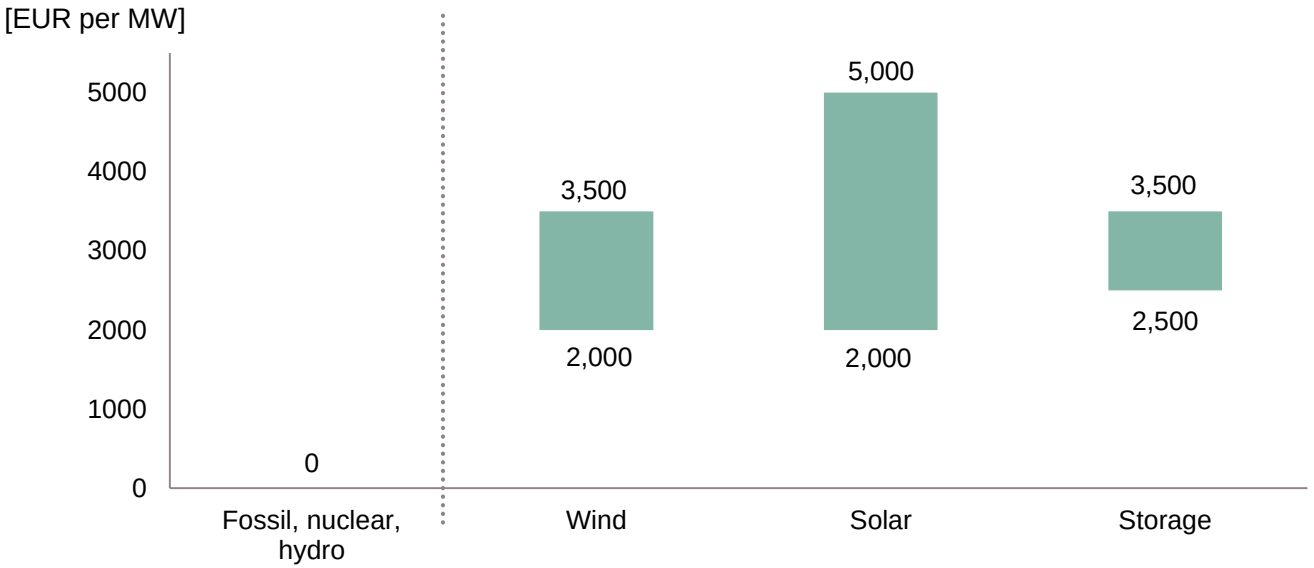
More Renewables Installations
Further Market Growth

Infineon provides solutions for all links in the energy conversion chain



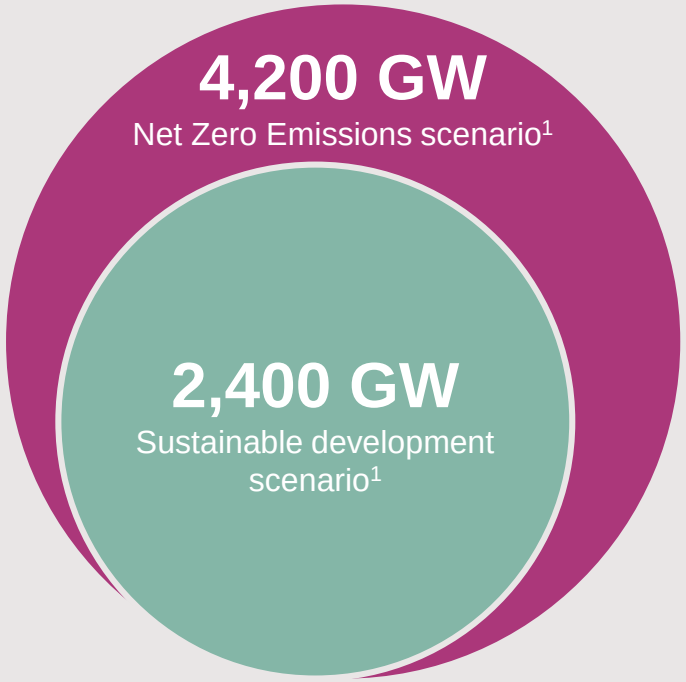
Green energy generation provides large business opportunities

Power semiconductor content by application



[GW]	Fossil, nuclear, hydro	Wind	Solar	Storage
Additions in 2020	114	134	5[2]	
Ø 2021 – 2030 annual additions Sustainable development scenario[1]	110	240	22[2]	
Ø 2021 – 2030 annual additions Net Zero Emissions (NZE) scenario[1]	240	420	33[3]	

Upside potential: example solar power



Global cumulated additions in solar power capacity until 2030.

1 IEA: *Net Zero by 2050 - A Roadmap for the Global Energy Sector*. May 2021 | **2** Based on or includes content supplied by IHS Markit Climate and Sustainability Group: *Grid Connected Energy Storage Market Tracker H1 2021*. August 2021
3 Extrapolation; conservative assumption of equal ratio renewable generation to storage capacity

What comes next?
Mid- to long-term structural growth opportunities

Core

CoolSiC™ Silicon Carbide

new material

EV charging

collaborative robots

Adjacent

solar pumps

energy storage

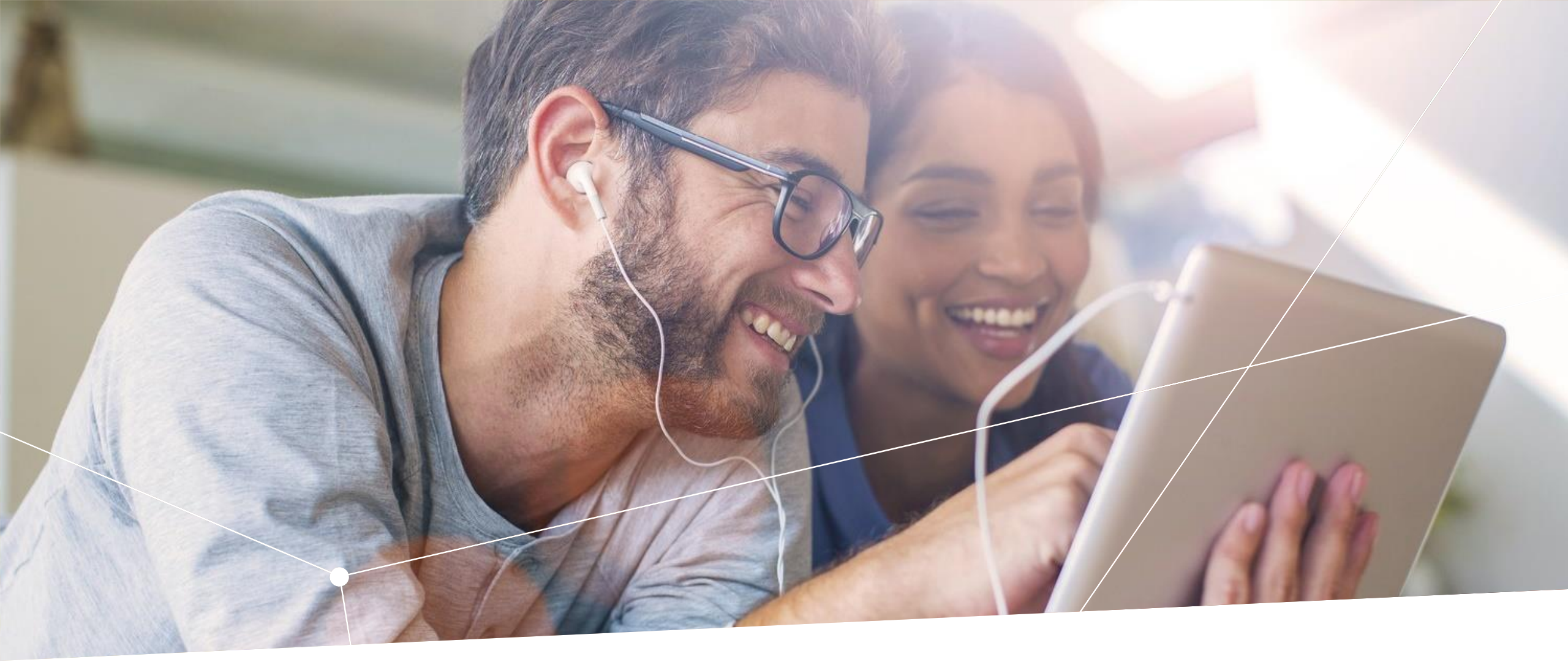
eDelivery vehicles

New area

fuel cell

eMarine

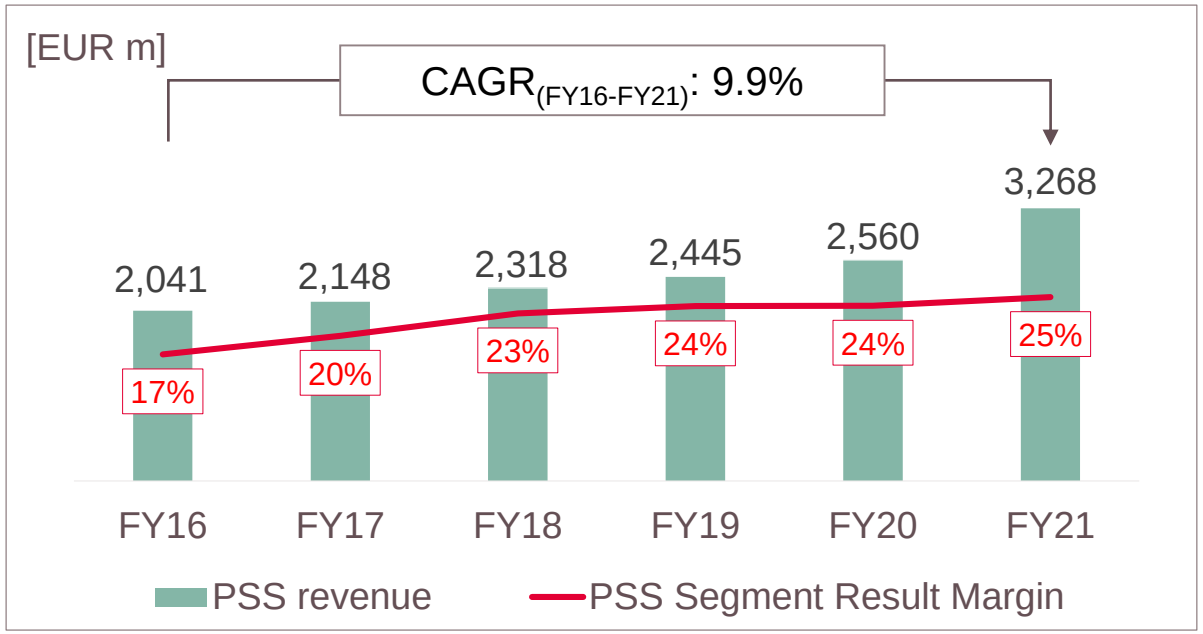
eAviation



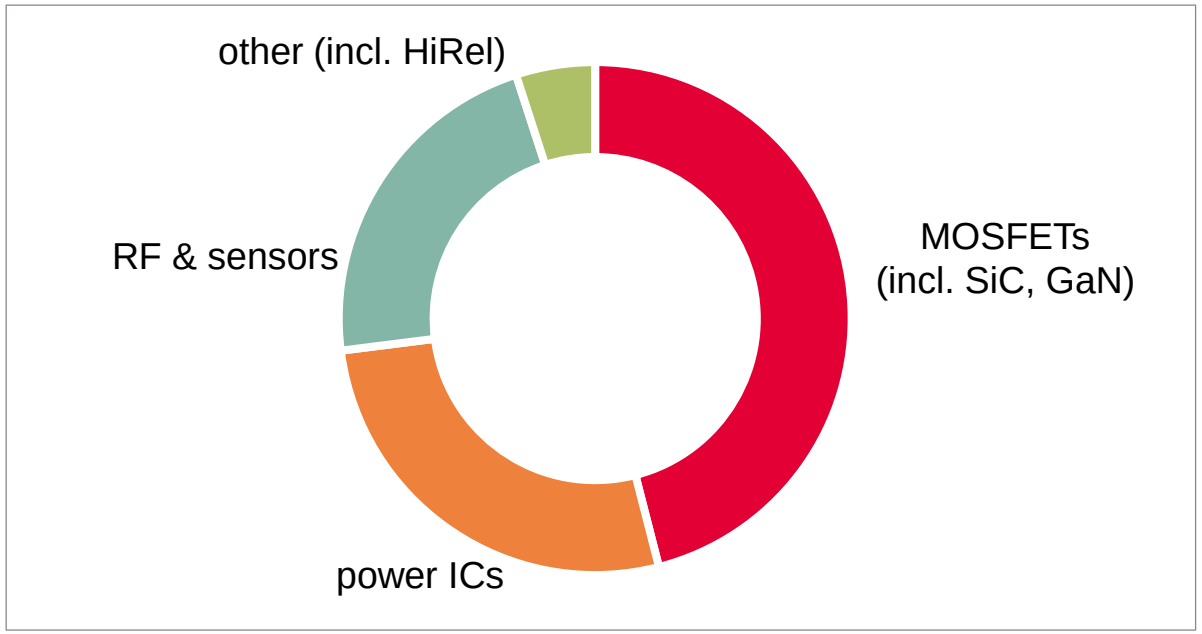
Power & Sensor Systems

PSS at a glance

PSS revenue and Segment Result Margin



FY21 revenue split by product group



Key customers

阿里巴巴 Alibaba.com, amazon, Advanced Energy, Baidu 百度, BOEING, CISCO, DELL, DELTA, ERICSSON, Google, Goertek, inspur, LITEON, makita, NOKIA, SAMSUNG, solaredge, ZTE

Market outlook for PSS division's target applications

Applications (% of FY21 segment revenue)[1]		Market Outlook for CY22
	~20%	› Structural growth driven by cloud computing and to a lesser extent by enterprise servers › PCs for education likely to experience saturation
	~5%	› 5G cycle will continue to drive telecom equipment spending in CY22 › Remaining trade tensions generate some uncertainty around speed of roll-outs
	~17%	› 5G replacement cycle expected to continue to drive demand growth
	~24%	› Demand expected to decline in some consumer areas, e.g. TVs, in light of re-allocation of consumer spending
	~25%	› Demand in renewable energy, EV charging and automotive expected to be healthy; value chain risks to be watched › Tailwinds from US and EU stimuli packages for infrastructure / green energy initiatives

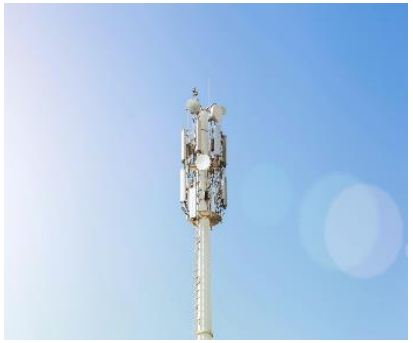
1 does not sum up to 100% due to other applications not shown here

PSS's growth is built on many applications from different sectors in power and non-power

Computing

- data center
- enterprise server
- PC, notebook
- peripherals
- chargers and adapters

Communications



- base stations
- backhaul cellular infrastructure
- 5G massive MIMO
- telecommunication servers

Smartphones

- smartphones
- mobile devices
- wearables
- USB Type-C, USB Type-C PD

Consumer

- eBikes, eScooter
- multicopter
- LSEV
- gaming
- TV sets
- smart home

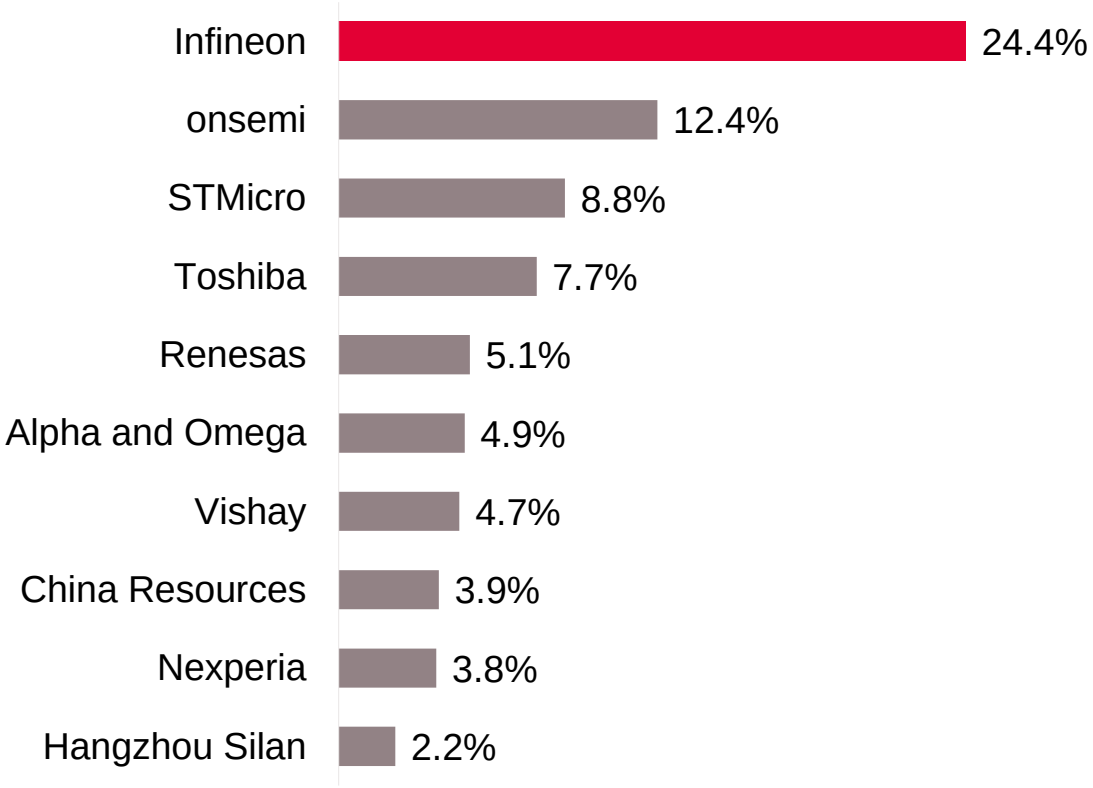
Industrial

- power supplies
- EV on-board charger
- charging infrastructure
- PV inverter
- power tools
- lighting
- Industry 4.0
- aerospace

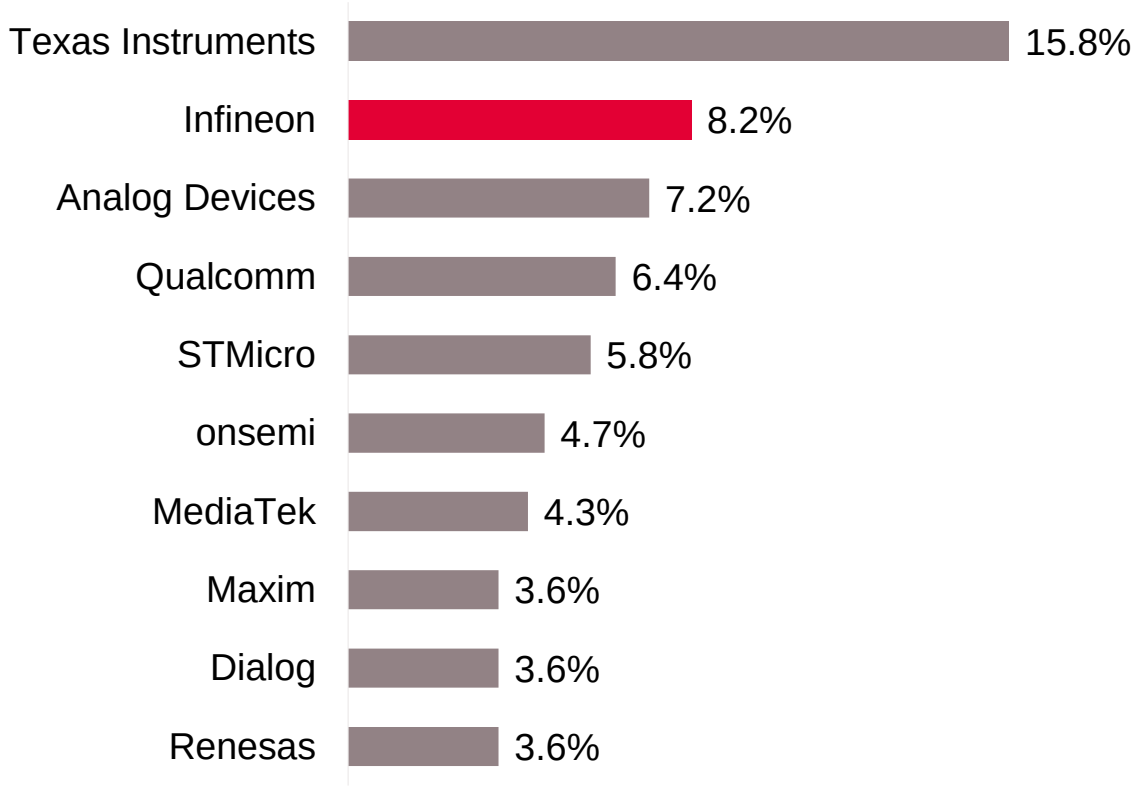
PSS – Power

Infineon is the clear leader in MOSFETs; growth potential in power ICs

Discrete Power MOSFETs[1]
2020 total market: $8.1bn



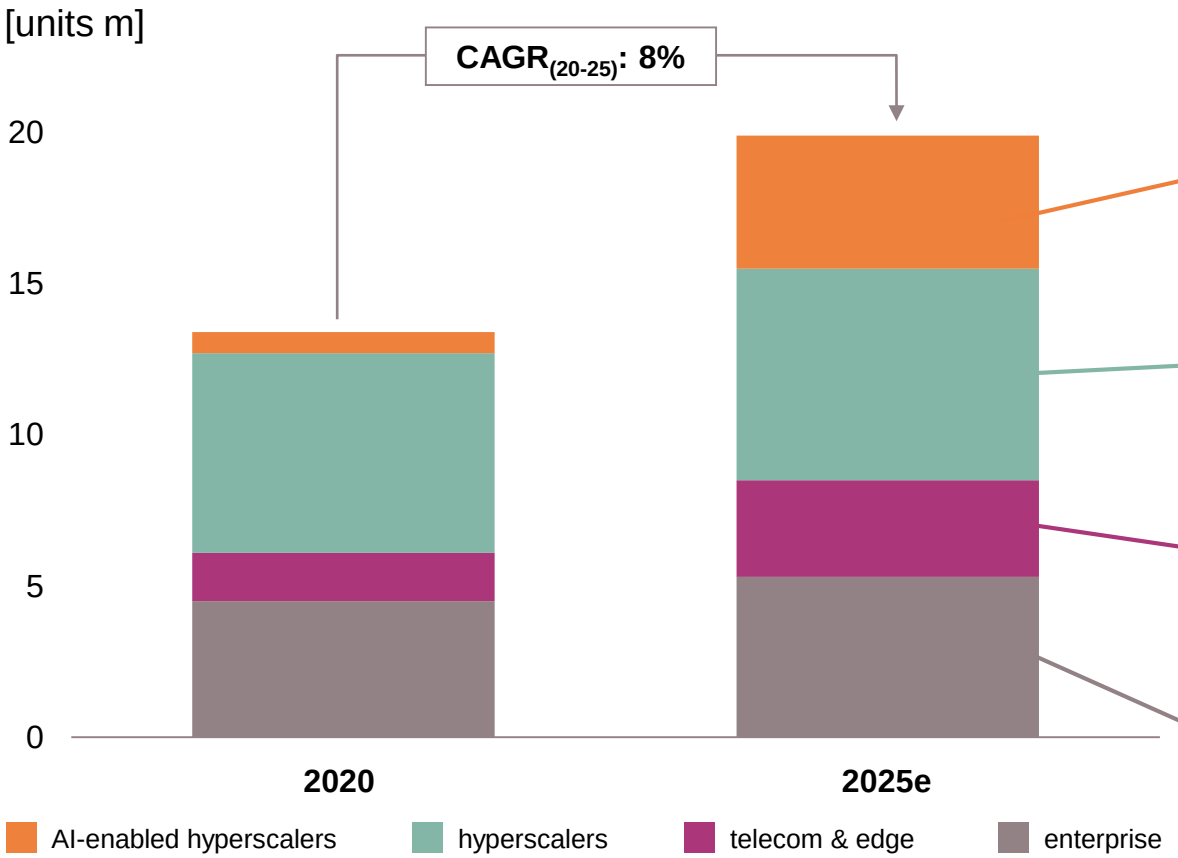
Power ICs[2]
2020 total market: $24.3bn



1 Discrete Power MOSFET market includes automotive MOSFETs, protected MOSFETs, SiC MOSFETs and GaN power transistors. | **2** Power IC market includes automotive power ICs.
Based on or includes research from Omdia: *Power Semiconductor Market Share Database 2020.* September 2021

Data center – AI hyperscaler and telecom/edge computing are driving the growth

Server growth



Power requirement per server

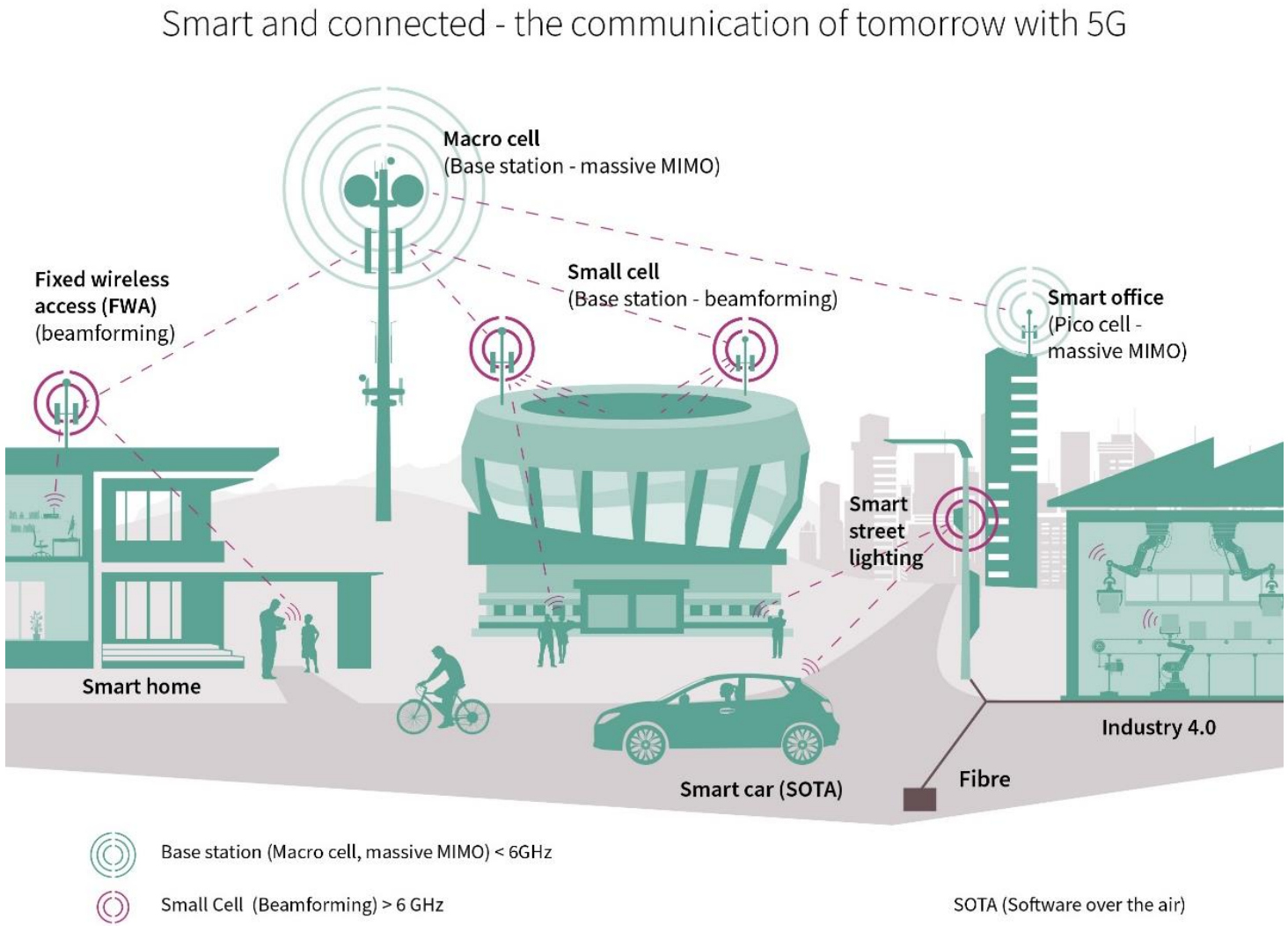
Power[1]:

Exponential increase in **AI Training & Networking** (ASIC/SoC/FPGA/CPU/GPU) power level requires cutting-edge innovation in Device & Packaging technologies to solve power efficiency and density challenges

→ The bill of material is outpacing unit growth by a factor of ~1.3x.

1 Normalized overall power requirement per server board for x-comparison
Based on or includes research from Omdia: *Data Center Server Equipment Market Tracker – 2Q21 Database. September* 2021

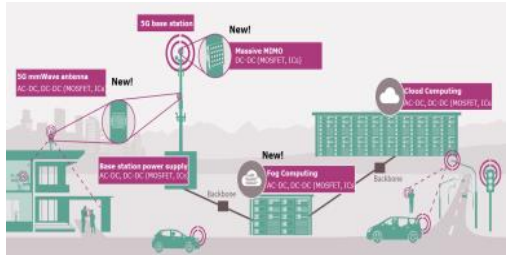
Transition from 3G/4G to 5G drives demand in power semis for antennas and power supplies



- **driver #1**: massive growth of data and computing power
- **driver #2:** higher number of base stations due to dense network
- **driver #3:** ~4x higher power semi content per radio board: from ~$25 for MIMO antenna to ~$100 for massive MIMO antenna array
- **driver #4:** fog computing data center as a completely new market

What comes next?
Mid- to long-term structural growth opportunities

Core



5G infrastructure


hyperscale AI data center

new material

Adjacent

smart building


wireless charging


on-board charger

New area

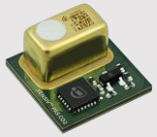
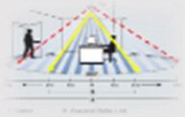

smart speaker


health & lifestyle


environmental sensor solutions

PSS – RF and Sensing

Main applications addressed by PSS sensors portfolio

MEMS microphone		3D radar (24/60 GHz)		3D ToF image sensor		Environmental	
	Best audio performance		Ultra-low power consumption		Best price / performance		High precision and Small form factor
	Low power consumption		Presence detection/ Vital Sensing		Face ID (biometrics), VR/AR		Measure CO_2

Main applications

- Smartphone
- True wireless stereo headsets
- Smart speaker
- Laptop & Tablet

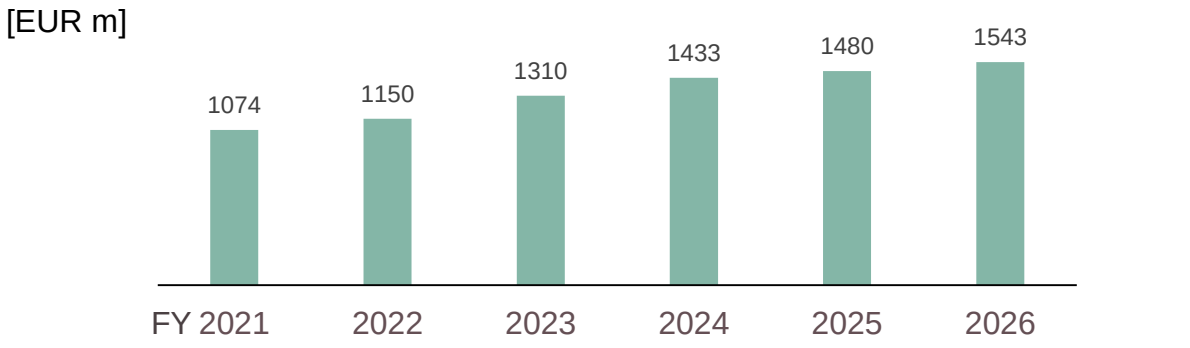
- Automotive
- Smart home
- TV
- Security camera
- Smart building

- Smartphone: world-facing and user-facing
- Robotics
- Automotive in-cabin sensing
- Payment terminals

- Heating, ventilation, air conditioning (HVAC)
- Air purifier
- Smart thermostat
- CO_2/virus risk reduction

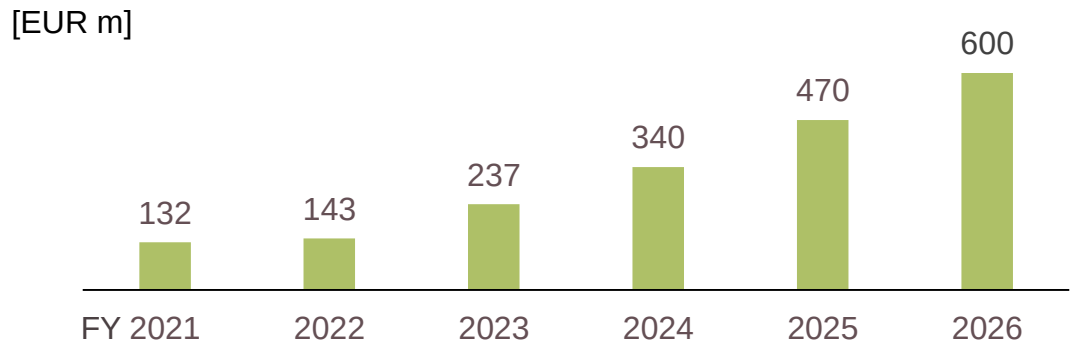
Sensor markets targeted by PSS offer attractive growth potential

MEMS microphone market



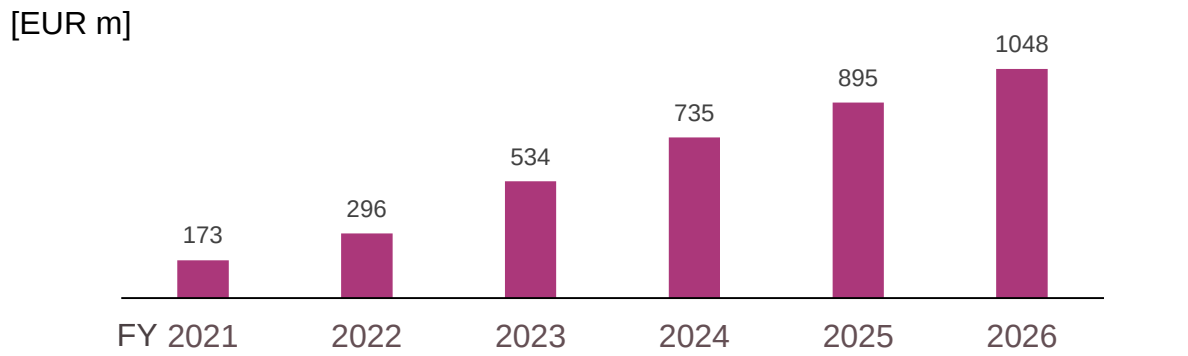
Source: Infineon estimates

Radar IC market (24 GHz and 60 GHz only)



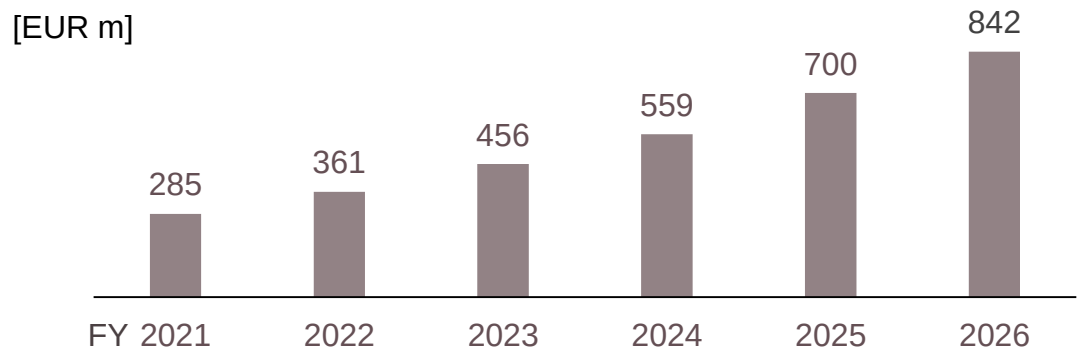
Source: Infineon estimates

3D ToF image sensor market



Source: Infineon estimates

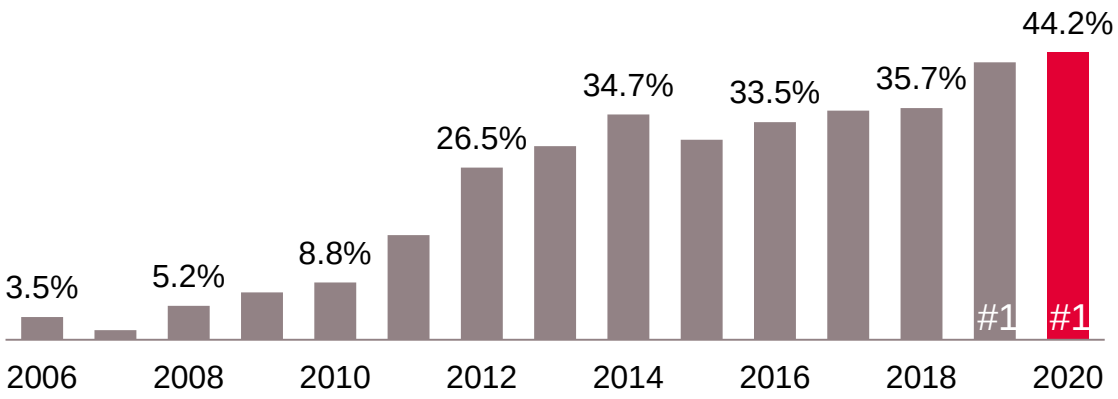
Environmental sensor market*

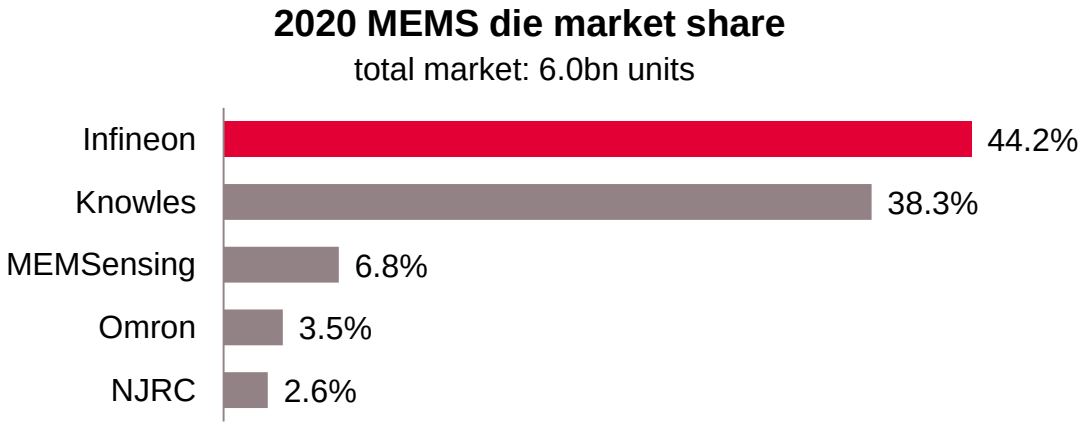


* Infineon is addressing smart building, smart home, smart appliances, consumer IoT devices and automotive
Source: Infineon estimates

Unparalleled audio characteristics of our XENSIV™ MEMS micro-phones made Infineon #1 in 2019 with further m/s gain in 2020

Infineon's market share development in MEMS microphones (by units)





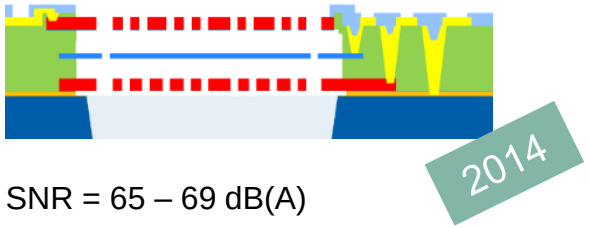
Based on or includes research from Omdia: *MEMS Microphones Dice Market Shares 2021*. July 2021

Technological progression of Infineon XENSIV™ MEMS microphones

1 Single-back plate

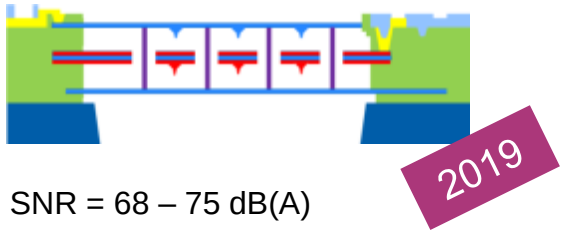
SNR = 62 – 65 dB(A)

2 Dual-back plate



SNR = 65 – 69 dB(A)

3 Sealed dual-membrane



SNR = 68 – 75 dB(A)

Radar offers several use cases for presence detection and health monitoring

Presence detection

- **Room Occupancy Devices**
  e.g. human localization and counting
- **Occupancy based heating and ventilation**
  e.g. reduction of CO_2 level to prevent spreading of diseases
- **Device switch on/off**
  e.g. reduction of energy consumption (e.g. lamp, TV, air conditioning…)
- **Directional audio effects on individuum**
  e.g. to improve audio quality (e.g. smart speaker, TV)
- **Home surveillance**
  e.g. detection of intruders

Health monitoring

- **Sleep monitoring**
  Sleep detection, sleep quality, apnea & snoring detection (radar combined with MEMS microphone)
- **Vital sensing for home Fitness**
  Heart rate and breathing rate measurement (person standing still after exercise)

Segmentation with radar enables smart devices to recognize each person in the room

Infineon 3D ToF is a versatile technology for many consumer applications

Mobile Phones – User Facing

Face ID

Hand ID

Payment

3D Gestures

Mobile Phones – World Facing

Bokeh

Virtual Retail

AR Gaming

3D Scanning

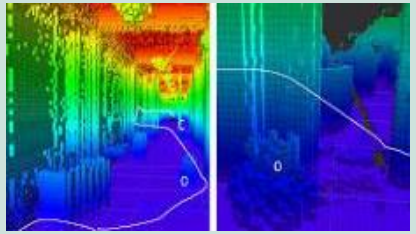
Consumer Robotics

Robot

Last Mile

Collision avoidance

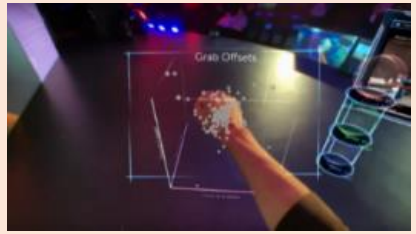
Navigation



Augmented- & Virtual Reality

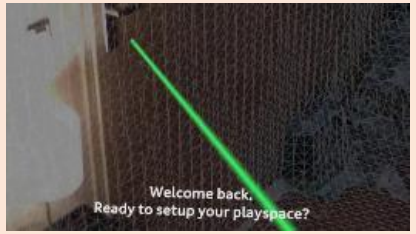
AR

Control



AR Gaming

Mapping



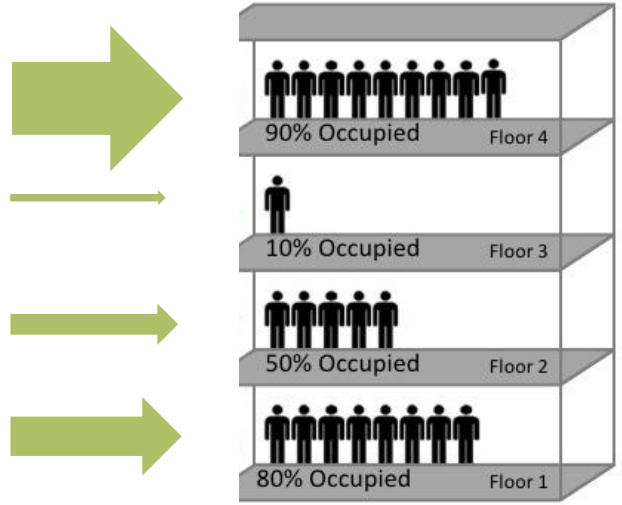
Infineon XENSIV™ PAS CO2 sensor enables highly-precise CO_2 measuring in an extremely small size

Photoacoustic spectroscopy (PAS) technology based on Infineon‘s high (SNR) signal-to-noise ratio MEMS microphone

- Infineon XENSIV™ PAS CO2 sensor enables highly-precise, cost-effective and space saving CO_2 measuring
- The technology offers an exceptionally small form factor (14 mm x 13.8 mm x 7.5 mm) that is 4x smaller and 3x lighter (2 grams) than the typical NDIR (non-dispersive infrared) sensor, allowing for more than 75% space savings in customer systems
- The SMD package ensures compatibility with high-volume manufacturing standards, enabling cost-effective, fast assembly and system integration
- Advanced compensation and configuration algorithms enable a plug-&-play sensor performance and fast design-to-market

XENSIV™ PAS CO2 leads to demand-oriented and energy efficient control of air conditioning systems

XENSIV™ PAS CO2 sensor measures the CO_2 level

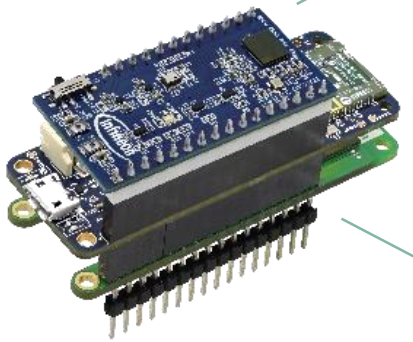


Infineon system solution addresses IoT market via combining XENSIV™ sensors, PSoC™ 6 MCU and connectivity

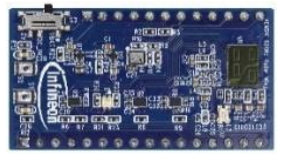
Key facts

- Infineon offers system solutions comprising of sensor, MCU, connectivity and software libraries (apps, SDKs)
- BLE functionality monolithically integrated on MCU
- IoT target applications for radar: entrance control or presence detection for smart home and smart building
- Radar solutions are anonymous and therefore respecting privacy
- First orders for presence detection received from several Asian customers
- Radar solution can perfectly be combined with Infineon's XENSIV™ PAS CO2 sensor for air quality monitoring

Example offering: Combination of sensors, microcontrollers and connectivity in development kit



XENSIV™ Radar + Pressure Wing Board



XENSIV™ PAS CO_2 Wing Board

Main board with MCU + Wi-Fi + Bluetooth combo

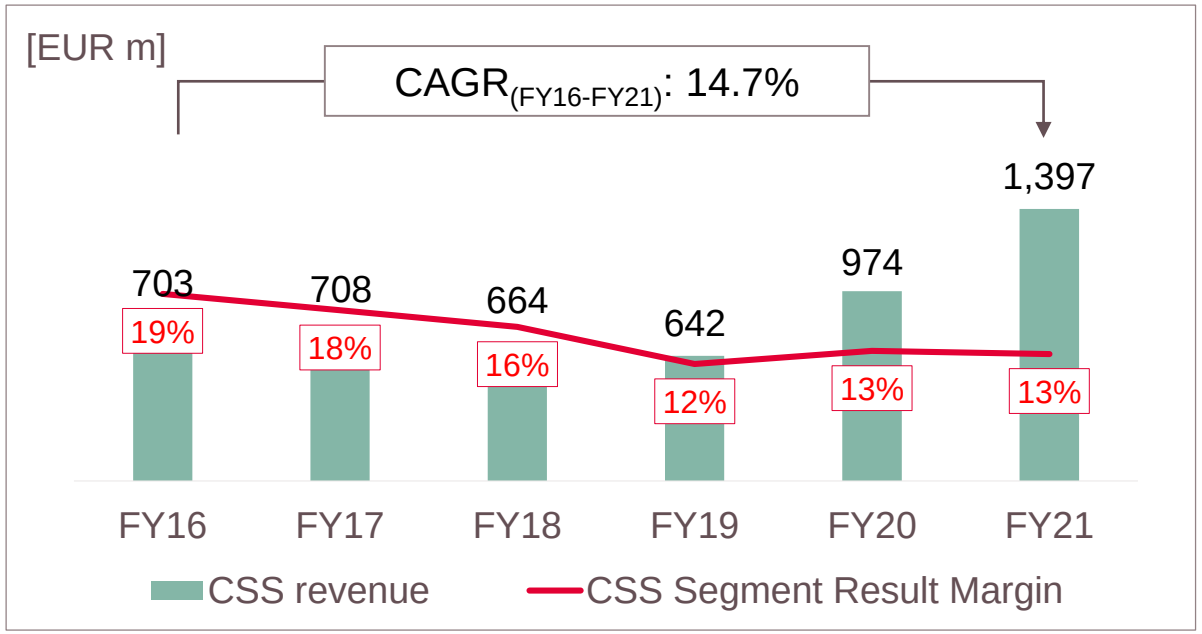
Advantages of radar over passive infrared

- super compact design; smaller system sizes
- determination of person's direction, speed, distance
- programmable; can flexibly be adapted to the target application
- higher accuracy; more precise measurements of detected objects

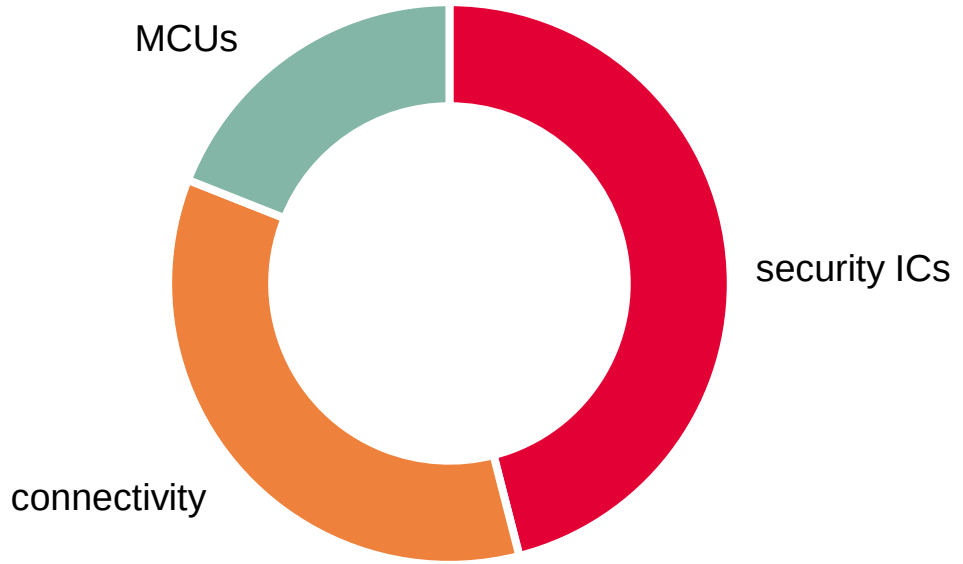
Connected Secure Systems

CSS at a glance

CSS revenue and Segment Result Margin



FY21 revenue split by product group



Key customers

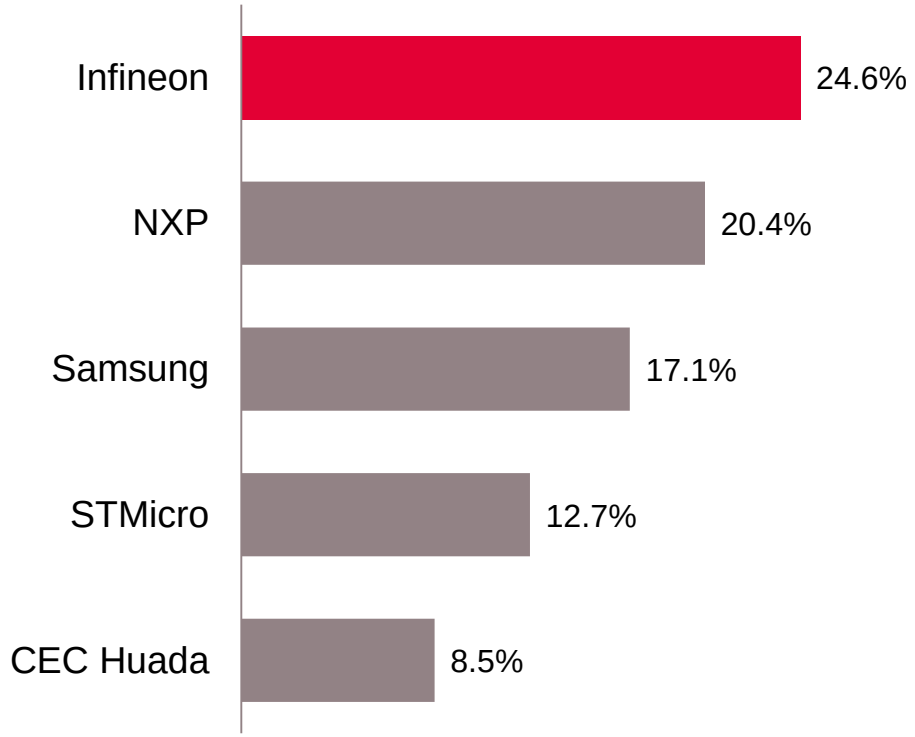
AdvanIDe
cpi card group
EPSON
fitbit
GPO
HARMAN
hp
IDEMIA
augmented identity
Lenovo
Microsoft
Nintendo
PERFECT Plastic
Raspberry Pi
SONY
THALES

Market outlook for CSS division's target applications

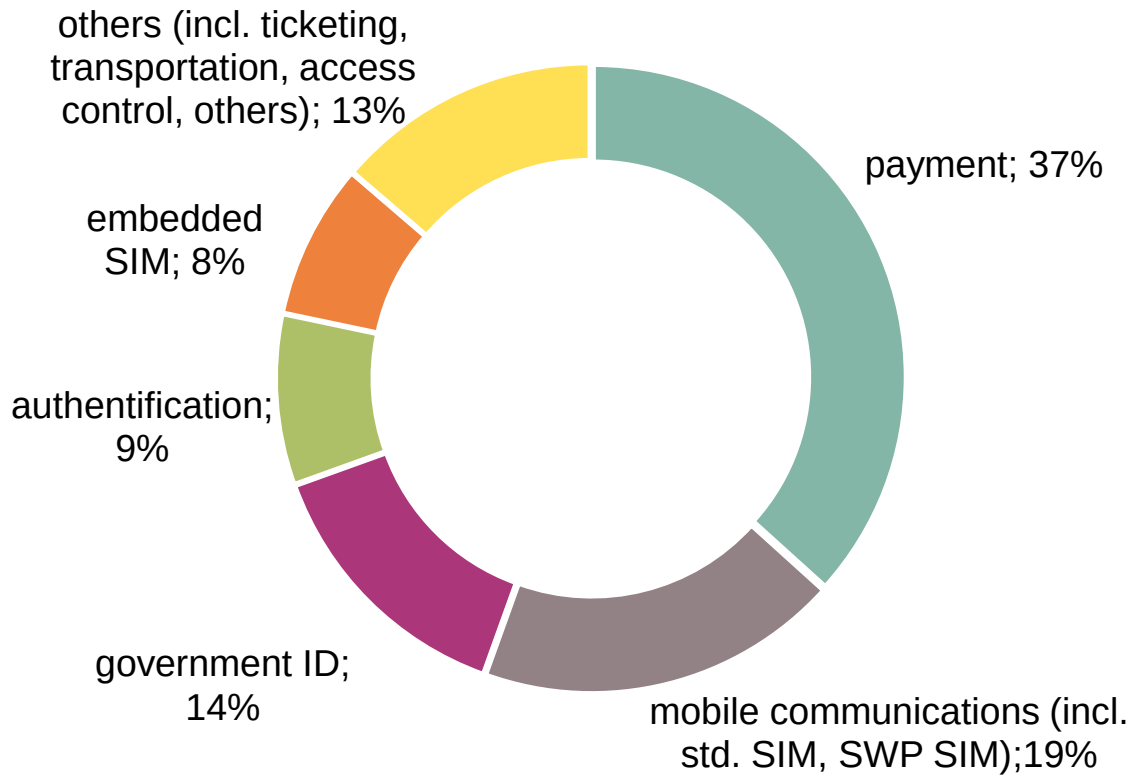
Applications (% of FY21 segment revenue)		Market Outlook for CY22
Industrial and Consumer IoT ~55%		Growth momentum in industrial segments to continue into CY22
		Further growth momentum across smart home devices expected
		Increasing penetration rate of eSIM Automotive and in-car connectivity to continue along with further recovery of overall vehicle sales
		The market is assumed to decline slightly from a high level after CY21 as demand stabilizes
		Growth in wearables market is assumed to stretch in CY22 driven mainly by smart watches
Payment, ID, Ticketing ~45%		Further migration and high demand for contactless payment solutions expected to continue, however under risk of foundry supply constraints
		Positive trend expected driven by recovery in passports issuance as well as project roll-out for other eDocuments

Infineon remains top player in security ICs

Security ICs (excl. NFC controllers; excl. NFC eSE)
2020 total market: $2.8bn

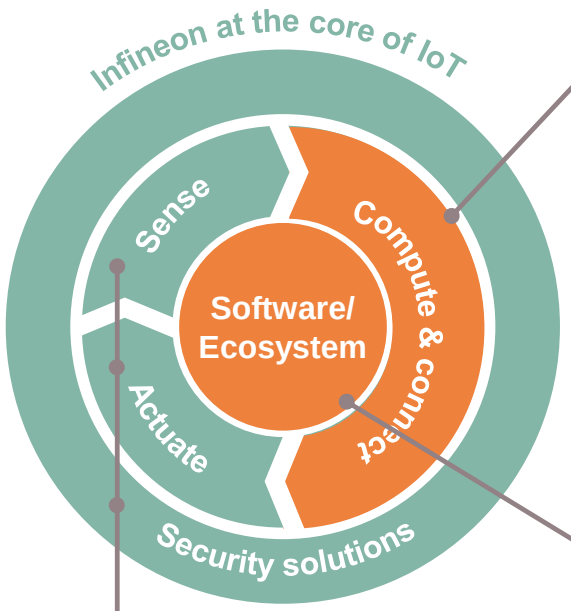


Security ICs (excl. NFC controllers; excl. NFC eSE)
2020 by application



ABI Research: *Smart Card and Embedded Security IC Technologies*. October 2021

MCU and software are key for the success in IoT as they define the functionality and time-to-market of the device



Numerous P2S opportunities with other system components

Hardware

Customer expectations

Broad portfolio

Application fit

Solution offering

Infineon's MCU offering

- Broad solution-oriented MCU family offering
- Platform strategy for MCU development:
  - shared core IP
  - use-case-specific components

Software

Customer expectations

Seamless experience

Ease of use

Rich ecosystem

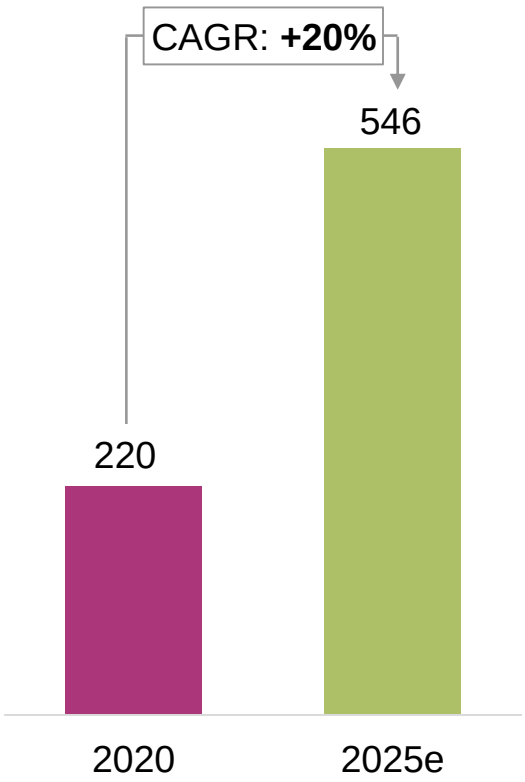
Infineon's software and services offering

- Software development environment and ecosystem with ModusToolbox™
- Cloud-connected software for IoT devices using Wi-Fi, PSoC™, OPTIGA™
- Motor drive software stack for iMOTION™ controller
- Driver software, firmware and complete functional products for easy hardware integration (e.g. OPTIGA™ family)
- Fast innovation: AI/ML enablement
- Software-as-a-service (SAAS) for IGBT module lifetime simulation

With a broad set of key enabling technologies, Infineon is well positioned to capture growth opportunities

Market: Home Automation Devices[1]

[units m]



Leading competencies to provide full system solutions

- **Application understanding**
- **Ease-of-use**
- **Software**
- **Sense**
- **Compute**
- **Actuate**
- **Security**
- **Connectivity**

smart door lock

wireless smart camera

Customer ex. for wireless smart cameras and smart door locks

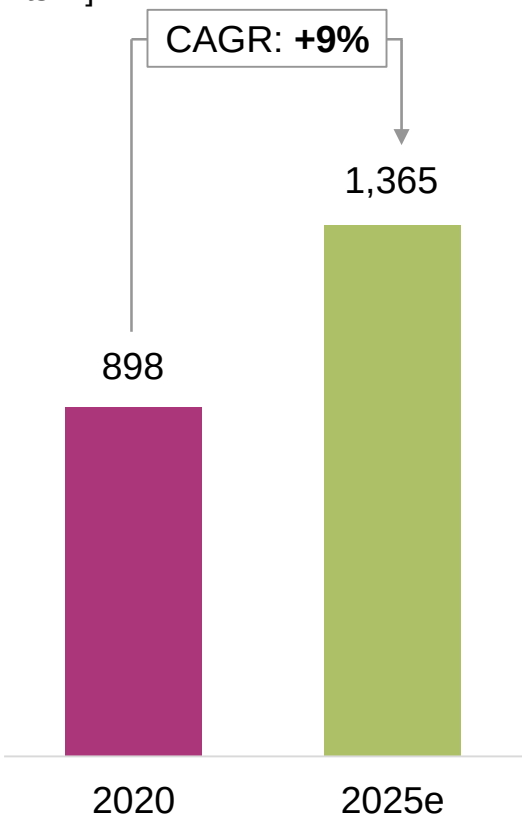
arlo
ASSA ABLOY
blink an amazon company
Google
LUMI
Kaadas
WYZE

1 ABI Research: *Wireless Connectivity Technology Segmentation and Addressable Markets*. July 2021; excluding Chromebooks, desktop PCs, feature phones, media tablets, netbooks, smartphones, white box tablets.

Infineon acts as one-stop-shop with excellent RF, sensor, connectivity, power, memory and security solutions

Market: Smartwatches, Trackers & Hearables[1]

[units m]



Acting as one-stop-shop with comprehensive solutions

- **Application understanding**
- **Ease-of-use**
- **Software**
- **Sense**
- **Compute**
- **Actuate**
- **Security**
- **Connectivity**

smartwatch

fitness tracker

Customer examples for smart watches and fitness trackers

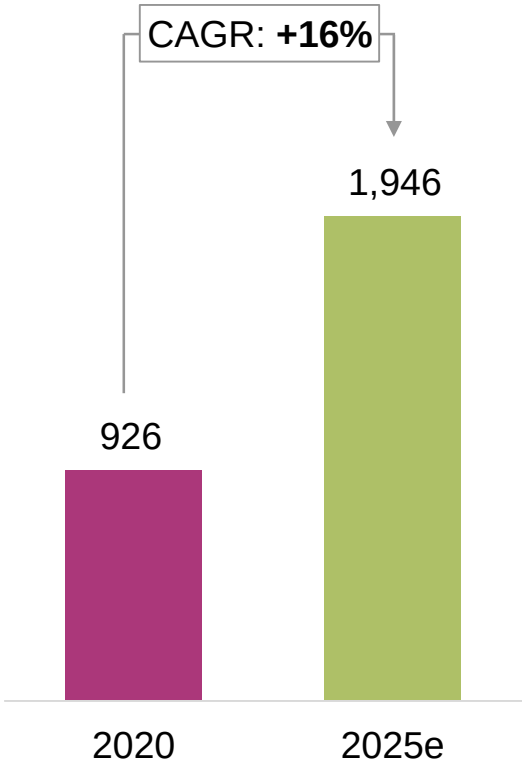
GARMIN, get, huami, POLAR, SAMSUNG, SUUNTO, vivo, WYZE

1 ABI Research: *Wireless Connectivity Technology Segmentation and Addressable Markets.* July 2021; excluding Chromebooks, desktop PCs, feature phones, media tablets, netbooks, smartphones, white box tablets.

We are driving the smart home opportunity together with market-shaping customers

Market: Smart home[1,2,3]

[units m]



Combining our portfolio to create new use cases with our customers

- **Application understanding**
- **Ease-of-use**
- **Software**
- **Sense**
- **Compute**
- **Actuate**
- **Security**
- **Connectivity**

Frame TV

smart vacuum cleaner

Customer examples for smart home

amazon

eesy INNOVATION

Microsoft

SAMSUNG

SONY

1 ABI Research: *Wireless Connectivity Technology Segmentation and Addressable Markets*. July 2021; excluding Chromebooks, desktop PCs, feature phones, media tablets, netbooks, smartphones, white box tablets.
2 ABI Research: *Smart Home Hardware Market.* June 2021. | **3** Incl. Smart Appliances, Smart Lighting, Flat Panel TVs, Smart Speakers & Displays, Smoke & Air Quality Sensors, Consumer Robotics, Thermostats and others.

Significant synergy potential of a combined company product portfolio

Synergies application examples

CSS offering | Other Infineon Divisions offering

Smart speaker

Connectivity
Wi-Fi / Bluetooth Combo

Sensing
MEMS microphone, radar IC

Security
OPTIGA™

HMI
Capacitive touch controller

Audio
Class D Audio IC

Smart lighting

Connectivity
Wi-Fi / Bluetooth Combo

Sensing
XENSIV™ Sensor

Security
OPTIGA™

MCU
XMC

Service robots

Connectivity
Wi-Fi / Bluetooth Combo

Sensing
XENSIV™ Sensor
LED Drivers

Security
OPTIGA™

HMI
Capacitive touch controller

Audio
Class D Audio IC

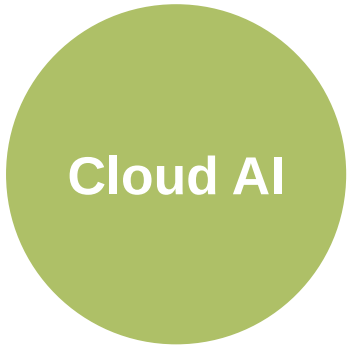
MCU
PSoC™ 6

Edge AI is a fast developing market enabled by and calling for many of our core competencies

Edge AI to offer additional growth opportunities as inference workloads move to device level

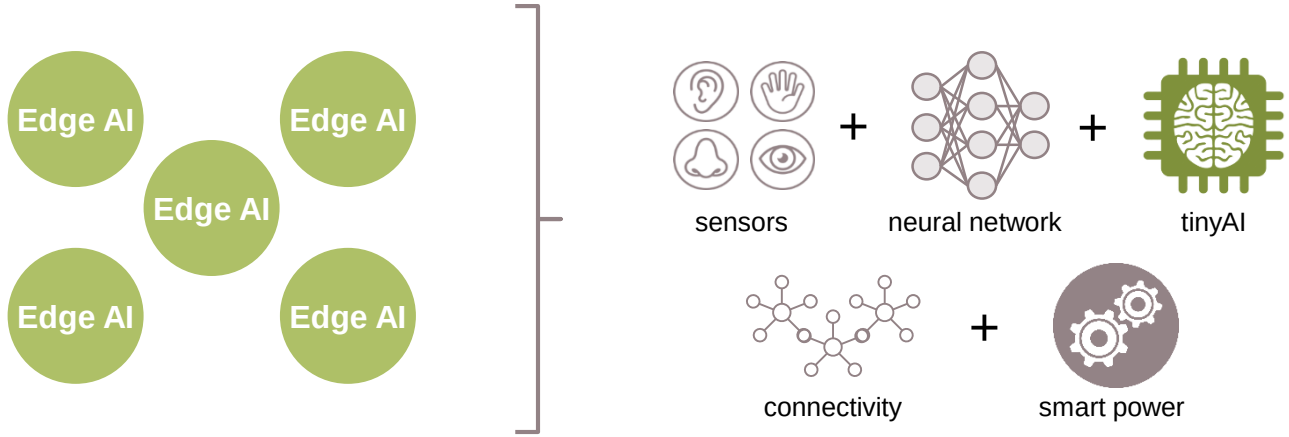
Cloud AI

- Public and private clouds offer scalability and flexibility
- Growing performance demand with higher power consumption (ASIC/SoC/FPGA/CPU/GPU)



Edge AI

- Smart subsystems offer low latency, improved privacy, higher power efficiency
- Growing solution demand for e.g. image and object recognition, autonomous material handling, predictive maintenance, and human-machine interface



Infineon:	**Power supply (AC-DC)** **Power conversion (DC-DC)**
Infineon:	**Smart sensors with AI capabilities** **Embedded control including connectivity and edge AI accelerators** **Smart power, toolchain/ecosystem, deployment services**

For the Industrial IoT, Edge AI enables predictive maintenance and other use cases – playing right into our core competences

Predictive maintenance is a significant lever for productivity

Maintenance prediction for key assets
(avoidance of fixed preventive maintenance cycles)

Advantages

- Reduced downtime through optimized maintenance
- Lower maintenance costs
- Increase transparency on device usage

Edge AI enhances Industrial IoT to enable predictive maintenance, increasing production efficiency and robustness

Edge AI-enabled
control and field-level devices

Products and services from Infineon enable safe, secure, power-efficient, dependable implementation

Smart sensors
Detect and pre-process signals through AI capabilities to recognize potential abnormal operation of equipment

Edge AI processing and control
Edge AI enabled MCUs to identify at-risk equipment, repair urgency and control adaptation

Smart Actuators
Receive and implement instructions to reduce potential impacts in production

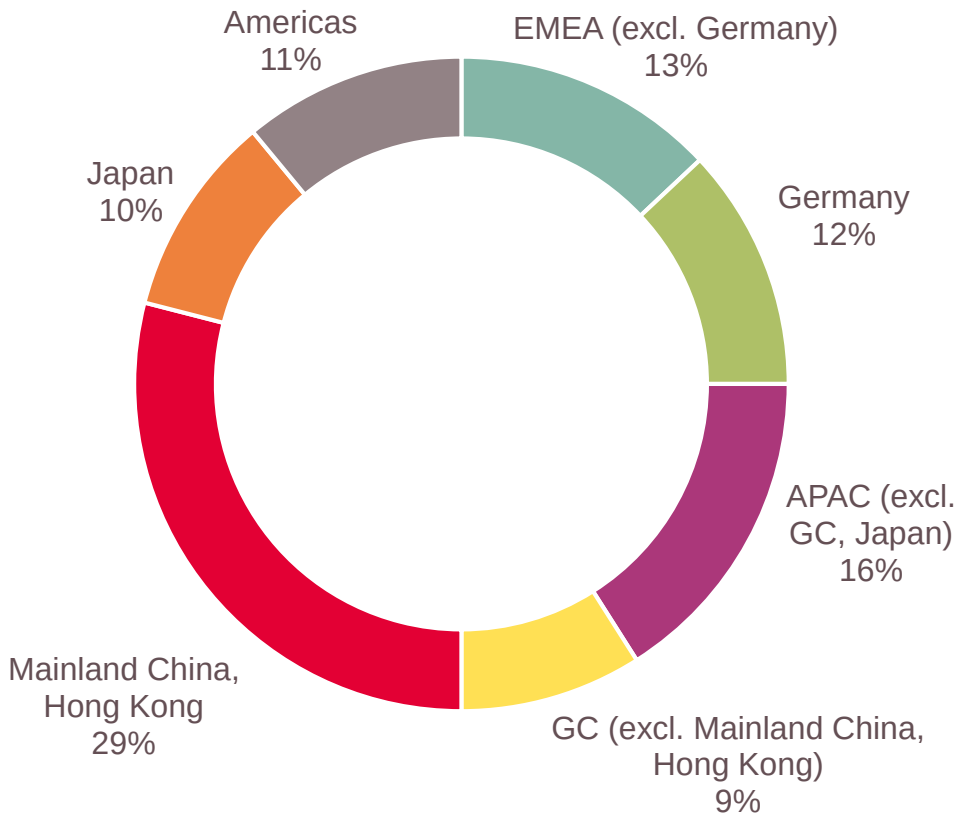
Security
Ensure secure communication and protection of critical information

Connectivity
Enable dependable communication across devices, factory levels, cloud and secure device management

Selected financial figures

Strong presence in all regions; well-balanced customer portfolio; no customer represents more than 10% of total sales

FY21 revenue by region

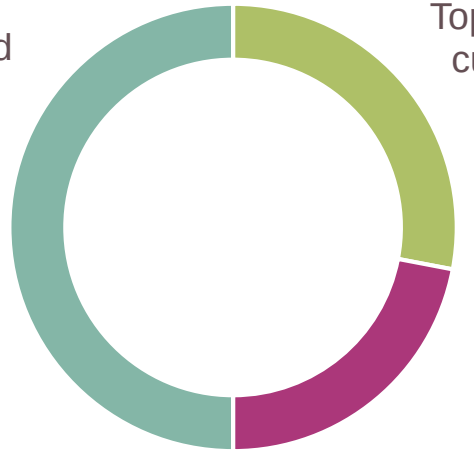


Revenue by sales channel

Distribution partners*

Top-10 direct customers*

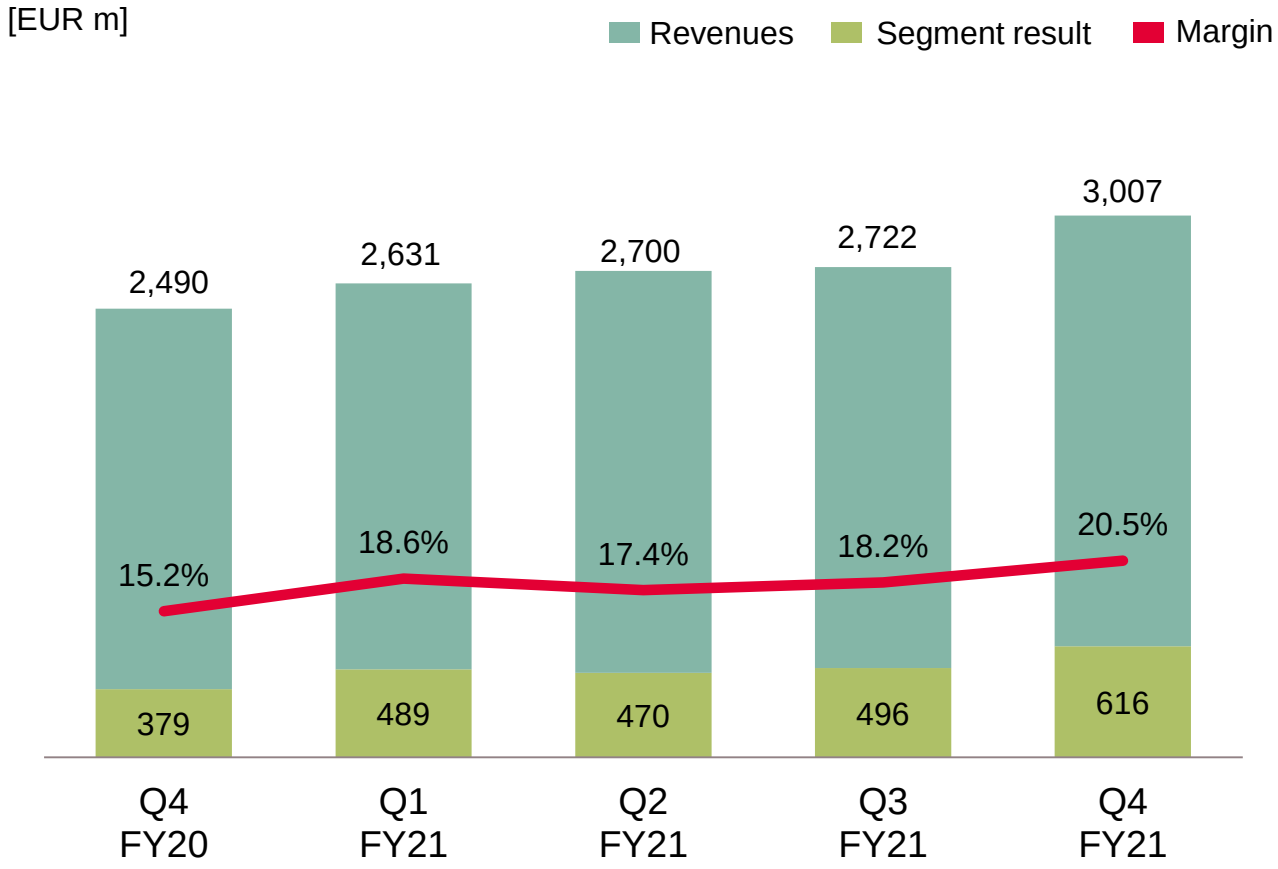
EMS partners*



* in alphabetical order

Group financial performance

Revenues and segment result

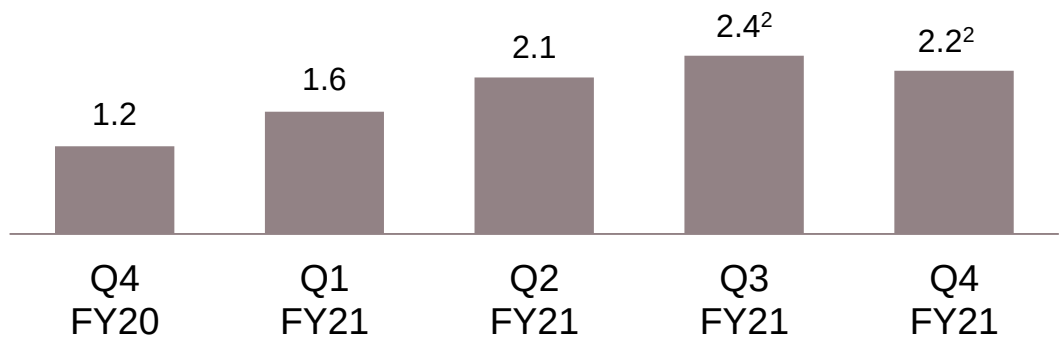


USD exchange rate

Average exchange rate

	Q4 FY20	Q3 FY21	Q4 FY21
ø USD/EUR	1.17	1.20	1.18

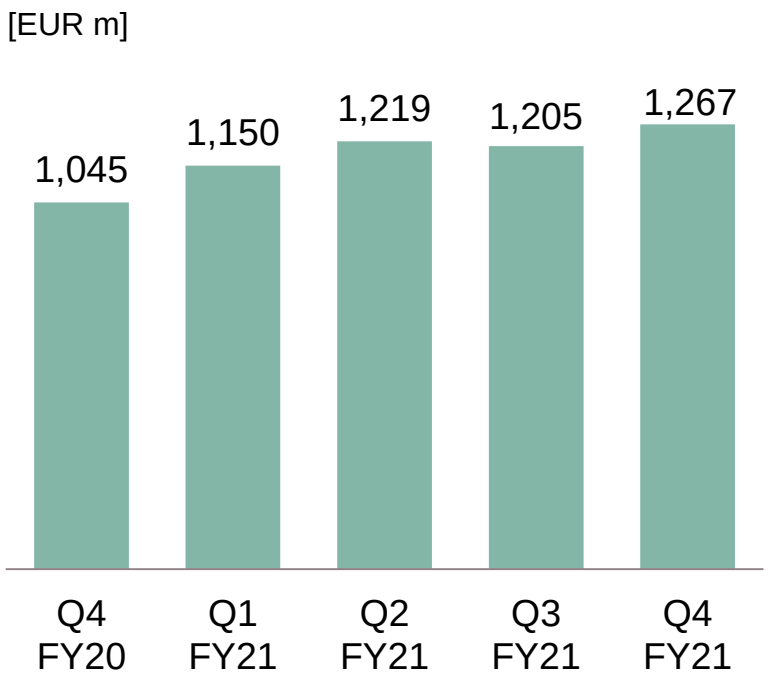
Book-to-bill[1]



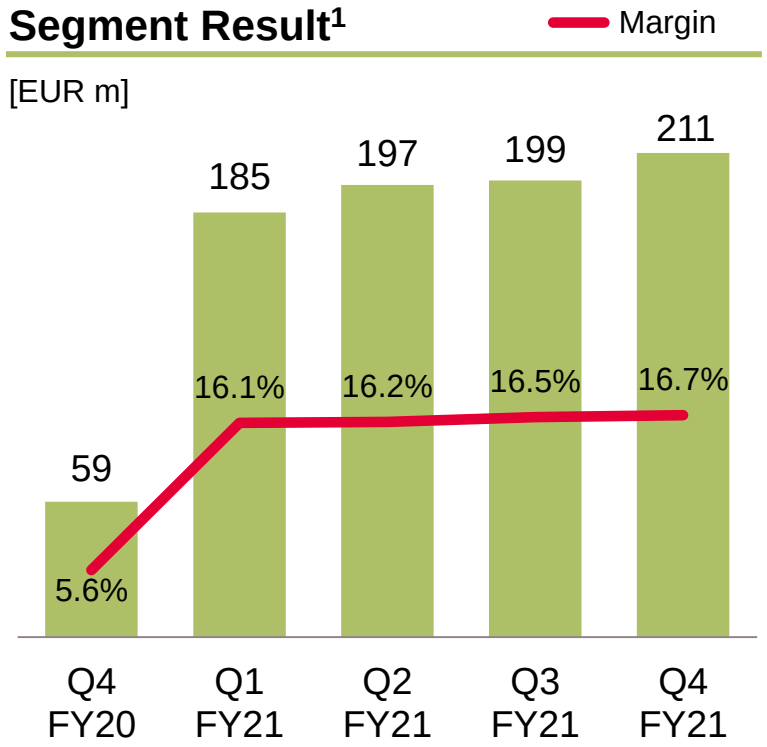
1 See notes for definition | **2** Calculated on a like-for-like basis

Automotive (ATV)

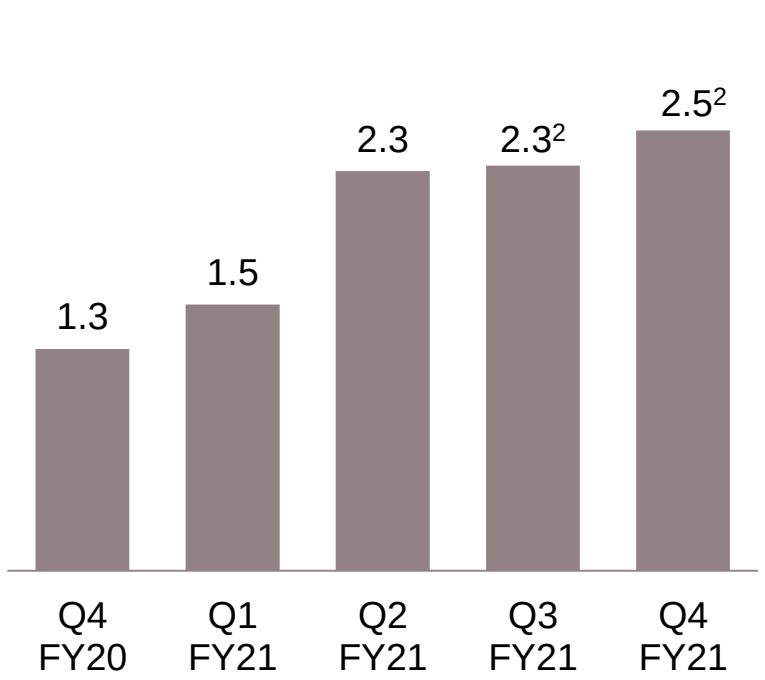
Revenues[1]



Segment Result[1]



Book-to-bill



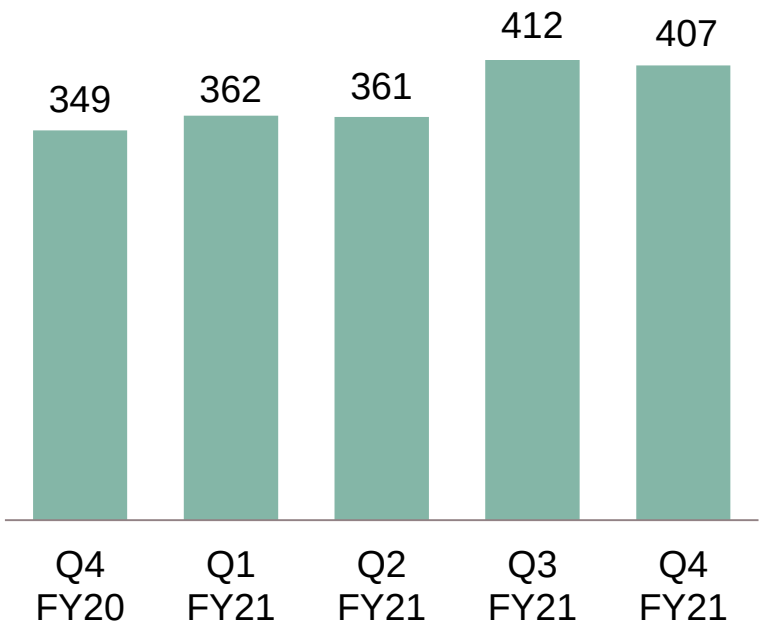
- Recovery of global car production continues to be hindered by supply limitations
- Strong growth of electric vehicles – penetration rates of battery electric and plug-in hybrid vehicles reached new highs
- Supply constraints expected to persist well into CY22; shortages will ease only gradually

1 With effect from 1 Oct 2020, we transitioned a group of industrial microcontrollers with an annual sales volume of a low-double digit million Euros from ATV to CSS. Historical figures have been retroactively adjusted.
2 Calculated on a like-for-like basis, see notes

Industrial Power Control (IPC)

Revenues

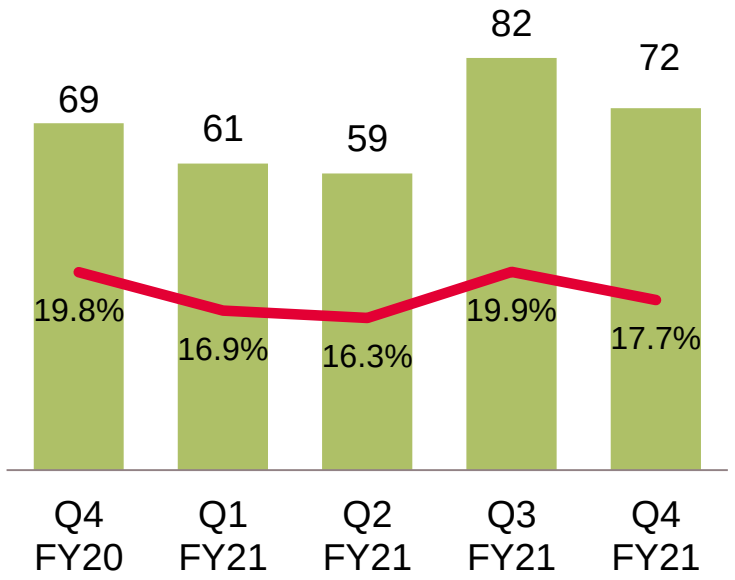
[EUR m]



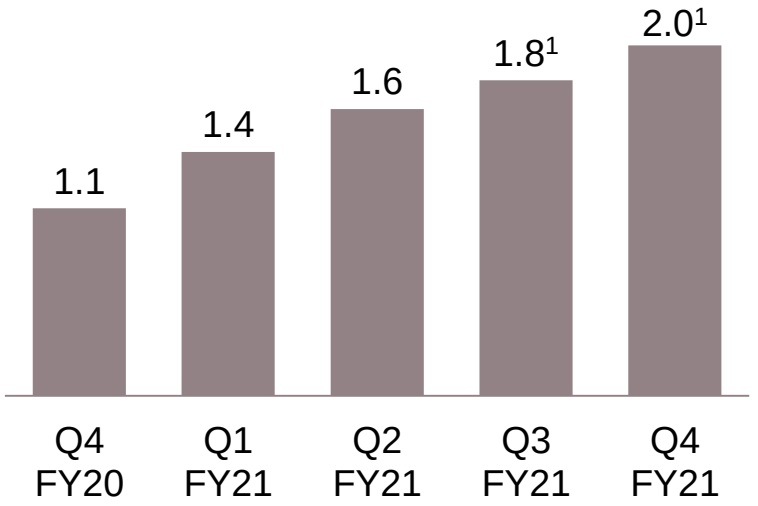
Segment Result

Margin

[EUR m]



Book-to-bill



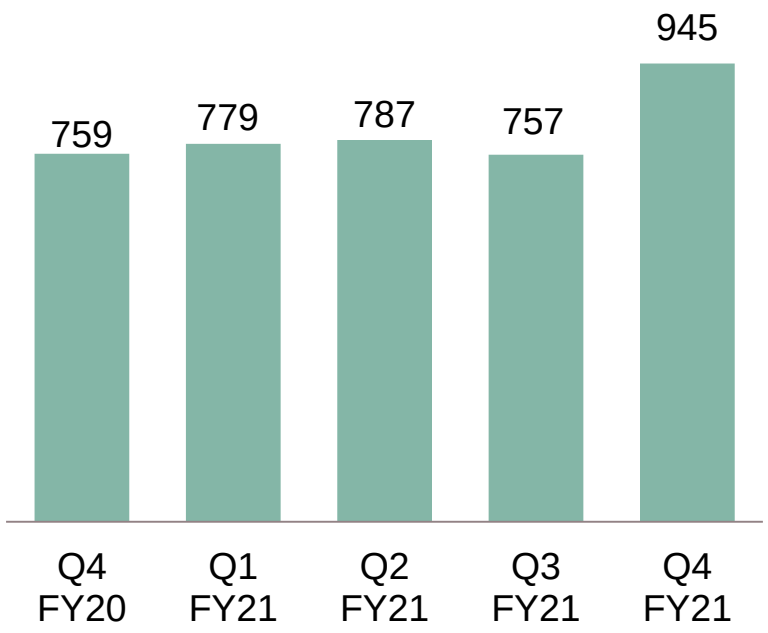
- Renewable energy and power infrastructure nearly matched previous quarter's record levels
- Automation and drives as well as major home appliances saw sequential increases – transportation revenues declined
- Going forward, gradual reversion to long-term average growth rates for key industrial applications expected

1 Calculated on a like-for-like basis, see notes

Power & Sensor Systems (PSS)

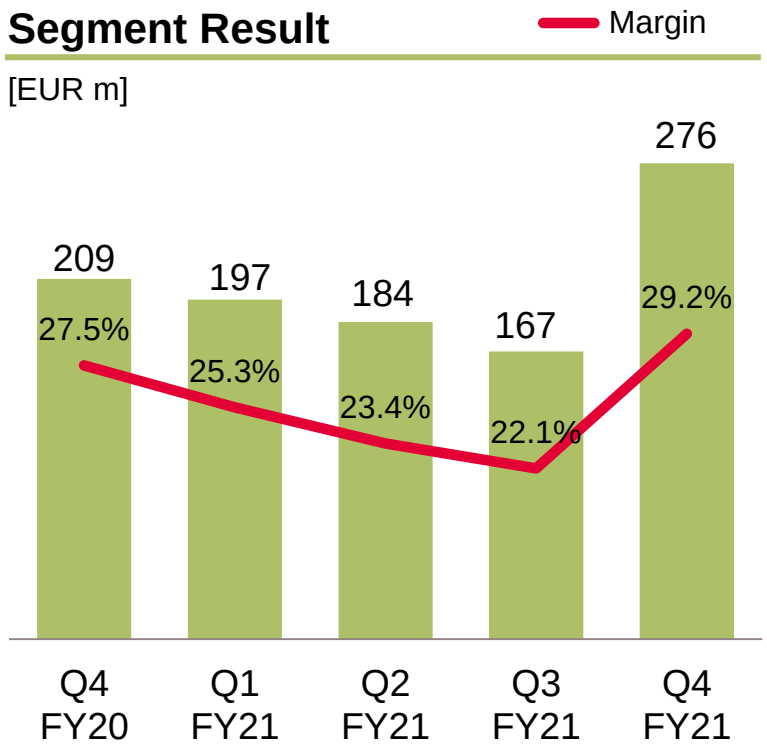
Revenues

[EUR m]

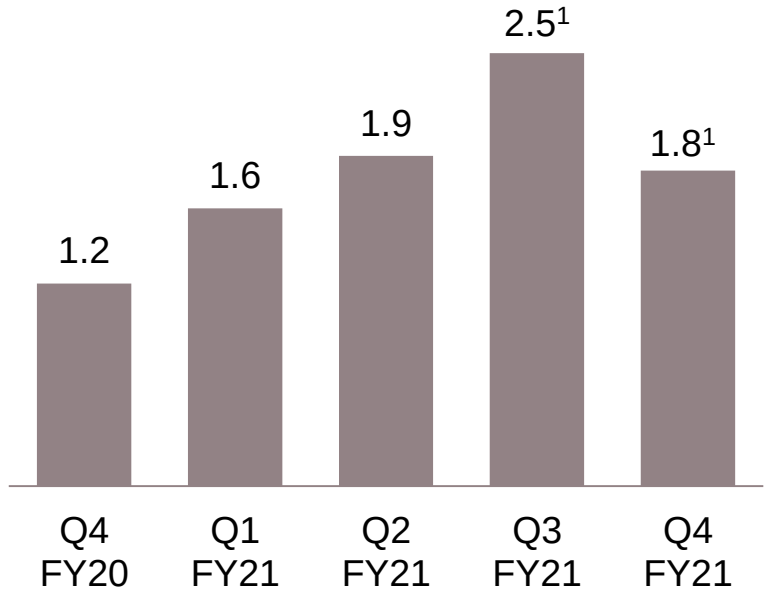


Segment Result

[EUR m]



Book-to-bill



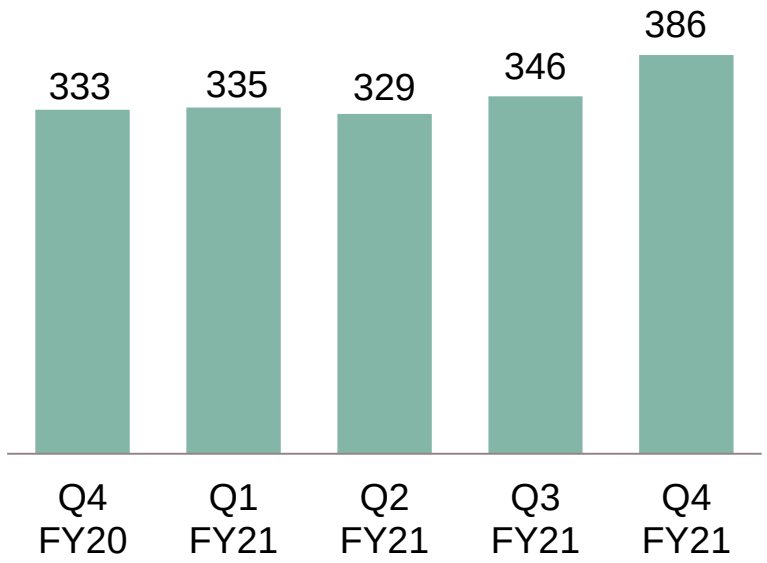
- Significant revenue increase driven by on-going strong demand, positive seasonality and an incrementally better supply situation
- Particular strength in power stages for servers and expected seasonal snapback in smartphone components
- Robust demand for majority of applications – transitioning from a boom phase into a phase of very strong market demand

1 Calculated on a like-for-like basis, see notes

Connected Secure Systems (CSS)

Revenues[1]

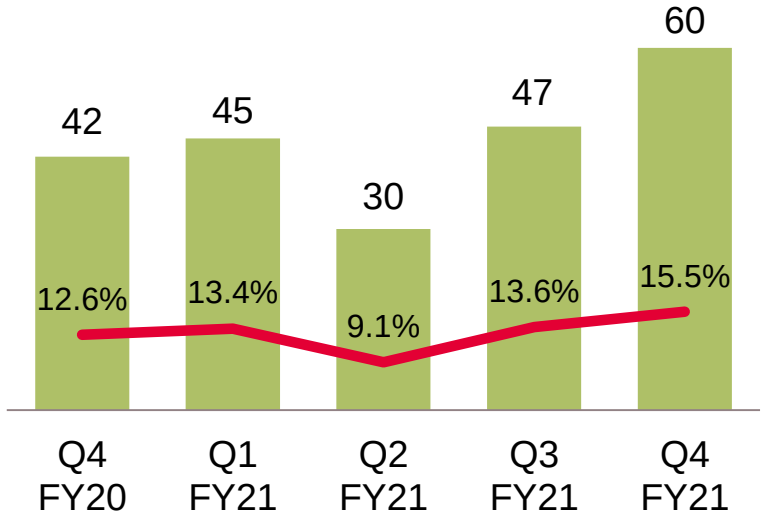
[EUR m]



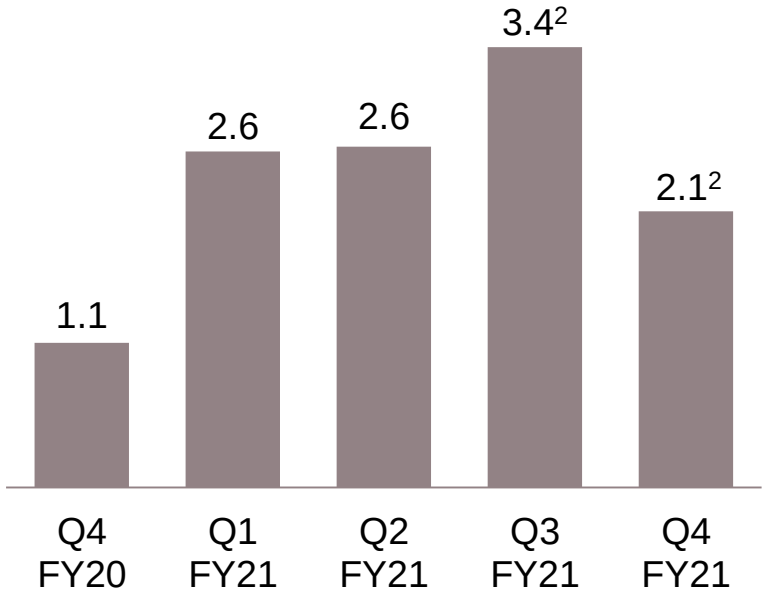
Segment Result[1]

Margin

[EUR m]



Book-to-bill

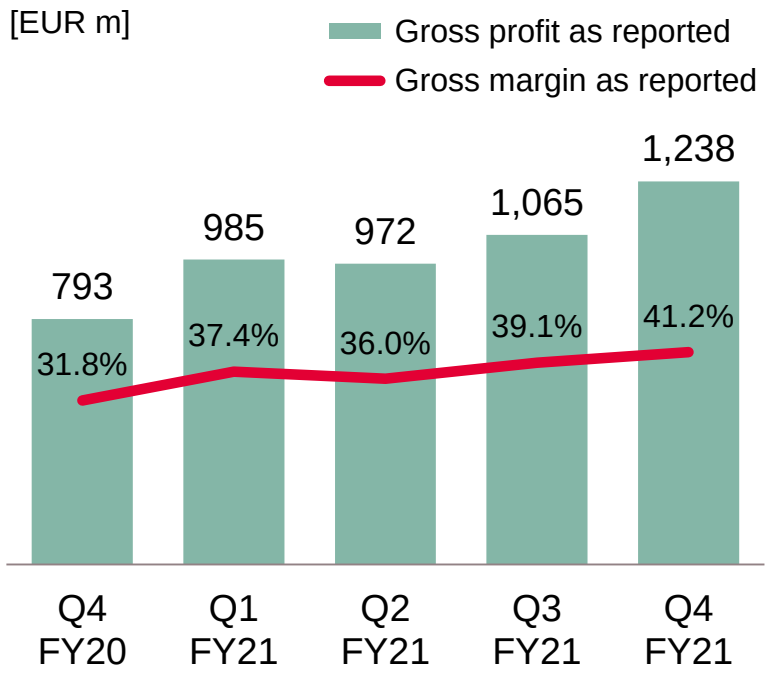


- Revenue and segment result improved by favorable product and customer mix
- Strategy of generating higher value from system solutions gaining momentum
- Demand for compute, connectivity, and security components remains strong – supply constraints expected to persist

1 With effect from 1 Oct 2020, we transitioned a group of industrial microcontrollers with an annual sales volume of a low-double digit million Euros from ATV to CSS. Historical figures have been retroactively adjusted.
2 Calculated on a like-for-like basis, see notes

Gross margin and Opex

Gross profit



Therein non-segment result charges

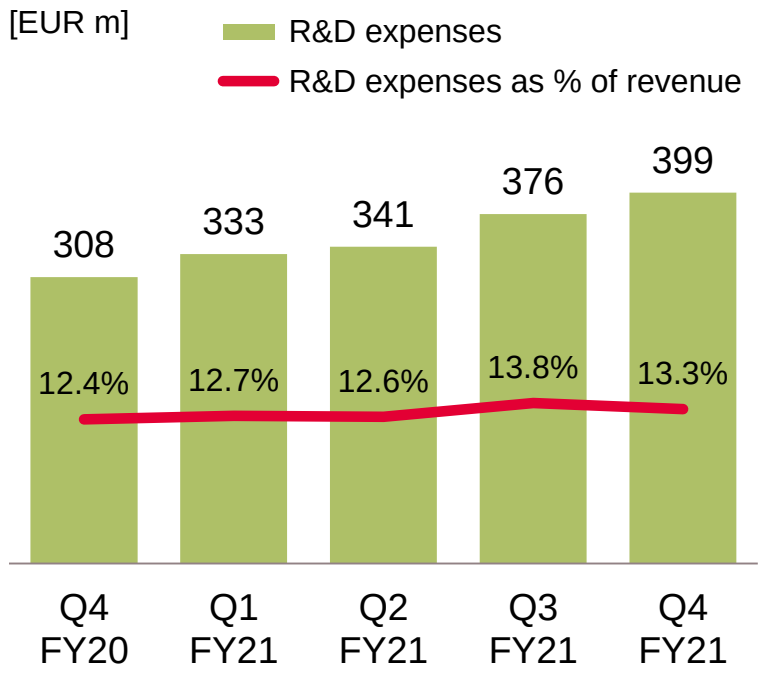
[EUR m]

Q4 FY20	Q1 FY21	Q2 FY21	Q3 FY21	Q4 FY21
118	75	89	74	83

Adjusted gross margin

Q4 FY20	Q1 FY21	Q2 FY21	Q3 FY21	Q4 FY21
36.6%	40.3 %	39.3%	41.8%	43.9%

R&D

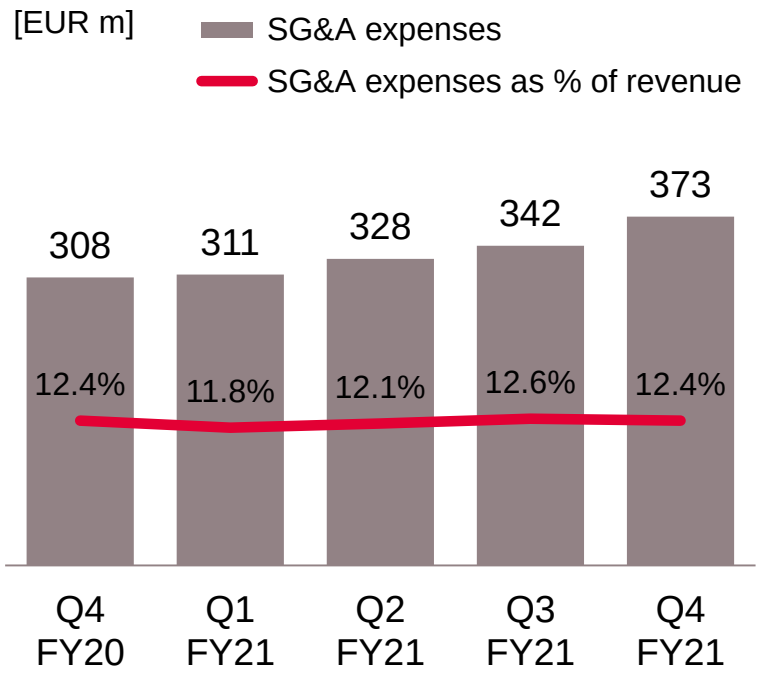


Therein non-segment result charges

[EUR m]

Q4 FY20	Q1 FY21	Q2 FY21	Q3 FY21	Q4 FY21
11	8	4	6	6

SG&A



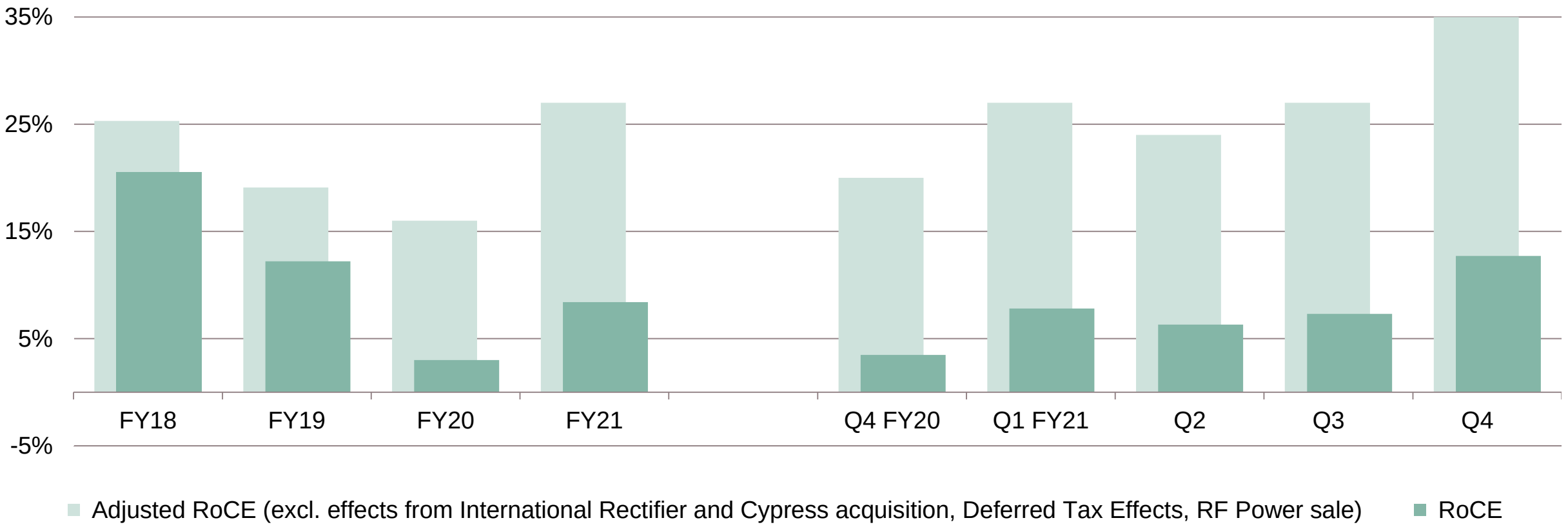
Therein non-segment result charges

[EUR m]

Q4 FY20	Q1 FY21	Q2 FY21	Q3 FY21	Q4 FY21
68	60	58	60	57

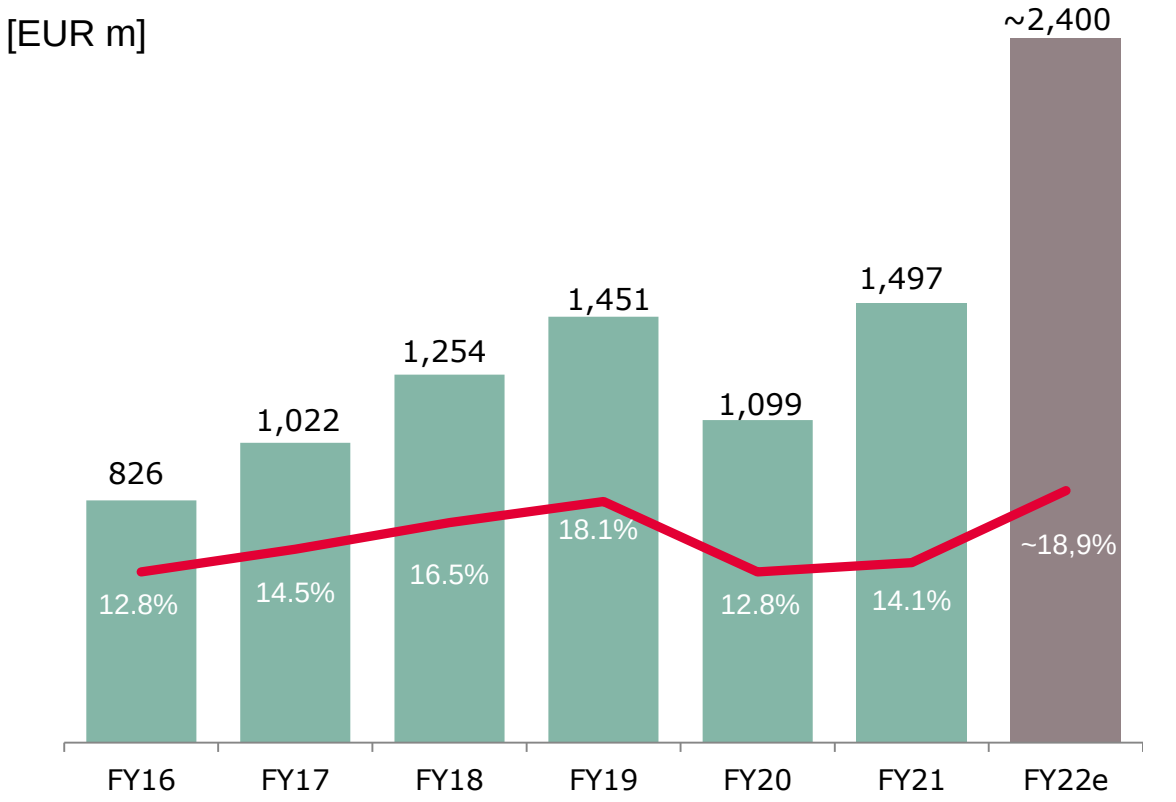
RoCE and adjusted RoCE

Historical development of RoCe and adjusted RoCE

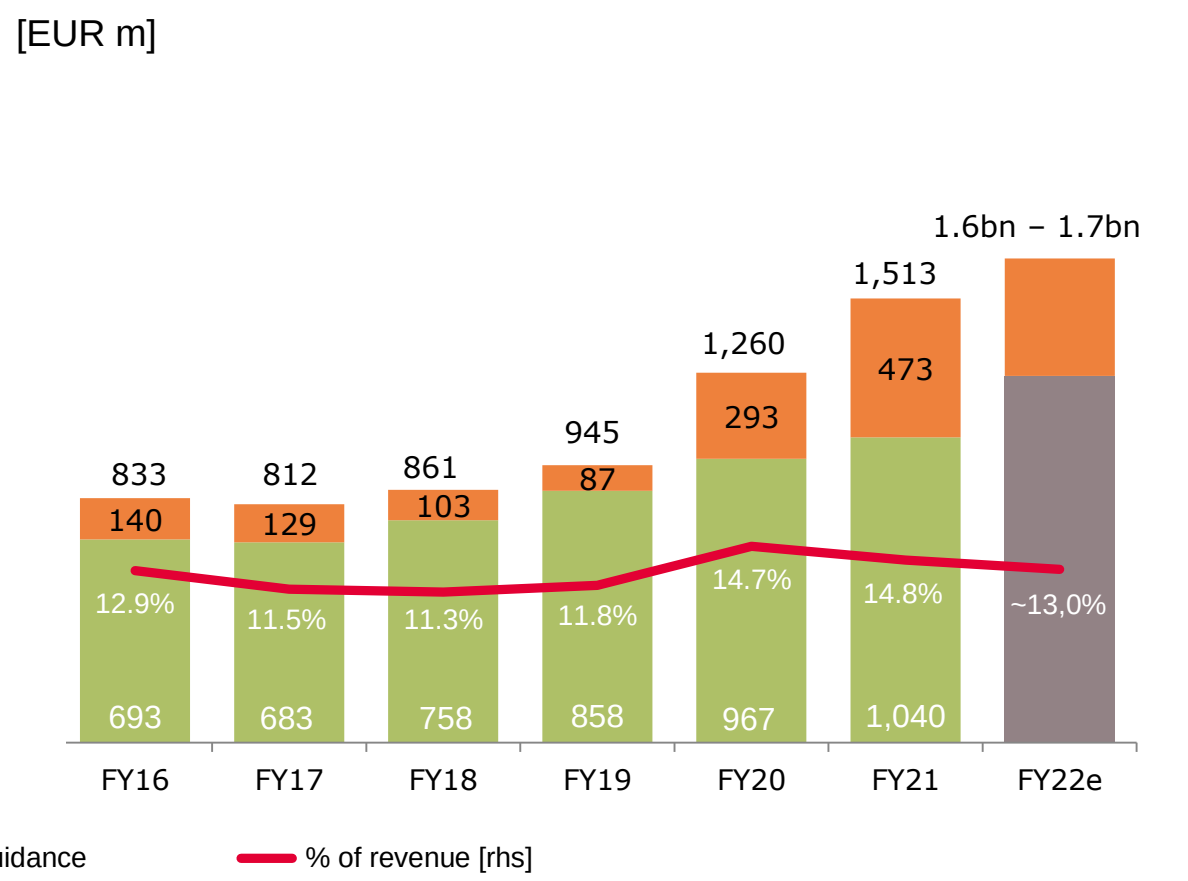


D&A mainly impacted by Cypress PPA

Investments*



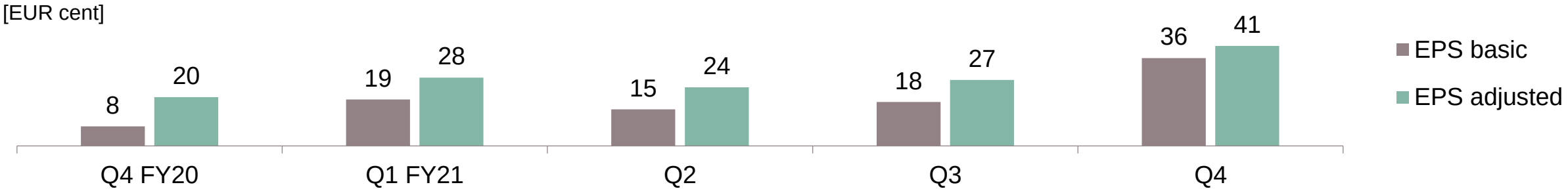
Depreciation & Amortization



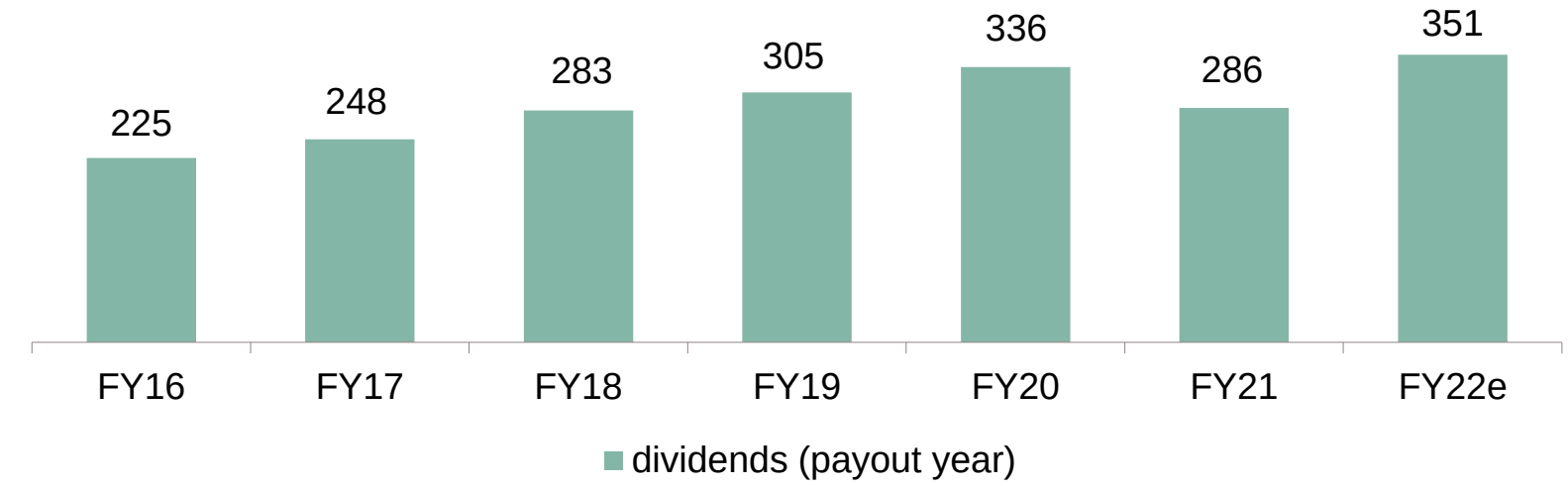
* For definition please see page "Notes".

Earnings-per-share and total cash return

Development of earnings-per-share (EPS) from continuing operations



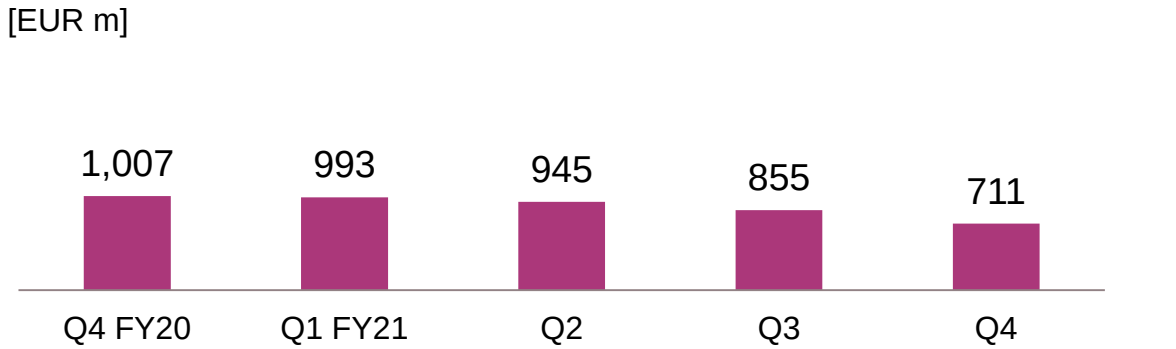
Total cash return to shareholders



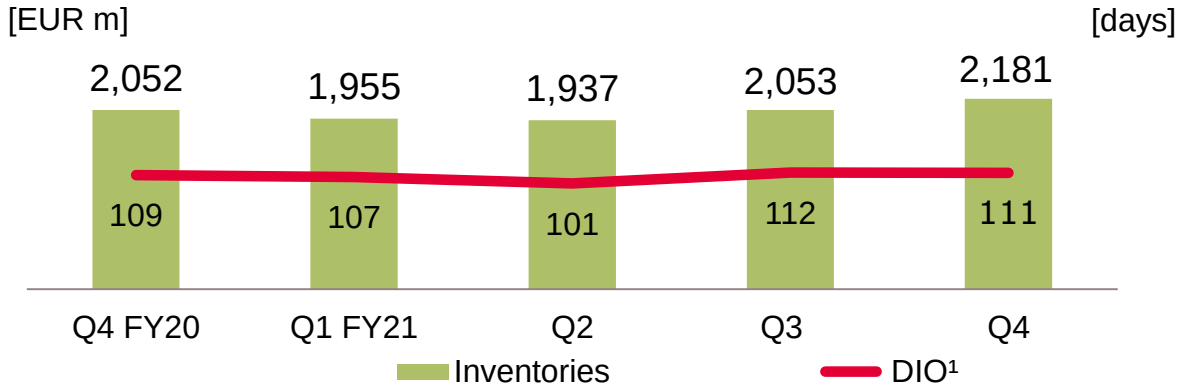
- Proposed dividend for FY21: €0.27 per share
- Proposed dividend payout of €351m for FY21

Working Capital, in particular trade working capital components

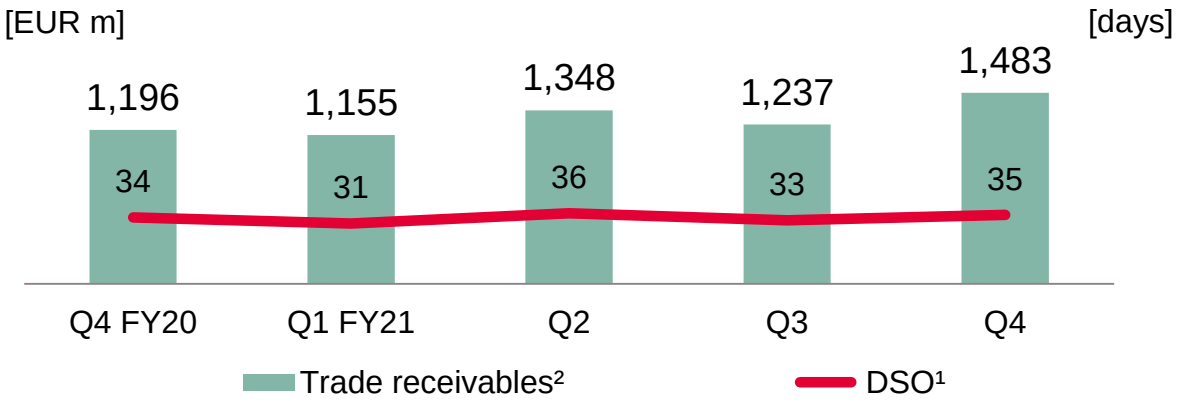
Working capital[1]



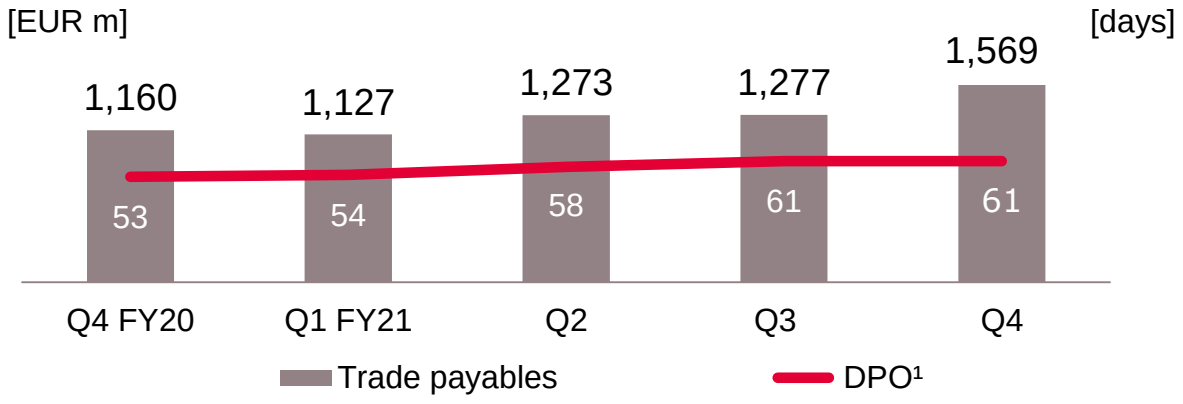
Inventories



Trade receivables



Trade payables

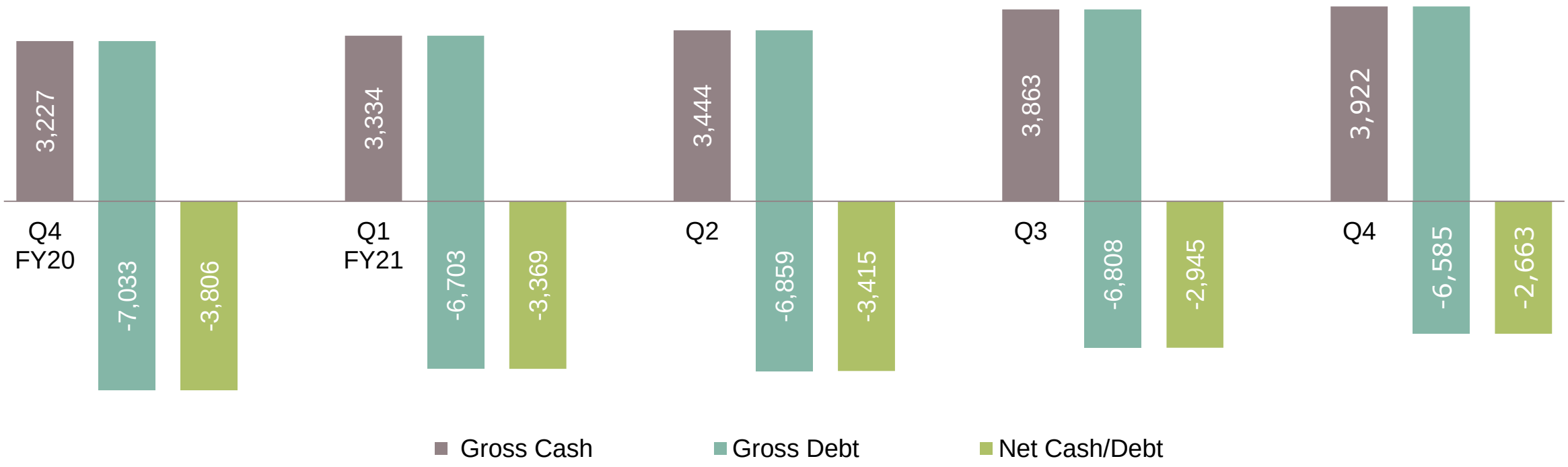


1 For definition please see page "Notes“
2 Along with the integration of Cypress refund liabilities to customers are presented under “other current liabilities” instead of “trade receivables”. Prior quarters’ figures were adjusted accordingly for better comparability.

Liquidity development

Historical liquidity development

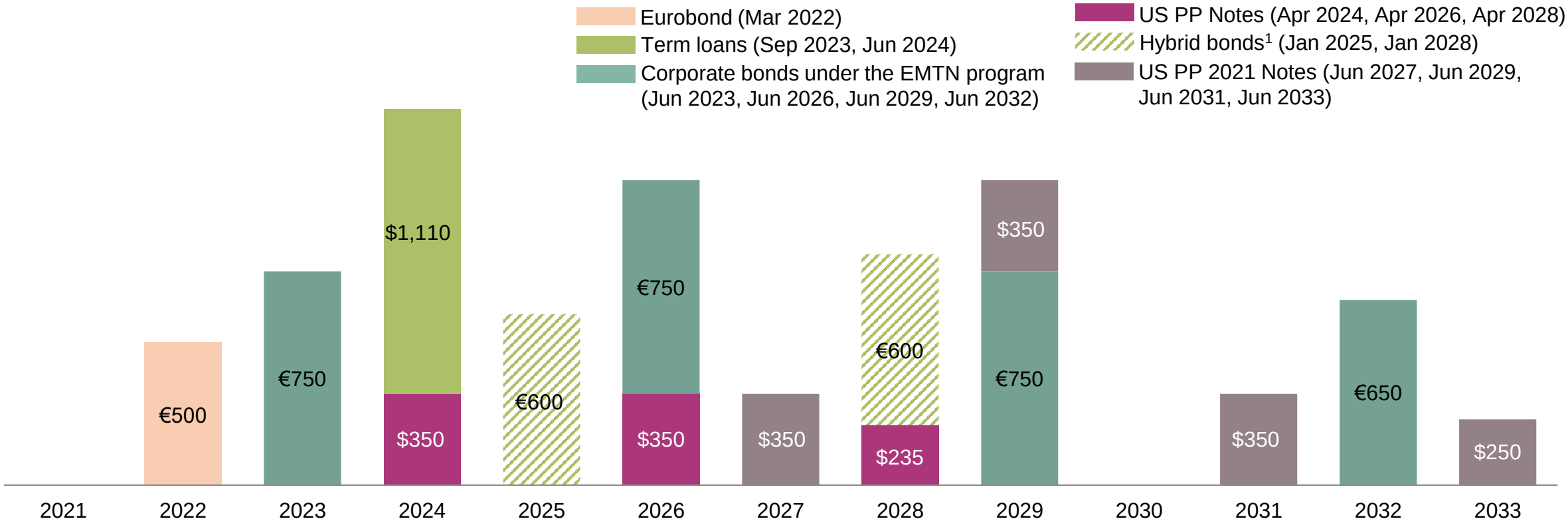
[EUR m]



Maturity profile

Maturity profile from 2021 to 2033

[EUR m; US$ m; nominal values]



Graph excludes pre-existing Cypress convertibles of ~$382m repayment value, maturing latest 2022, and additional debt with maturities between 2021 and 2023 totaling €6m.
1 On 1 Oct 2019, Infineon issued a perpetual hybrid bond with two tranches: €600m with first call date in 2025 and €600m with first call date in 2028; both are accounted as equity under IFRS.

Conservative financial policy and strict commitment to investment-grade rating are the basis for through-cycle flexibility

	Financial Policy Targets	Status Quo (LTM 30 September 2021)
Gross Cash[1]	€1bn + at least 10% of revenues → **€2.1bn**	€1bn + 26% of revenues → **€3.9bn**
Gross Debt[2]	**≤ 2.0x** EBITDA	**2.2x** EBITDA – target to be reached in FY22

Comfortable liquidity position	› Flexibility for financing operating activities and investments through the cycle › Cushion for net pension liabilities and contingent liabilities
Balanced debt position	› Gross debt target temporarily exceeded for CY acquisition, but still compatible to investment-grade rating › Public commitment to return to target level of ≤ 2.0x – to be reached one year earlier, by FY22

Rating	Investment grade	**BBB-** positive outlook (by S&P Global)

1 Gross cash position is defined as cash and cash equivalents plus financial investments | **2** Gross debt is defined as short-term debt and current maturities of long-term debt plus long-term debt. EBITDA is calculated as the total of earnings from continued operations before interest and taxes plus scheduled depreciation and amortization

Part of your life. Part of tomorrow.

Glossary (1 of 2)

ABB	accelerated book building
ABS	anti-blocking system
AC	alternating current
AC-DC	alternating current - direct current
AD	automated driving
ADAS	advanced driver assistance system
AEB	automatic emergency braking
AFS	advanced frontlight system
AI	artificial intelligence
AR	augmented reality
ASP	average selling price
BEV	battery electric vehicle
BGA	ball grid array
BLE	Bluetooth Low Energy
BMS	battery management system
BoM	bill of material
BT	Bluetooth
CL	contactless
CPU	central processing unit
CRC	cyclical redundancy check
DC	direct current
DC-DC	direct current - direct current
DIF	dual-interface (contact-based and contactless)
DIY	do it yourself
DPM	digital power management
eCall	emergency call

ECC	error correction code
ECU	electronic control unit
EPS	electric power steering
eSIM	embedded subscriber identity module
ESS	energy storage system
EV	electric vehicle
FHEV	full hybrid electric vehicle
FPGA	field programmable gate array
G2M	go-to-market
GaN	gallium nitride
GPS	global positioning system
GPU	graphics processing unit
HEV	mild and full hybrid electric vehicle
HMI	human machine interaction
HSM	hardware security module
HST	high-speed train
HVAC	heating, ventilation, air conditioning
HW	hardware
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate biploar transistor
IoT	Internet of Things
IPM	intelligent power module
IVN	in-vehicle networking
iPoI	image processing line
IRF	International Rectifier

Glossary (2 of 2)

IVN	in-vehicle networking
LCD	liquid crystal display
LDO	low dropout voltage regulator
LED	light-emitting diode
LSEV	low-speed electric vehicle
LSPS	LS Power Semitech Co. Ltd.
µC	microcontroller
Mb	megabit
MCU	microcontroller unit
MEMS	micro electro-mechanical systems
MHA	major home appliances
MHEV	mild hybrid electric vehicle
MIMO	multiple input, multiple output
micro-hybrid	vehicles using start-stop systems and limited recuperation
mild-hybrid	vehicles using start-stop systems, recuperation, DC-DC conversion, e-motor
MOSFET	metal-oxide silicon field-effect transistor
MPU	microprocessor unit
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon‘s strategic product-to-system approach
PAS	photo-acoustic spectroscopy
PFC	power factor correction
PHEV	plug-in hybrid electric vehicle
PMIC	power management IC
PoL	point-of-load
PSoC	programmable system-on-chip

PTC	positive temperature coefficient
PV	photovoltaic
RF	radio frequency
rhs	right-hand scale
Si	silicon
SiC	silicon carbide
SiGe	silicon germanium
SMD	surface mounted device
SMPS	switch-mode power supply
SNR	signal-to-noise ratio
SoC	system-on-chip
SOTA	software over-the-air
SPI	serial peripheral interface
SRAM	static random access memory
SW	software
TAM	total addressable market
TCO	total cost of ownership
ToF	time-of-flight
TPM	trusted platform module
UPS	uninterruptible power supply
USB	universal serial bus
V2X	vehicle-to-everything communication
VR	virtual reality
VSD	variable speed drive
Wi-Fi	wireless fidelity
WSC	World Semiconductor Council
xEV	all degrees of vehicle electrification (EV, HEV, PHEV)

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Disclaimer

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Financial calendar

Date	Location	Event
17 – 18 Nov 2021	Barcelona → virtual	Morgan Stanley TMT Conference
19 Nov 2021	Hong Kong → virtual	JPMorgan 9th Global TMT Conference Asia
29 Nov – 2 Dec 2021	Scottsdale (AZ)	Credit Suisse TMT Conference
2 Dec 2021	Paris → virtual	Société Général Premium Review Conference
7 Dec 2021	Pennyhill Park (Surrey, UK)	Berenberg European Conference
9 Dec 2021	London	Deutsche Bank Auto Tech Day
3 Feb 2022[1]		Q1 FY22 Results
17 Feb 2022		Annual General Meeting
9 May 2022[1]		Q2 FY22 Results
3 Aug 2022[1]		Q3 FY22 Results
15 Nov 2022[1]		Q4 FY22 and FY 2022 Results

1 preliminary

Notes and ESG footnotes

Investments =	'Purchase of property, plant and equipment' + 'Purchase of intangible assets and other assets' incl. capitalization of R&D expenses
Capital Employed =	'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale – ('Total Current liabilities' – 'Short-term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')
RoCE =	Operating profit from continuing operations after tax / Capital Employed = ('Operating profit' – 'Financial result excluding interest result' – 'Share of profit (loss) of associates and joint ventures accounted for using the equity method'-'Income tax') / Capital Employed
Working Capital =	('Total current assets' – 'Cash and cash equivalents' – 'Financial investment' – 'Assets classified as held for sale') – ('Total current liabilities' – 'Short term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')
DIO (days inventory outstanding; quarter-to-date) =	('Net Inventories' / 'Cost of goods sold') x 90
DPO (days payables outstanding; quarter-to-date) =	('Trade payables' / ['Cost of goods sold' + 'Purchase of property, plant and equipment']) x 90
DSO (days sales outstanding; quarter-to-date) =	('Trade receivables' - 'reimbursement obligations')* / 'revenue' x 90 *without debtors with credit balances

Book-to-bill = Orders received / Revenue in Euro per quarter

Orders received contains order backlog and external customer forecast. External customer forecast includes consignment stock forecast by customers. Not included are internal consignment replenishment orders.

Orders received does not include unconfirmed orders received. Unconfirmed demand will be reported as orders received and in book-to-bill when it gets confirmed.

Orders received may not coincide with the IFRS 15 definition of a contract with a customer.

Like-for-like calculation as of Q3 FY21: In the light of continued strong order intake, Infineon has temporarily switched from automatic to manual order confirmation. As a result, comparatively fewer orders are being confirmed. To provide a comparable view, the book-to-bill figure has been adjusted by assuming the same confirmation rate of newly received orders as in the previous quarter.

ESG footnotes:

1) This figure takes into account manufacturing, transportation, own vehicles, travel, raw materials and consumables, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. as well as direct and indirect energy-related emissions by manufacturing service providers. It is based on data collected internally and publicly available conversion factors and relates to the 2021 fiscal year.

2) This figure is based on internally established criteria, which are described in the explanatory notes. The figure relates to the 2020 calendar year and takes into account the following application areas: automotive, LED, induction cookers, servers, renewable energy (wind, photovoltaic) and cell phone chargers as well as drives. CO2 savings are calculated based on the potential savings generated by technologies in which semiconductors are used. The CO2 savings are allocated based on Infineon's market share, semiconductor share, and the lifetime of the technologies concerned, based on internal and external experts' estimations. Despite the fact that carbon footprint calculations are subject to imprecision due to the complex issues involved, the results are nevertheless clear.

For further reading

CMD 2021
5 October 2021

https://www.infineon.com/2021cmd

IPC Business Update Call
Dr. Peter Wawer
6 May 2021

https://www.infineon.com/2021ipccall

ATV Business Update Call
Peter Schiefer
5 October 2020

https://www.infineon.com/2020atvcall

CSS Business Update Call
Thomas Rosteck
3 March 2021

https://www.infineon.com/2021csscall

PSS Business Update Call
Andreas Urschitz
1 July 2021

https://www.infineon.com/2021psscall

Annual Report 2021
Sustainability Report 2021
29 November 2021

https://www.infineon.com/2021annualreport
https://www.infineon.com/2021sustainabilityreport

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